



# VW2010 A/V/S CODEC Chip Hardware Description

*Proprietary and Confidential*

**Preliminary**

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**Revision Table**

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June 28, 2001	0.1	BR	First Revision
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# Contents

<i>Chapter 1</i>	<i>Functional Description</i> .....	<i>1</i>
	Physical Modules .....	1
	MPEG Encoder Modules .....	1
	MPEG Decoder Modules .....	2
	System Modules .....	2
	Host Interface Modes .....	3
	Data Paths .....	3
	Uncompressed Data Input Paths .....	5
	Encoder Path .....	5
	Compressed Data Output Paths (CDO) .....	6
	Compressed Data Input Paths (CDI) .....	6
	Decoder Paths .....	6
	Uncompressed Data Output Paths .....	7
	Transcoding / Transrating Path .....	7
	Time Shifting Path .....	7
	DMA Data Paths .....	7
	Control Buses .....	8
	Microcode .....	9
<i>Chapter 2</i>	<i>Feature Set</i> .....	<i>11</i>
	Feature List .....	11
	Video Encoding .....	11
	Audio Encoding .....	12
	Video Decoding .....	12
	Audio Decoding .....	12
	Multiplexing .....	12
	Demultiplexing .....	13
	Graphics .....	13
	MPEG-4 / MPEG-2 Feature Differences .....	13
	General System Facts .....	14

Interfaces .....	15
<i>Host Interfaces</i> .....	15
<i>System Interfaces</i> .....	15
<i>A/V Input Interfaces</i> .....	15
<i>A/V Output Interfaces</i> .....	15
Features and Benefits .....	16
Applications .....	16

### Chapter 3

### *Encoder Modules* ..... 19

Input Modules .....	20
<i>Video Input Unit (VIU)</i> .....	20
<i>Audio Input Unit (AIU)</i> .....	20
Encoder Core Modules .....	20
<i>Motion Estimation Unit (MEU)</i> .....	21
<i>Motion Vector Refinement Unit (MRU)</i> .....	21
<i>Chroma Compensation Unit (CCU)</i> .....	21
<i>Mode Select Unit (MSU)</i> .....	21
<i>Video Encoder Unit (VEU)</i> .....	21
<i>Encoder Processor Unit (eCPU)</i> .....	22
<i>Rate Control Unit (RCU)</i> .....	22
Output Modules .....	22
<i>Multiplexer (MUX)</i> .....	22
<i>CDO Port</i> .....	25
<i>Host / PCI Port</i> .....	25
Application Notes .....	25

### Chapter 4

### *Decoder Modules* ..... 29

Input Modules .....	30
<i>Demultiplexer (DEMUX)</i> .....	30
<i>CDI Port</i> .....	32
<i>Host / PCI Port</i> .....	32
Decoder Core Modules .....	32
<i>Decoder Processor Unit (dCPU)</i> .....	32
<i>Variable Length Decoding Unit (VLD)</i> .....	32
<i>Inverse Quantization / Inverse DCT Unit (IQ/IDCT)</i> ....	33
<i>Motion Compensation Unit (MCU)</i> .....	33
Output Modules .....	33
<i>Video Output Unit (VOU)</i> .....	33
<i>Audio Output Unit (AOU)</i> .....	36
Application Notes .....	36

### Chapter 5

### *System Modules* ..... 39

Embedded Processor (RISC/DSP) .....	40
-------------------------------------	----

	<i>RISC Multiplexer</i>	40
	<i>RISC Audio Encoder</i>	40
	<i>RISC Demultiplexer</i>	40
	<i>RISC Audio Decoder</i>	40
	<i>Data Cache (dmem)</i>	40
Memory Interfaces		41
	<i>Encoder Memory Interface Unit (EMIU)</i>	41
	<i>Decoder Memory Interface Unit (DMIU)</i>	41
Host / PCI Interface		41
	<i>Architecture</i>	41
	<i>Applications</i>	41
	<i>Functions</i>	42
	<i>Data Paths</i>	42
DMA Controller		46
	<i>DMA Features</i>	46
	<i>DMA Data Paths</i>	47
ROM Interface (RIU)		48
	<i>Power-Up Modes</i>	49
General Purpose I/O (GPIO)		50
Inter-Chip Communication Interface (ICI)		51
Main Phase Locked Loop (PLL)		51
Audio PLL		52
Power Management (PMU)		52
	<i>Initial State</i>	52
	<i>Normal State</i>	53
	<i>Sleep State</i>	53
JTAG		54
Extended JTAG		54
Application Notes		54
	<i>Basic Design</i>	54
	<i>PCI Interface</i>	60
	<i>Host Interface</i>	61
	<i>Embedded Host Mode</i>	61
	<i>EJTAG Mode</i>	62
<b>Chapter 6</b>	<b><i>Encoder Interface Signals</i></b>	<b>63</b>
	<i>Video Input Interface</i>	64
	<i>Audio Input Interface</i>	64
	<i>VBI Input Interface</i>	65
	<i>Encoder Memory Interface</i>	65
	<i>Multiplexer Interface</i>	66
	<i>Application Notes</i>	67

<i>Chapter 7</i>	<i>Decoder Interface Signals</i> .....	69
	Demultiplexer Interface .....	70
	Decoder Memory Interface .....	71
	Video Output Interface .....	72
	Audio Output Interface .....	72
	Application Notes .....	73
<i>Chapter 8</i>	<i>System Interface Signals</i> .....	75
	Host Interface, Motorola Mode .....	76
	Host Interface, Intel Mode .....	78
	Host Interface, PCI Mode .....	79
	ROM Interface .....	81
	Global Signals .....	82
	GPIO Signals .....	82
	ICI Signals .....	83
	Main PLL Signals .....	83
	Audio PLL Signals .....	84
	JTAG Signals .....	84
	Extended JTAG Signals .....	85
	Application Notes .....	85
<i>Chapter 9</i>	<i>Pin Lists</i> .....	87
	Summary of the Contents .....	87
	<i>Package Dimensions</i> .....	87
	<i>Pin-out Diagram</i> .....	89
	<i>Pin Lists</i> .....	91
	<i>Signal Multiplexing</i> .....	91
	Application Notes .....	92
<i>Chapter 10</i>	<i>Electrical Characteristics</i> .....	147
	Absolute Maximum Ratings .....	147
	DC Characteristics .....	148
	AC Timing Characteristics .....	148
	<i>HIU-Motorola Mode</i> .....	149
	<i>HIU-Intel Mode</i> .....	151
	<i>HIU-PCI Mode</i> .....	153
	<i>Video Input</i> .....	155
	<i>Video Output</i> .....	156
	<i>VBI Input</i> .....	156
	<i>Audio Input</i> .....	157



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Audio Output .....	158
Compressed Data Input (CDI) .....	158
Compressed Data Output (CDO) .....	159
Host DMA In .....	160
Host DMA Out .....	161
PCI DMA .....	162
Encoder SDRAM Interface (2M32) .....	162
Decoder SDRAM Interface (1M16) .....	166
ROM Interface .....	168
ICI Interface .....	169
PLL Interface .....	170
JTAG / EJTAG Interface .....	171

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# List of Figures

Figure 1	Block Diagram of the VW2010.....	2
Figure 2	Data Path Diagram of the Vweb VW2010.....	5
Figure 3	DMA Data Paths of the Vweb VW2010.....	8
Figure 4	Control Buses of the Vweb VW2010.....	9
Figure 5	Modules of the VW2010.....	19
Figure 6	Data Paths through the Multiplexer Buffers.....	23
Figure 7	External FIFO Interface.....	24
Figure 8	Connections between the MPEG Encoder, Video Decoder and Audio ADC.....	26
Figure 9	Modules of the VW2010.....	29
Figure 10	Data Paths through the Demultiplexer Buffers.....	31
Figure 11	Graphics Plane Hierarchy.....	34
Figure 12	Alpha-Blending Hierarchy.....	35
Figure 13	Connections between the MPEG Decoder, Video Encoder and Audio DAC.....	37
Figure 14	Modules of the VW2010.....	39
Figure 15	CDO Data Path via the HIU.....	43
Figure 16	CDI Data Path via the HIU.....	44
Figure 17	SDRAM and dmem Buffers Active in DMA Transfers in the VW2010.....	48
Figure 18	Power-On / Reset States of the VW2010.....	53
Figure 19	VW2010 External Clock Oscillator.....	55
Figure 20	VW2010 Encoder 2M32 SDRAM Interface.....	56
Figure 21	VW2010 Decoder 2M32 SDRAM Interface.....	57
Figure 22	VW2010 Decoder 1M16 SDRAM Interface.....	58
Figure 23	VW2010 ROM Interface.....	59
Figure 24	VW2010 EEPROM Interface.....	59
Figure 25	VW2010 PCI Interface.....	60
Figure 26	VW2010 Host Interface (USB).....	61
Figure 27	Audio and Video I/O Signals of the VW2010.....	64
Figure 28	Audio and Video I/O Signals of the VW2010.....	70
Figure 29	System I/O Signals of the VW2010.....	76
Figure 30	Package and Ball Array Dimensions (bottom --> up view).....	88
Figure 31	Package Thickness Dimensions.....	88
Figure 32	Package Dimensions (top --> down view).....	89
Figure 33	BGA Ball Map of the VW2010 (top --> down view).....	90
Figure 34	Host Read Timing, HIU-Motorola Mode.....	149

Figure 35 Host Write Timing, HIU-Motorola Mode .....150  
Figure 36 Host Read Timing, HIU-Intel Mode.....151  
Figure 37 Host Write Timing, HIU-Intel Mode.....152  
Figure 38 Host Read Timing, HIU-PCI Mode.....153  
Figure 39 Host Write Timing, HIU-PCI Mode.....154  
Figure 40 Video Input Timing .....155  
Figure 41 Video Output Timing .....156  
Figure 42 VBI Input Timing.....156  
Figure 43 Basic I2S Bus Timing.....157  
Figure 44 I2S Transmitter and Receiver Timing .....157  
Figure 45 S/P-DIF Audio Output Timing.....158  
Figure 46 Compressed Data Input Timing .....158  
Figure 47 Video Mux / Compressed Data Output Timing.....159  
Figure 48 DMA-In Timing .....160  
Figure 49 DMA-Out Timing .....161  
Figure 50 SDRAM Read Cycle Timing (2M32).....163  
Figure 51 SDRAM Write Cycle Timing (2M32).....165  
Figure 52 SDRAM Read Cycle Timing (1M16).....166  
Figure 53 SDRAM Write Cycle Timing (1M16).....167  
Figure 54 ROM Interface Read Timing.....168  
Figure 55 Data Transfer on the ICI Bus .....169  
Figure 56 ICI Timing.....169  
Figure 57 JTAG / EJTAG Timing.....171

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# List of Tables

Table 1	MPEG Feature Enhancements Implemented in the VW2010 .....	13
Table 2	Maximum Search Range Table .....	21
Table 3	Buffers in Encoder SDRAM and dmem .....	23
Table 4	Buffers in Decoder SDRAM and dmem .....	30
Table 5	Boot Mode Selection Truth Table .....	49
Table 6	Boot Mode Pull-Down Resistor Stuffing Option .....	50
Table 7	Audio PLL Output Frequencies .....	52
Table 8	365L BGA Package Dimensions .....	87
Table 9	I/O Signals, Sorted by Pad Number .....	93
Table 10	I/O Signals, Sorted by BGA Coordinates .....	104
Table 11	I/O Signals, Sorted by Module .....	115
Table 12	I/O Signals, Sorted by Signal Name .....	126
Table 13	Power and Ground Connections .....	137
Table 14	Signal Multiplexing Scheme .....	141
Table 15	Board-Level Requirements for Unused Input Pins .....	142
Table 16	Host Interface, Address/Data Bus .....	144
Table 17	Host Interface Bus Control Signals .....	145
Table 18	Maximum Ratings .....	147
Table 19	DC Characteristics .....	148
Table 20	Host Read Timing Parameters, HIU-Motorola Mode .....	150
Table 21	Host Write Timing Parameters, HIU Motorola-Mode .....	151
Table 22	Host Read Timing Parameters, HIU-Intel Mode .....	152
Table 23	Host Write Timing Parameters, HIU Intel-Mode .....	153
Table 24	Timing Parameters, HIU-PCI Mode .....	154
Table 25	Video Input Timing Parameters .....	155
Table 26	Video Output Timing Parameters .....	156
Table 27	VBI Input Timing Parameters .....	156
Table 28	I2S Timing Parameters .....	158
Table 29	S/P-DIF Audio Output Timing Parameters .....	158

Table 30	Video Demux / CDI Timing Parameters .....	159
Table 31	Video Mux / CDO Timing Parameters .....	160
Table 32	DMA-In Timing Parameters .....	161
Table 33	DMA-Out Timing Parameters .....	162
Table 34	SDRAM Read Cycle Parameters .....	164
Table 35	SDRAM Write Cycle Parameters .....	165
Table 36	SDRAM Read Cycle Parameters .....	167
Table 37	SDRAM Write Cycle Parameters .....	168
Table 38	ROM Read Timing Parameters .....	169
Table 39	ICI Timing Parameters .....	170
Table 40	JTAG / EJTAG Timing Parameters .....	171

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## CHAPTER 1

# Functional Description

## Physical Modules

The VW2010 is a very flexible MPEG-1, -2, -4 and H.263 A/V/S encoder/decoder (CODEC) chip. As [Figure 1 on page 2](#) shows, it consists of an embedded RISC/DSP processor, a number of modules that comprise the encoder, a number of modules that comprise the decoder, and a number of I/O modules.

### MPEG Encoder Modules

The MPEG encoder in the VW2010 consists of the following modules:

- Video input unit (VIU)
- Audio input unit (AIU)
- Video encoder/compression core units
  - Motion estimation unit (MEU)
  - Motion vector refinement unit (MRU)
  - Chroma compensation unit (CCU)
  - Mode select unit (MSU)
  - Rate control unit (RCU)
  - Encoder central processor unit (eCPU)
  - Video encoder unit (VEU)
- Audio encoder/compression in the RISC/DSP processor
- Multiplexer and buffer controller (MUX and BUF)

As an MPEG audio/video encoder, the VW2010 compresses video data using a proprietary, patent-pending, motion estimation and rate control algorithm that has been optimized for low latency, fast scene detection, and smooth bit rate allocation. The embedded RISC/DSP processor packetizes the compressed data into an output MPEG stream format selected by the user. The VW2010 accepts two channels of I<sup>2</sup>S audio, and uses the audio encoder functions in the RISC/DSP to generate compressed audio data, which may be multiplexed into the output MPEG stream.

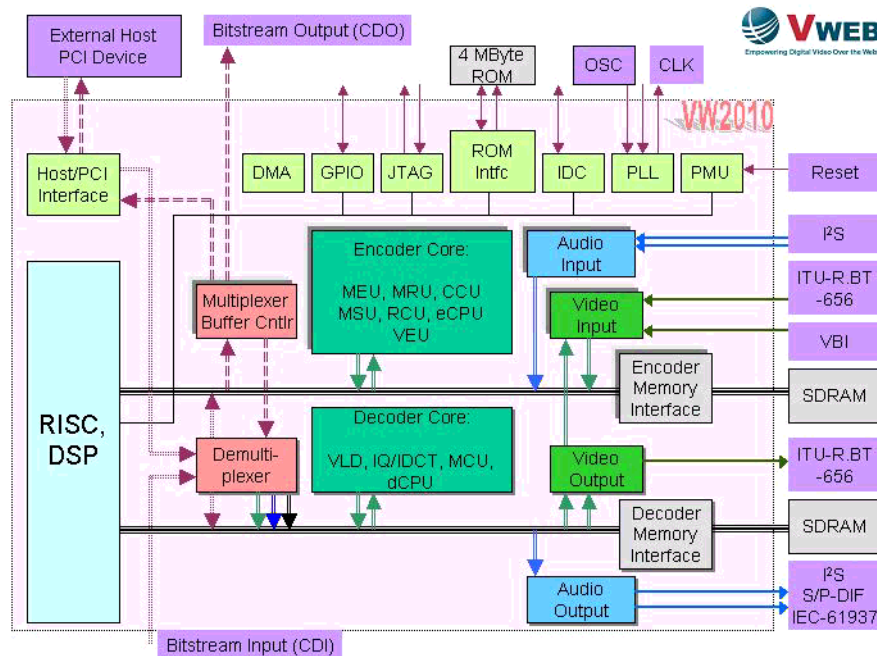


Figure 1 Block Diagram of the VW2010

## MPEG Decoder Modules

The MPEG decoder in the VW2010 consists of the following modules:

- Demultiplexer (DEMUX)
- Video decoder/decompression core units
  - Variable length decoding unit (VLD)
  - Inverse quantization / inverse discrete cosine transform unit (IQ/IDCT)
  - Motion compensation unit (MCU)
  - Decoder central processor unit (dCPU)
- Audio decoder/decompression in the RISC/DSP processor
- Video graphics and output unit (VOU)
- Audio output unit (AOU)

As an MPEG video and audio decoder, the VW2010 demultiplexes an MPEG bitstream into its video, audio and user data components (if any), decompresses the video and audio information, and combines the video with graphics, Closed Caption, Teletext or other user data. The output video data is presented in standard ITU-R.BT.656 format. The output audio is available in I<sup>2</sup>S or S/P-DIF digital audio format, or as IEC-61937 compressed audio.

## System Modules

The VW2010 includes a power management module (PMU) and a number of I/O interface modules:

- Host/PCI interface (for an external processor, storage and other devices)



- DMA controller (DMA)
- ROM interface (for boot and other microcode)
- General purpose input / output (GPIO)
- Boundary scan ports (JTAG and EJTAG)
- Phase-locked loops (main PLL and audio PLL)
- Inter-device communications interface (ICI)

All of these modules are described in some detail later in this manual (“Encoder Modules” on page 19, “Decoder Modules” on page 29, and “System Modules” on page 39).

## Host Interface Modes

The host interface of the VW2010 can be configured to operate in the following host modes:

- 16-bit Motorola-style mode
- 16-bit Intel-style mode
- PCI target mode

These modes can be selected at power-up / reset, as described in the section titled “Host Mode” on page 49.

## Data Paths

Transfer of data among these modules takes place using the following means:

- Direct input and output ports (shown in [Figure 2 on page 5](#))
- Two dedicated high-speed SDRAM buses (shown in [Figure 2 on page 5](#))
- DMA channels between selected modules (shown in [Figure 3 on page 8](#))

The main I/O ports of the VW2010 are shown in [Figure 2 on page 5](#). A list and description of the I/O signals are presented at the end of this manual (“Encoder Interface Signals” on page 63, “Decoder Interface Signals” on page 69, and “System Interface Signals” on page 75).

Two dedicated high-speed SDRAM buses connect the RISC to the two SDRAM interfaces. The encoder SDRAM bus is 32 bits wide, and the decoder SDRAM bus is 64 bits wide. Both interfaces to the external SDRAM devices are 32 bits wide. All modules in the encoder exchange data among themselves via the encoder SDRAM bus. All modules in the decoder exchange data among themselves via the decoder SDRAM bus.

To perform the functions of the VW2010, the physical data paths can be used to facilitate the following functional data paths between I/O and encoder/decoder modules:

- Taking ITU-R.BT.656 video data and VBI data from the video input ports, and I<sup>2</sup>S audio data from the audio input ports.
- Encoding this same data.
- Presenting compressed data on the compressed data out port, or on the host/PCI port.
- Taking compressed video (+ audio + user) data from the compressed data input port, or the host/PCI port.
- Decoding this same data.
- Presenting the ITU-R.BT.656 video on the video output port.
- Presenting I<sup>2</sup>S and S/P-DIF digital audio or IEC-61937 compressed audio on the audio output ports.
- Transrating / transcoding.
- Time shifting.

Two control buses are used to set up and configure these data paths, as described under [“Control Buses” on page 8](#).

*Note:* All internal buses and all I/O buses of the VW2010 are big-endian. (Among other things this means that bit 0 is the least significant bit.) The only exception is the host/PCI port:

*Note:* The host/PCI port may be big-endian or little-endian, depending on the host mode. For more details, see [“Host Interface, Motorola Mode” on page 76](#) and [“Host Interface, Intel Mode” on page 78](#).

For a more detailed discussion of the internal data paths, given in terms of the data buffers set up in SDRAM, see the sections titled [“Encoder Buffers” on page 22](#) and [“Decoder Buffers” on page 30](#).

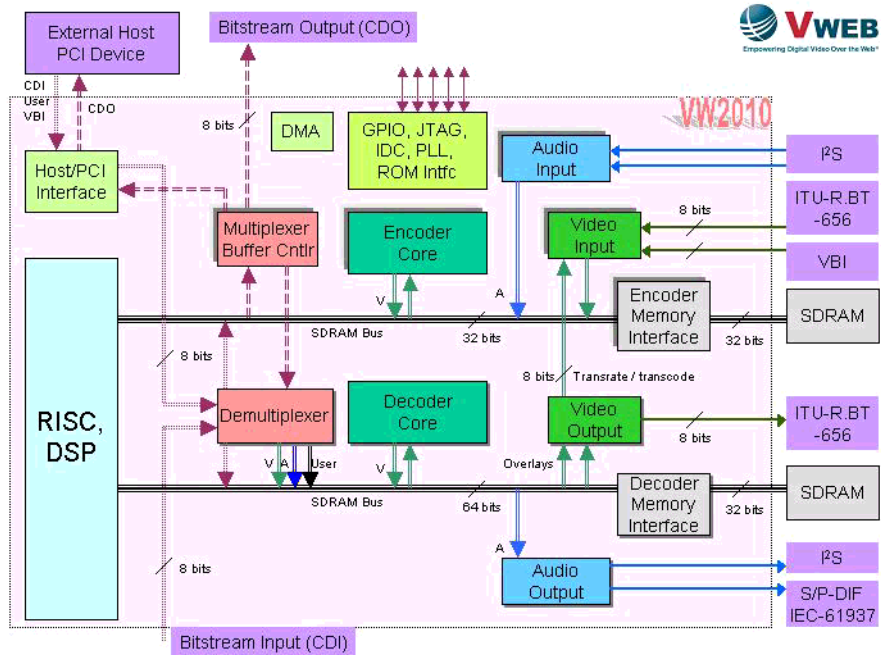


Figure 2 Data Path Diagram of the Vweb VW2010

### Uncompressed Data Input Paths

The video data to be encoded is available on one of the video input unit's (VIU) input ports:

- 8-bit ITU-R.BT.656 uncompressed video data
- 8-bit VBI data
- A special 8-bit port from the video output unit (VOU) that is used in transcoding/transrating applications.

The audio data to be encoded is available on the two I<sup>2</sup>S input ports of the audio input unit (AIU).

### Encoder Path

The VIU filters and loads its input data into the encoder SDRAM via the high speed encoder SDRAM bus. The video encoder core modules retrieve this data from SDRAM as needed. The video encoding core modules read and write to the SDRAM the intermediate and final results of the MPEG-1, -2, -4 or H.263 encoding process. This compressed data is available to the multiplexer in the RISC via the SDRAM.

The AIU sends its input data to the RISC via the encoder SDRAM. Audio compression is done by the audio digital signal processing (DSP) extensions in the RISC. The DSP puts the compressed audio back into SDRAM so the data will be available to the multiplexer in the RISC.

In the RISC, the compressed video from the encoder core modules is optionally combined with compressed audio, and with user data, if any; then the data is multiplexed and/or processed for network delivery. The resulting compressed data stream (CDO bitstream) is sent to the multiplexer buffer controller (BUF) via the encoder SDRAM bus.

By this time the CDO is a regular MPEG bitstream (SS, PS, TS, ES or PES, depending on how the encoder was set up). For the sake of generality, in this document this MPEG bitstream is still called CDO.

### Compressed Data Output Paths (CDO)

Under control by the RISC, the multiplexer buffer controller (BUF) sets up the appropriate buffers and FIFOs, and routes the CDO bitstream to the host/PCI interface unit's output port, or directly to the dedicated 8-bit parallel or 1-bit serial CDO output port.

### Compressed Data Input Paths (CDI)

Multiplexed / combined / compressed data input bitstream (CDI), as well as user data and VBI, can be input on one of the input ports: on the host/PCI port, or on the dedicated 8-bit parallel / 1-bit serial CDI input port. From these ports, the data is internally routed to the demultiplexer (DEMUX), which directly stores the data in the decoder or encoder SDRAM via the corresponding high speed SDRAM bus (without demultiplexing at this time).

There is no separate compressed audio input path. It is assumed the CDI bitstream may contain or may consist of tagged video, audio or user data components.

### Decoder Paths

Decoder processing begins in the RISC. It selects buffers and FIFOs for use by the demultiplexer (DEMUX). The DEMUX retrieves the CDI from SDRAM, extracts video, audio and user data from the CDI, and places each type of data into their separated buffers and FIFOs. The data flow between the decoder modules takes place via the decoder SDRAM, as follows.

The demultiplexer (DEMUX) extracts video data from the CDI bitstream, and sends it to the video decoder core via the decoder SDRAM. The video decoder core modules retrieve this data from SDRAM as needed. The video decoding core modules read and write to the SDRAM the intermediate and final results of the MPEG-1, -2, -4 or H.263 decoding / decompressing / filtering calculations. The decoder core sends the resulting video data to the video output unit (VOU) via SDRAM. The VOU completes the conversion of the video data to the ITU.R-BT.656 format. The VOU also contains a graphics module, which, under user control, can generate multiple graphics overlays to be superimposed on the video.

The DEMUX extracts user data from the CDI bitstream, and sends it to the decoder SDRAM, for further processing by the RISC. In the RISC, user data is converted to Closed Caption or Teletext data, and sent back into SDRAM as VBI data to be mixed with the video data in the VOU.

The DEMUX extracts audio data from the CDI bitstream, and sends it to the decoder SDRAM. The audio is decompressed using the DSP extensions within the RISC, and put back into SDRAM. The audio output unit (AOU) retrieves this data from SDRAM and converts it to I<sup>2</sup>S or S/P-DIF format.

### Uncompressed Data Output Paths

The VOU sends video data in ITU-R-BT.656 format either to an off-chip NTSC/PAL encoder (to be displayed on a standard television screen), or back to the video input unit (VIU) in transrating/transcoding applications.

The decompressed audio output of the AOU is presented on the I<sup>2</sup>S or S/P-DIF ports. Compressed audio in IEC-61937 format is available as a bypass option on the S/P-DIF port.

### Transcoding / Transrating Path

The VW2010 can be used to transrate (change the bit rate of) or transcode (change the MPEG encoding format of) a video data stream. Either application requires both the encoder and the decoder. By definition a data stream to be transrated or transcoded is a CDI, therefore first it must be decoded as usual (that is, as described above). However, instead of presenting it as ITU-R.BT.656 data to an external NTSC/PAL encoder, it is routed as input to the VIU on an internal 8-bit data path between the decoder's VOU and the encoder's VIU. Thus introduced into the encoder data path, the data can be re-rated or re-coded as desired, and routed to any of the CDO ports, just like any other CDO bitstream.

### Time Shifting Path

The VW2010 can be used to do time shifting. This application requires both the encoder and the decoder. In this case the program to be time-shifted (from the external NTSC/PAL decoder) is an input to the VIU, encoded as usual, and written out as CDO to an external storage device (such as a hard disk). At a later time of the viewer's choosing, the compressed data is retrieved from the external storage device, input to the decoder as a CDI bitstream, decoded as usual, and sent back out as ITU-R.BT.656 data to an external NTSC/PAL encoder.

## DMA Data Paths

The data paths that can be set up via DMA channels between selected modules in the VW2010 are shown in [Figure 3 on page 8](#). (Some of the data paths described in previous sections are actually implemented by means of these DMA paths.) As the figure shows, the DMA engine can be thought of as a direct bridge between the following devices in the chip:

- The dmem data cache in the RISC
- External host memory, via the host/PCI interface
- The encoder SDRAM, via the EMIU
- The encoder MUX (and then the EMIU and the encoder SDRAM)
- The decoder SDRAM, via the DMIU
- The decoder DEMUX (and then the DMIU and decoder SDRAM)

Note that not every possible combination of source and destination devices is supported by the DMA engine. For specific details, see [“DMA Controller” on page 46](#).

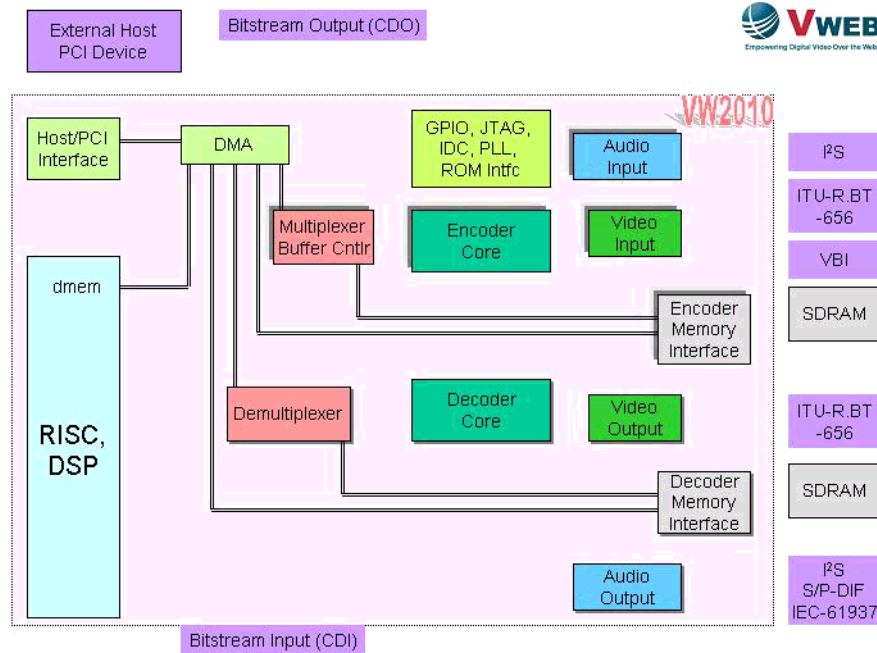


Figure 3 DMA Data Paths of the Vweb VW2010

The DMA engine uses the internal 32-bit SDRAM bus to talk to the encoder's EMIU and BUF. The DMA engine uses the internal 64-bit SDRAM bus to talk to the decoder's DMIU and DEMUX. As both of these buses are connected to the RISC, dmem can send or receive data on whichever one is active at the time. The DMA engine uses the internal CDI/CDO bus to talk to the HIU's holding buffer for host/PCI memory.

*Note:* As Figure 3 on page 8 indicates (by omission), the chip's direct CDO port, and the bus from the MUX to the CDO port, are not available to the DMA engine.

For more detail, see the section titled "DMA Controller" on page 46.

## Control Buses

The DMA channels and other I/O paths are set up and configured by means of signals on a control bus for the encoder and another control bus for the decoder. Both control buses are connected to the host interface unit (HIU). The DMA module, as well as the other I/O modules, gain control of these buses by bridging with the HIU. This is shown schematically in Figure 4 on page 9.

The embedded RISC or external host processor gains control over these buses, and therefore the DMA and other I/O data paths, by means of internal registers. Note the following:

- The hardware path from the embedded RISC or external host processor to the registers is provided via the HIU.
- Software access is provided by high-level protocols and APIs, not by direct access to registers or microcode.

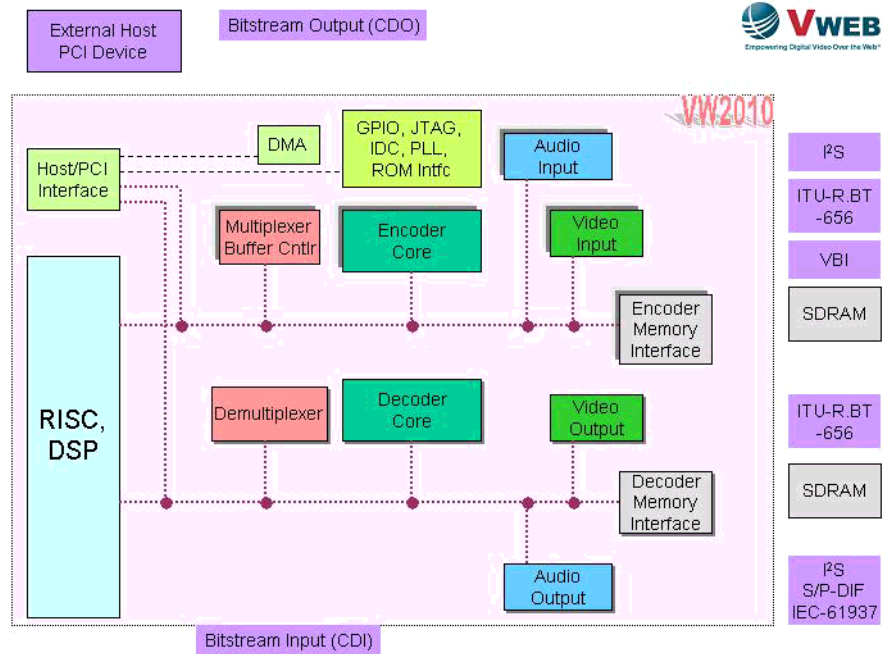


Figure 4 Control Buses of the Vweb VW2010

## Microcode

A number of modules in the VW2010 require microcode to operate. These include, for example, the RISC processor as well as the dedicated RISC engines in the encoder and decoder core. As [Figure 1 on page 2](#) indicates, the VW2010 chip design anticipates that the microcode would be stored in an external ROM (flash, EEPROM or other type of ROM device); the ROM interface is built into the chip.

The microcode from this ROM would be downloaded into the chip at power-up / boot time. As the signal multiplexing scheme described in the chapter titled “[Pin Lists](#)” on [page 87](#) indicates, the ROM data pins are available for other uses after power-up.

The size of ROM may depend on user preference or board design; however, one 4-Mbyte ROM, such as an AT49BV1614, should be sufficient for each VW2010 chip used in the design. (See [Figure 23 on page 59](#).) The minimum required ROM space is set by the type and size of firmware used on the board, but typically is not expected to exceed 512KB. (Vweb reference/debug board designs place a ROM of 2 or 4 MB on the board).

However, it is also possible to load the microcode from an external host via the HIU. In such a design, the user may still need to keep basic boot parameters in a small ROM device (even such as a 128-byte SEEPROM). In such a case the boot parameters could be programmed into the ROM via the ICI bus, and at boot time loaded from the ROM into the VW2010 again via the ICI bus. (See [Figure 24 on page 59](#); see also “[Boot from ICI](#)” on page 46.)

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## CHAPTER 2

# Feature Set

The VW2010 is a real-time MPEG-1, -2 and -4 audio/video/system CODEC chip (simultaneous compression/decompression, or encode/decode) that fully complies with ISO/IEC-11172-2, ISO/IEC-13818-2, ISO/IEC-14496-2 and ITU-T H.263 (baseline). The video encoder accepts uncompressed ITU-R.BT.656 digital video. It filters the input and compresses the video into MPEG-1, -2, -4 or H.263 formats. The audio encoder accepts two independent channels of I<sup>2</sup>S digital audio, filters the input, and compresses each audio into MPEG-1, MPEG-2, MP3, AAC, or AC-3 audio formats. The VW2010 outputs them as transport streams for network applications or program streams for storage applications. The video decoder accepts an MPEG bit-stream and outputs ITU-R.BT.656 digital video. The audio decoder accepts an MPEG-1, MPEG-2, MP3, AAC, or AC-3 bitstream and outputs I<sup>2</sup>S, S/P-DIF or IEC-61937 audio.

This chapter tabulates the feature set of the VW2010. The features are described in greater detail in subsequent chapters.

## Feature List

### Video Encoding

- Support for MPEG-1
- Support for MPEG-2 MP@ML
- Support for MPEG-4 Simple Profile @ L1, L2 and L3, with extensions to full D1 and interlaced video
- Adaptive field/frame motion compensation and DCT type
- 4:2:2 to 4:2:0 conversion
- Scene change detection
- Inverse telecine (3:2 pulldown)
- Motion estimation search range  $\pm 127$  pels horizontal and  $\pm 63$  pels vertical, with half-pel accuracy
- 8-tap horizontal filter and 4-tap vertical filter

- Extraction of VBI data (including close captioned and NABTS data) from the ITU-R.BT.656 input
- Support for private and user data insertions from VBI port or host/PCI port
- Dynamically adjustable controls
  - Fixed frame rates of 29.97 (NTSC) or 25 (PAL) frames per second, or variable frame rates in low delay mode
  - Constant or variable bit-rate from 22.5 Kb/s to 15 Mb/s
  - Horizontal resolution between 128 pixels and 720 pixels in 16-pixel steps
  - Vertical resolution between 80 pixels and 480 pixels (NTSC) or 576 pixels (PAL) in 16-pixel steps
- Programmable GOP structure and length: I, IP, IBP and IBBP
- Programmable low delay mode

### Audio Encoding

- MPEG-1 Layer I, II
- MPEG-1 Layer III (MP3)
- MPEG-2 Layer I and II
- 2-channel consumer-grade AAC
- 2-channel consumer-grade AC-3
- G.7xx
- Sampling frequencies: 8, 16, 22.05, 24, 32, 44.1, 48 and 96 KHz.
- Number of bits per channel: 16, 20, 24, 32 bits

### Video Decoding

- MPEG-1, -2, -4 and H.263 baseline decoding
- 7-tap horizontal filter and 2-tap vertical filter
- Letterbox conversion
- 3:2 pulldown
- Closed Captioning and Teletext

### Audio Decoding

- MPEG-1 Layer I, II
- MPEG-1 Layer III (MP3) <sup>1</sup>
- MPEG-2 Layer I and II
- 2-channel consumer-grade down-mixed AAC <sup>1</sup>
- 2-channel consumer-grade down-mixed AC-3 <sup>1</sup>
- G.7xx <sup>1</sup>
- Sampling frequencies: 8, 16, 22.05, 24, 32, 44.1, 48 and 96 KHz.
- Number of bits per channel: 16, 20, 24, 32 bits
- For S/P-DIF, 32, 44.1 and 48 KHz at 32 bits

### Multiplexing

#### Input

- User data or VBI data insertion
- Video and audio Elementary Stream (ES) or Packetized Elementary Stream (PES)

#### Output

- MPEG-1 System Stream

---

1. Future option

- MPEG-2 Program Stream (PS) or Transport Stream (TS)
- MPEG-4 video encapsulated in MPEG-2 TS
- ES and PES output without multiplexing

## Demultiplexing

### Input

- System stream, program stream, and transport stream

### Output

- Program clock recovery (PCR)
- 7 output buffers: 1 video, 4 audio, 1 PSI, 1 user (subtitle, Teletext)

## Graphics

- Background (solid color) plane
- MPEG video plane
- Two 32-bit ARGB (RGB with alpha-blending) or AYUV (YUV with alpha-blending) 8:8:8:8 graphics planes
- Cursor plane
- 2-, 4- or 8-bit color indexing
- 0.5X or 2X vertical scaling; arbitrary horizontal scaling on 16-pixel boundaries (letterboxing, QSIF to SIF, SIF to D1, D1 to SIF, SIF to QSIF)
- Per-pixel alpha-blending
- Deflicker filter

## MPEG-4 / MPEG-2 Feature Differences

Table 1 summarizes features that represent an MPEG-4 enhancement over MPEG-2.

The VW2010 encoder supports most features of MPEG-4 Simple Profile (including but not limited to the features listed in this Table), plus some additional features of the MPEG-4 Advanced Simple Profile (flagged with “ASP” in this Table), as noted in the “Implementation” column.

The VW2010 decoder supports all features of the encoder, plus additional features of MPEG-4 Simple Profile and MPEG-4 Advanced Simple Profile (flagged with “SP” and “ASP” in this Table), as noted in the “Implementation” column.

**Table 1 MPEG Feature Enhancements Implemented in the VW2010**

Feature	Implementation				SP <sup>1</sup>	Benefit
	MPEG-2 Encoder	MPEG-2 Decoder	MPEG-4 Encoder	MPEG-4 Decoder	ASP <sup>2</sup>	
Prediction	One-directional DC prediction	One-directional DC prediction	AC/DC prediction	AC/DC prediction	SP	Saves bits
Quantization style	MPEG-2	MPEG-2	MPEG-2	MPEG-2	ASP	Medium-high bit rate
			H.263	H.263	SP	Low bitrate
Bits per macro-block	Quantizer coding, 5 bits for quantizer per macroblock	Quantizer coding, 5 bits for quantizer per macroblock	Dquant coding, 2 bits for quantizer per macroblock	Dquant coding, 2 bits for quantizer per macroblock	SP	Saves bits

**Table 1 MPEG Feature Enhancements Implemented in the VW2010 (Continued)**

Feature	Implementation				SP <sup>1</sup>	Benefit
	MPEG-2 Encoder	MPEG-2 Decoder	MPEG-4 Encoder	MPEG-4 Decoder	ASP <sup>2</sup>	
VLC tables	MPEG-2 VLC tables	MPEG-2 VLC tables	H.263 VLC tables	H.263 VLC tables	SP	Low bitrate
Motion vector prediction	One-directional	One-directional	Median value - based	Median value - based	SP	Saves bits
No. of motion vectors	2 motion vectors (one-directional)	2 motion vectors (one-directional)	2 motion vectors (one-directional)	4 motion vectors (one-directional)	SP	Medium-high bit rate, detail-focused app's
Unrestricted motion vectors	No	No	No	Yes	SP	Scenes with global motion
Motion estim. accuracy	Half-pel	Half-pel	Half-pel	Half-pel	SP	
Global motion estimation	No	No	No	No	ASP	Scenes with global motion
Error resilience	No	No	No	Yes	SP	Robust to errors
Coding	Interlaced Non-interlaced	Interlaced Non-interlaced	Interlaced (frame DCT / field predict.) Non-interlaced	Interlaced (frame DCT / field predict.) Non-interlaced	ASP	Interlaced I/O
B-frames	Yes	Yes	No	No	ASP	Medium-high bit rate

1. "SP" = MPEG-4 Simple Profile

2. "ASP" = MPEG-4 Advance Simple Profile

## General System Facts

- 162 MHz MIPS-like RISC processor with DSP extensions for multiplexing, demultiplexing, audio encoding and audio decoding
- 365-pin PBGA package; physical dimensions: 27 mm by 27 mm
- Input voltages: 1.8 V (internal), 3.3 V (I/O)

- Estimated power consumption: under 1.0 W in normal operating mode (see [Table 18 on page 147](#));  
On-chip power management
- Boundary scan and assembly testing compliant with IEEE 1149.1 (JTAG) and EPI EJTAG 2.0 (extended JTAG)

## Interfaces

### Host Interfaces

- 16-bit Motorola-style interface
- 16-bit Intel-style interface
- PCI interface, target mode: 32 bits, 33 MHz

### System Interfaces

- GPIO (general purpose input/output): 12 pins
- ROM interface
- ICI (inter-device communication interface, similar to Philips I<sup>2</sup>C master mode)
- SDRAM
  - 32-bit memory interface, using 1Mx16-5 or 2Mx32-5 SDRAM
  - Minimum requirements, VW2010: 4 to 8 MB for encoder, plus 4 to 8 MB for decoder (8 MB recommended if OSD is used)

### A/V Input Interfaces

#### Uncompressed Input

##### MPEG Encoder

- Video: 8-bit ITU-R.BT.656
- Audio: two I<sup>2</sup>S ports
- VBI, user data: 8-bit video input

#### MPEG Bitstream Input

##### MPEG Decoder

- 8-bit / 1-bit compressed data input interface (CDI)
- PCI interface
- Host interface

### A/V Output Interfaces

#### Compressed Output

##### MPEG Encoder

- 8-bit / 1-bit compressed data output interface (CDO)
- PCI interface
- Host interface

#### Uncompressed Output

##### MPEG Decoder

- Video: 8-bit ITU-R.BT.656 port
- Audio: I<sup>2</sup>S port, IEC-958 S/P-DIF digital audio port with IEC-61937 compressed audio bypass
- VBI, user data:

- 1-bit (serial) bitstream using ICI or GPIO interface
- Embedded in 8-bit video bitstream

## Features and Benefits

<ul style="list-style-type: none"> <li>■ Uses (less than) 8 MB of external SDRAM</li> <li>■ 32-bit SDRAM interface</li> <li>■ Proprietary motion estimation algorithm</li> <li>■ MPEG-4 compression reduces storage requirements</li> </ul>	Saves money and power
<ul style="list-style-type: none"> <li>■ Easy to set up and configure</li> </ul>	Decreases time to market
<ul style="list-style-type: none"> <li>■ Efficient rate control algorithm monitors 60 different variables, which results in a more consistent GOP structure; thus, scene changes are handled well.</li> </ul>	Superior video quality
<ul style="list-style-type: none"> <li>■ Programmable frame rates, bit rates, resolution and low delay mode</li> <li>■ Programmable GOP structure</li> <li>■ Transcoding and transrating among MPEG-1, -2, -4 and H.263</li> </ul>	Superior flexibility
<ul style="list-style-type: none"> <li>■ MPEG-1, -2, -4 full-D1 interlaced encoder/decoder</li> <li>■ Low latency support</li> <li>■ MPEG-4 short header support (H.263 base-line support)</li> </ul>	Superior ingenuity

## Applications

The VW2010 is ideally suited for the following consumer applications:

- Camcorder
- Network camera
- Personal video recorder
- Set-top box
- PC capture device for video capture, content creation, and display
- VCD, Super-VCD and DVD player and recorder
- Cellular phones and PDAs

In addition, the VW2010 is suited for the following network applications:

- Streaming video distribution over DSL, cable, ethernet, fiber and wireless networks
- Transcoding and transrating among MPEG-1, -2, -4 and H.263
- Video conferencing
- Security / surveillance
- Video-on-demand servers

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## CHAPTER 3

*Encoder Modules*

This chapter presents more detailed descriptions of each individual encoder module's functions. Figure 5 on page 19 summarizes the encoder modules in the VW2010, and their relationships to each other. In this figure, the middle row of modules belong to the encoder.

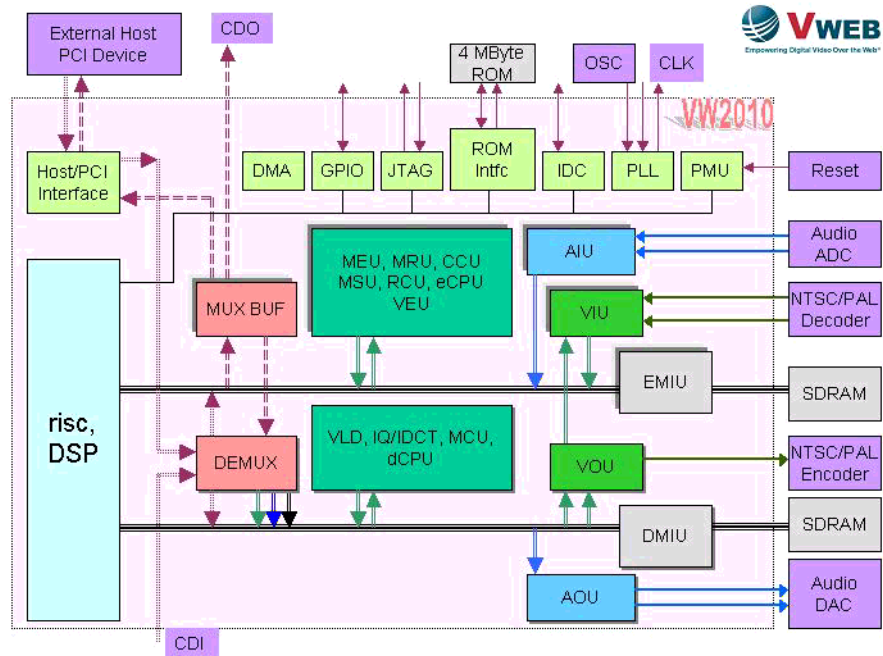


Figure 5 Modules of the VW2010

## Input Modules

The VW2010 encoder has two input modules:

- Video input unit (VIU)
- Audio input unit (AIU)

### Video Input Unit (VIU)

The VIU serves as the interface between the VW2010 and the uncompressed digital video data. The VIU reads a standard 8-bit ITU-R.BT.656 (parallel D1) port. The VIU performs the following functions:

- **Video input decoding;** the video input decoding process extracts the timing information and VBI data.
- **Scaling;** the scaling engine consists of a 3-line buffer, 4-tap vertical filter and 8-tap horizontal filter, which supports variable resolutions from sub-QCIF to full D1 in 16-pixel increments.
- **Color sub-sampling;** the color sub-sampling engine converts the image from the 4:2:2 to the 4:2:0 format.
- **SAD statistic gathering;** the SAD statistical gathering process supports the 3:2 pull-down engine among other prediction services.

### Audio Input Unit (AIU)

The AIU accepts uncompressed digital audio input data on two I<sup>2</sup>S channels; the encoder can process two stereo audio streams simultaneously. The AIU supports master and slave timing. When using master-timing mode, an internal timing module generates all timing signals for the external ADC. When using slave-timing mode, the AIU reads the data according to externally supplied clock signals. In the end, the audio and video clocks can be tied together using program clock recovery (PCR).

The AIU supports the audio sampling frequencies (sampling rates from 8 KHz to 96 KHz) and the bits-per-channel, left/right modes (from 16 to 32 bits) shown in the “Feature List” on page 11.

The AIU sends the audio data to the RISC/DSP via the SDRAM, for processing by the audio encoder and multiplexer functions implemented in the RISC/DSP.

## Encoder Core Modules

The VW2010 encoder core consists of the following modules:

- Motion estimation unit (MEU)
- Motion vector refinement unit (MRU)
- Chroma compensation unit (CCU)
- Mode select unit (MSU)
- Video encoder unit (VEU)
- Encoder processor unit (eCPU)
- Rate control unit (RCU)

### Motion Estimation Unit (MEU)

The MEU estimates the distance that a macroblock has moved relative to the reference frame, for the luma component of the video data. The MEU uses a proprietary search scheme, which reduces the computational complexity of calculating the motion vectors. A coarse estimate of the motion vectors is calculated within the search window. The best-matched frame and field motion vectors and vertical field-select bits are sent to the MRU. [Table 2 on page 21](#) shows the maximum search windows. The search range is programmable in 16-pixel steps.

**Table 2 Maximum Search Range Table**

	Frame Prediction	Field Prediction
P-Picture	Horizontal: $\pm 127$ pels Vertical: $\pm 63$ pels	Horizontal: $\pm 127$ pels Vertical: $\pm 63$ pels
B-Picture	Horizontal: $\pm 63$ pels Vertical: $\pm 63$ pels	Horizontal: $\pm 63$ pels Vertical: $\pm 63$ pels

### Motion Vector Refinement Unit (MRU)

The MRU takes the output of the MEU and applies a “fine search refinement scheme” to fine-tune the luma motion vectors to within one-half pel. The MRU initiates a second search around the origin of the coarse motion estimation block calculated by the MEU.

### Chroma Compensation Unit (CCU)

The CCU takes the refined motion vectors from the MRU (for the luma component), and uses them to perform motion compensation on the chroma component.

### Mode Select Unit (MSU)

The MSU performs macroblock inter/intra DCT decision and activity measure calculations required by the RCU. It performs the following calculations:

- Squared error of the best prediction
- Variance of the currently coded macroblock
- Activity measure of the current coded macroblock
- Parameters for field- or frame- DCT decisions

### Video Encoder Unit (VEU)

The VEU actually performs the video compression. Based on the MSU calculations, unless overridden by the host processor, the VEU performs field or frame-based DCT calculations. The DCT coefficients are quantized, zig-zag-scanned and VLC-coded. The VEU performs the inverse quantization (IQ) and inverse DCT (IDCT) calculations to generate the reconstructed image that is used in the motion vector calculations. In sum, the VEU performs the following tasks:

- Download the user-defined quantization matrix for MPEG-2 quantization
- MPEG-1, -2, -4 quantization / inverse quantization
- Frame/field forward DCT / inverse DCT
- Coded block pattern generation
- DC/AC prediction in MPEG-4
- Motion-vector prediction and coding

- MPEG-1, -2, -4 variable length coding (VLC)
- Reconstruction of macroblocks
- Distortion measurements between original and reconstructed macroblocks
- Keeping track of the number of bits generated

### Encoder Processor Unit (eCPU)

The eCPU is implemented using a proprietary RISC processor with up to 4K x 20 bits of microcode. The eCPU controls the operations of the encoder. It sequences the input video data through the compression process up to the ES output, places the MPEG video headers on the data, monitors the status of the various modules, and controls the output of the data. The Vweb Corporation provides the microcode in binary format.

### Rate Control Unit (RCU)

The RCU is implemented using a proprietary RISC processor with up to 4K x 24 bits of microcode. Different parts of the rate control algorithms are invoked by signals from the eCPU and VEU at various points during the encoding process. The RCU calculates sixty variables, which it uses to manage the encoded bit rate and bit budget. The Vweb Corporation provides the microcode in binary format.

## Output Modules

The VW2010 encoder has one output module:

- Encoder multiplexer unit (MUX)

and two output ports:

- Multiplexer compressed data out (CDO) port
- Host / PCI port

### Multiplexer (MUX)

The MUX provides user control of the compressed data output (CDO) buffers and FIFOs for routing the combined / multiplexed CDO bitstream from the RISC (that is, from the encoder SDRAM after the RISC has finished its work on the bitstream) to the host/PCI port or to the CDO port. If the destination is the CDO port, the MUX can generate either an 8-bit parallel or a 1-bit serial CDO bitstream.

### Encoder Buffers

In the encoder, the multiplexer (MUX) also acts as a buffer controller (BUF). The multiplexer (under control of the RISC) sets up eight buffers in SDRAM for transport multiplexing; that is, combining video, audio and user data to create the CDO, and to route data into and out of the encoder. The buffers in SDRAM, and the corresponding buffers set up by the RISC in dmem, are listed in [Table 3 on page 23](#).

*Note:* The role of these buffers in DMA transfers is shown under “[DMA Controller](#)” on [page 46](#).

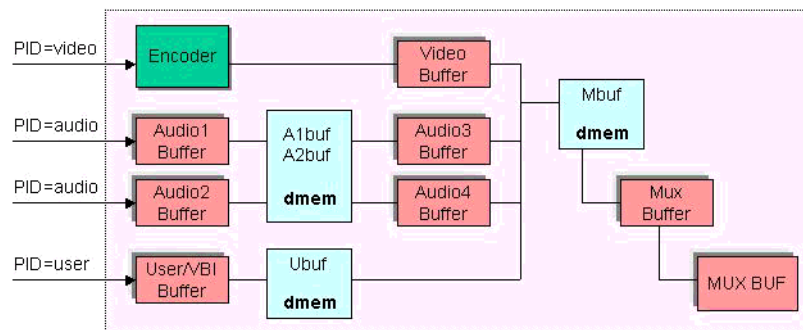
**Table 3 Buffers in Encoder SDRAM and dmem <sup>1</sup>**

Encoder SDRAM	I/O	dmem
Video	Out	
User	In	User
VBI	In	
Mux (out)	Out	Mux
Audio1	In	Audio1
Audio2	In	Audio2
Audio3	Out	
Audio4	Out	

1. The buffer sizes are set by Vweb firmware and may vary with each release.

**Data Paths via the Buffers**

The data paths, in terms of the A/V buffers, are shown in [Figure 6 on page 23](#). Note that there is a 1:1 correspondence between a PID and the buffer for the data type identified by the PID.

**Figure 6 Data Paths through the Multiplexer Buffers**

As [Figure 6 on page 23](#) shows, the RISC/DSP takes uncompressed data from two audio input buffers to generate compressed audio:

- Audio 1 buffer
- Audio 2 buffer

The results are stored in a second set of two audio buffers (audio 3 and 4). Under control by the RISC, the MUX gets the components of the CDO bitstream from up to five sets of FIFOs and buffers (depending on the video/audio/user data actually being encoded):

- Video buffer
- Audio 3 buffer
- Audio 4 buffer
- VBI buffer
- User data buffer

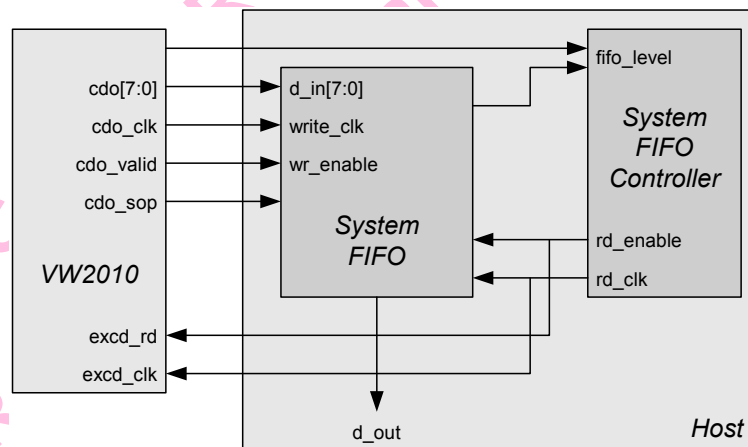
Data in the video buffer is the output of the video encoder core modules. There is no user data / VBI output buffer, as user data can multiplexed into the compressed video stream from the encoder core at the TS, PES or picture level. The resulting multiplexed, compressed data is stored in an eighth buffer:

- Mux buffer

The MUX gets the compressed data from this buffer for routing it as a CDO stream to the CDO port.

#### External Buffer Control

CDO is pumped out to an external device in the host, typically a system FIFO under the control of a system FIFO controller. The interface is summarized in [Figure 7 on page 24](#).



**Figure 7 External FIFO Interface**

Compressed data is pumped out the CDO port cdo[7:0] at the rate set by cdo-clk when the chip indicates that the CDO data is valid. The fifo\_level signal from the chip as an interrupt to the system FIFO controller when the chip's output FIFO is half full.

The host can control the CDO data rate, by sending excd\_rd to inform the chip about the external FIFO level, and by sending excd\_clk to latch excd\_rd. Using this information, Vweb firmware adjusts the CDO burst size to match the output data rate of the

system FIFO. The fifo\_level signal from the system FIFO as an interrupt to the system FIFO controller when the system FIFO reaches a user-defined value.

## CDO Port

The CDO port is part of the MUX. The external interface signals are listed under “[Multiplexer Interface](#)” on page 66.

## CDO Modes

The CDO port runs in two modes:

- VW2000 mode, bursting data out at  $\text{sysclk}/4 = 40.5 \text{ MHz}$
- ASI mode, clocking data out in 188-byte packets at 27, 13.5 or 6.75 MHz.

In VW2000 legacy mode, the interface consists of six signals shown in Figure 7 (cdo[7:0], cdo\_clk, cdo\_valid, excd\_rd, excd\_clk, fifo\_level). Strictly speaking, excd\_rd and excd\_clk are not needed; in such a case, of course, there is no data rate adjustment.

In ASI mode, the interface consists of the five VW2010 output signals (cdo[7:0], cdo\_clk, cdo\_valid, cdo\_sop, fifo\_level). The burst size is fixed, always 188 bytes. The cdo\_sop signal can go to a FIFO as shown in Figure 7, or, more typically, to a DVB-ASI encoder chip as shown in the Vweb win10 schematic.

## CDO Streams

The CDO bus is used to output a transport stream (TS). However, it can also be programmed to output ES, PES, video ES, audio ES, video PES, audio PES.

When outputting TS, PCR is inserted automatically. If the PCR PID is the same as the video PID, then the PCR is inserted into the video packet, and the PCR\_Present bit is set in the TS header. If the PCR PID is different from the video PID, then a PCR packet is generated exclusively.

When outputting TS, PAT and PMT are also generated automatically and inserted into the TS. The interval is programmable; the default is the industry standard for DVB, 600 ms.

## Host / PCI Port

For a detailed description, see “[System Modules](#)” on page 39 and “[System Interface Signals](#)” on page 75.

The host/PCI port can be used to input and output CDO streams, download micro-code into the VW2010 device, program the graphics plane, as well as other data.

## Application Notes

The VW2010 encoder connects directly, seamlessly, without glue logic, to a video decoder such as the Philips SAA7115 and to an audio ADC such as the Philips UDA1342 CODEC, as illustrated in the following figure (based on the schematic of the VwebWin10 Evaluation Board).

The video decoder and audio ADC have their own requirements for input signal filtering and input power smoothing, and in the case of the Philips video decoder, requires an external 32.11 MHz oscillator. These requirements are explained in the Philips data sheets.

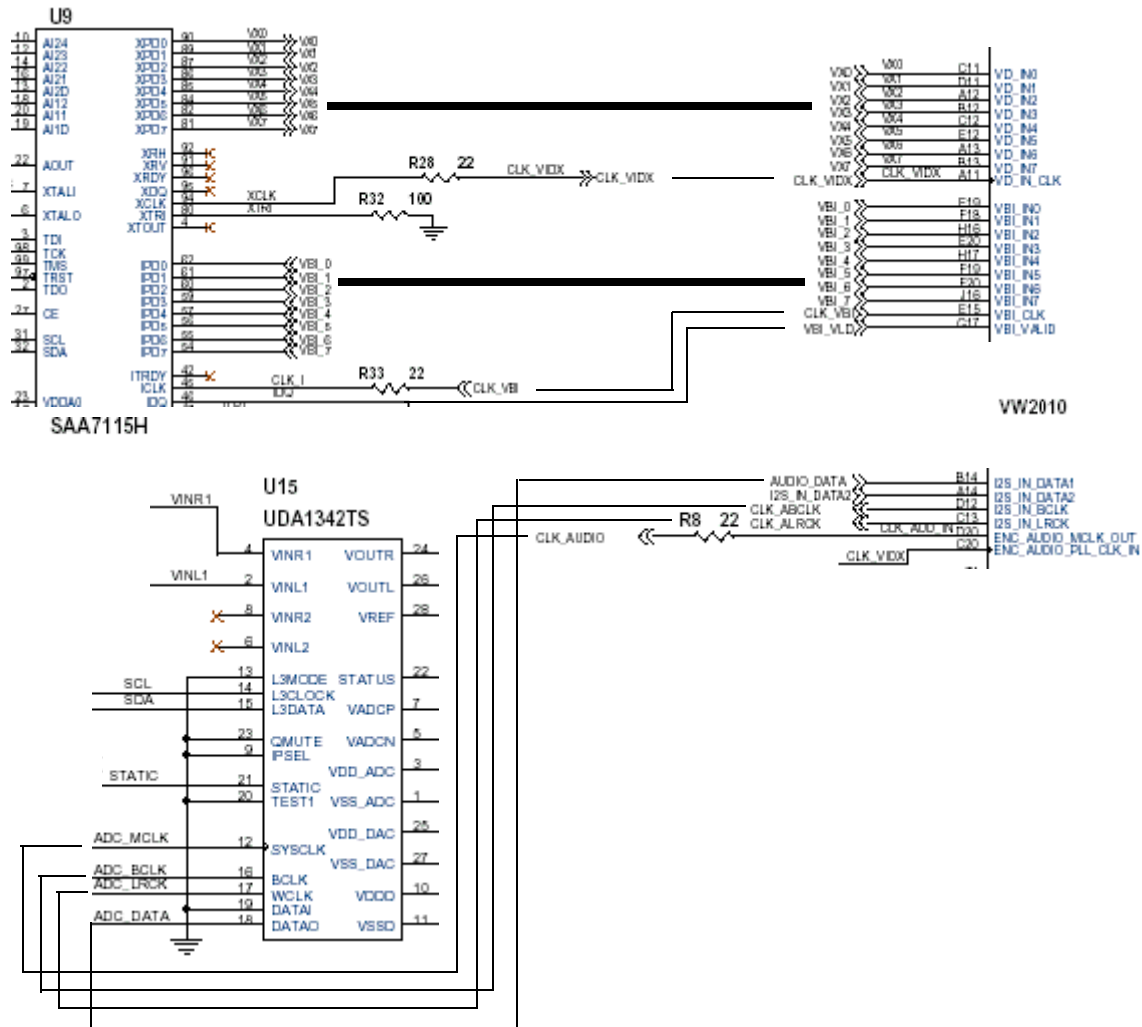


Figure 8 Connections between the MPEG Encoder, Video Decoder and Audio ADC



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# CHAPTER 4

# Decoder Modules

This chapter presents more detailed descriptions of each individual VW2010 decoder module's functions. Figure 9 on page 29 summarizes all the modules that constitute the VW2010, and their relationships to each other. The bottom row of modules belong to the decoder.

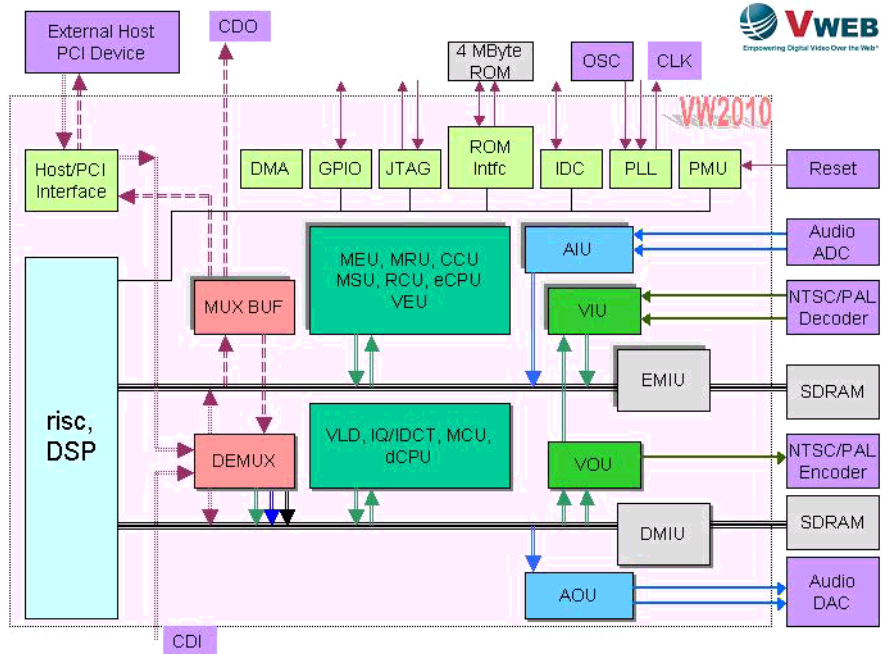


Figure 9 Modules of the VW2010

## Input Modules

The VW2010 has two input modules:

- Decoder demultiplexer (DEMUX)
- Host interface unit (HIU)

and two input ports:

- Demultiplexer compressed data in (CDI) port
- Host / PCI port

### Demultiplexer (DEMUX)

The DEMUX provides user control of buffers and FIFOs used in demultiplexing the compressed data input (CDI) bitstream, and for routing the resulting video and audio streams to the video and audio output ports, or to the host/PCI port. The DEMUX accepts CDI either from the CDI port or from the host/PCI port. In either case, there is a bypass in the DEMUX unit to store the incoming data either in encoder SDRAM or in decoder SDRAM. If the active input is the CDI port, the DEMUX can process either an 8-bit parallel or a 1-bit serial CDI bitstream.

### Decoder Buffers

In the decoder, the DEMUX acts as a buffer controller. The DEMUX (under control by the RISC) sets up eight buffers in SDRAM for transport demultiplexing; that is, separating video, audio and user data from the CDI. The buffers in SDRAM, and the corresponding buffers set up by the RISC in dmem, are listed in [Table 4 on page 30](#).

*Note:* The role of these buffers in DMA transfers is shown under “DMA Controller” on page 46.

**Table 4 Buffers in Decoder SDRAM and dmem <sup>1</sup>**

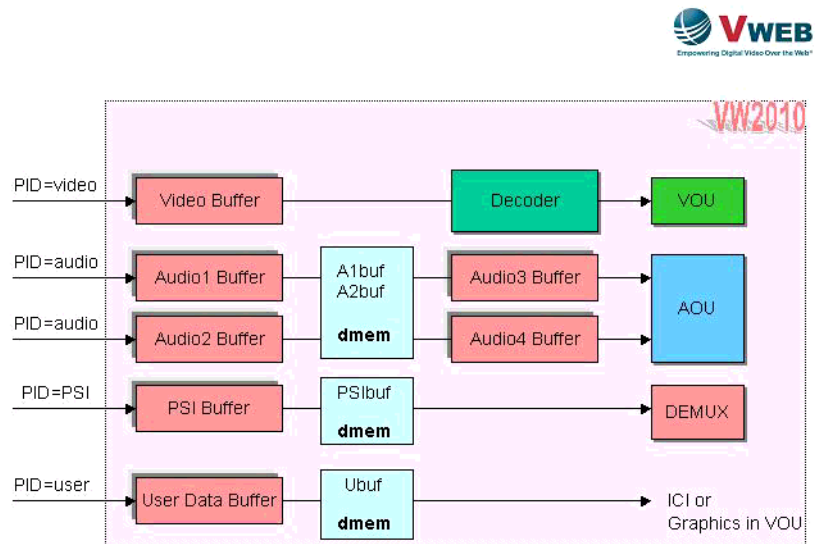
Decoder SDRAM	I/O	dmem
Video	In	
Demux	In	
PSI	In	PSI
User	In	User
Audio1	In	Audio1
Audio2	In	Audio2
Audio3	Out	
Audio4	Out	

1. The buffer sizes are set by Vweb firmware and may vary with each release.

There is no output buffer for video/demodulator and user data, as video/demodulator data is an output streamed by the decoder core modules directly to a video encoder, and

user/VBI data can be output directly either to the internal graphics module or streamed out on the ICI port.

**Data Paths via the Buffers** The data paths, in terms of the A/V buffers, are shown in Figure 10 on page 31. Note that there is a 1:1 correspondence between a PID and the buffer for the data type identified by the PID.



**Figure 10 Data Paths through the Demultiplexer Buffers**

As Figure 10 on page 31 shows, under control by the RISC the DEMUX stores the components of the CDI bitstream in up to five sets of FIFOs and buffers (depending on the contents of the CDI bitstream):

- Video buffer
- Audio 1 buffer
- Audio 2 buffer
- PSI buffer
- User data buffer

Data from the video buffer is processed through the video decoder core modules. The user/VBI data may be routed to the graphics module in the VOU, or output to an external device on the ICI port. PSI data is processed in the DEMUX. The RISC/DSP takes data from the two audio buffers to generate uncompressed audio. The results are stored in a second set of two audio buffers:

- Audio 3 buffer
- Audio 4 buffer

Data from audio 3 and 4 are used by the audio output unit (AOU) to generate its outputs.

**CDI Port**

The CDI port is part of the DEMUX. The external interface signals are listed under “Demultiplexer Interface” on page 70.

**Host / PCI Port**

For a detailed description, see “System Modules” on page 39 and “System Interface Signals” on page 75.

## Decoder Core Modules

The VW2010 decoder core consists of the following modules:

- Variable length decoding unit (VLD)
- Inverse quantization / inverse DCT unit (IQ/IDCT)
- Motion compensation unit (MCU)
- Decoder processor unit (dCPU)

The decoder can handle MPEG-1 and MPEG-2 I, P and B pictures, and MPEG-4 I-VOP and P-VOP.

**Decoder Processor Unit (dCPU)**

The dCPU is implemented using a proprietary RISC processor with up to 4K x 20 bits of microcode. The dCPU controls the operations of the decoder. It sequences the input compressed data through the decompression process up to the VOU input, removes the MPEG video headers on the data, monitors the status of the various modules, and controls the output of the data. The Vweb Corporation provides the microcode in binary format.

The dCPU generates motion vectors and decodes the following video layers:

- Sequence headers
- Group of pictures
- Picture
- Slice
- Macroblock
- Block

**Variable Length Decoding Unit (VLD)**

The VLD unit performs the following functions to start the decoding process:

- Variable-length decoding
- Inverse scan

The VLD uses variable-length decoding to recover the DC and AC coefficients for intra-coded blocks, and DC coefficients for non-intra-coded blocks. From these coefficients the VLD computes a set of predictors for each of the three color components.

Then the VLD uses inverse scan to convert the one-dimensional matrix of predictors into the two-dimensional matrix of coefficients required by the IQ/IDCT unit.

For further details, see the MPEG specification ISO/IEC 13818-2, Clause 7, section 7.3.

### **Inverse Quantization / Inverse DCT Unit (IQ/IDCT)**

The IQ/IDCT unit performs field- or frame-based inverse quantization (IQ) to produce the reconstructed DCT coefficients. Then it performs inverse discrete cosine transform calculations (IDCT) to obtain the inverse transform values, which are needed in the MCU to generate the reconstructed image.

For further details, see the MPEG specification ISO/IEC 13818-2, Clause 7, section 7.4 and 7.5.

### **Motion Compensation Unit (MCU)**

The MCU recreates (reconstructs) pixels based on the data from the IQ/IDCT unit. The MCU takes the decoded motion vectors from the dCPU, and translates them into row and column coordinates. The MCU supports frame and field motion vector types, and implements the following prediction modes:

- Frame prediction mode
- Field prediction mode
- Field prediction mode with 16x8 motion compensation and forward/backward/bi-directional motion vectors.

The MCU is accurate to 1/2 pel and it limits the saturation value of the final reconstructed pixel to between 0 and 255.

For further details, see the MPEG specification ISO/IEC 13818-2, Clause 7, section 7.6.

## **Output Modules**

The VW2010 has two output modules:

- Video output unit (VOU)
- Audio output unit (AOU)

### **Video Output Unit (VOU)**

The VOU includes post-processing filters, mixers and display control timing. The VOU outputs 4:2:2 compatible data in ITU-R.BT.656 format. Under the control of the RISC, user data is converted to Closed Caption or Teletext, and is inserted into the VBI.

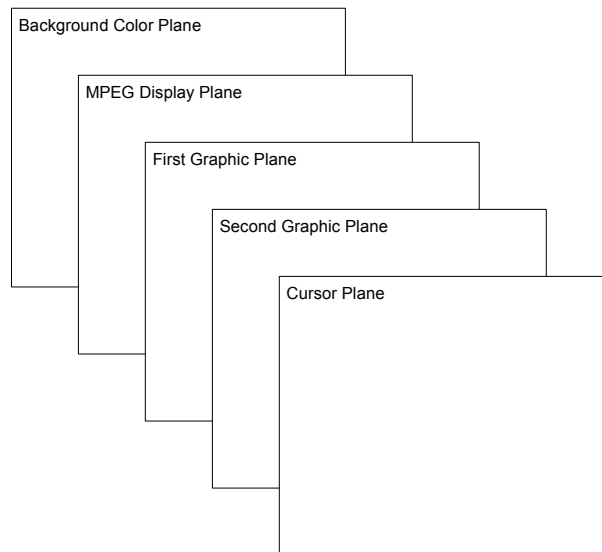
The VOU also manages up to five graphics planes, which can be superimposed onto each other before converting the data to ITU-R-BT.656 format. If the resultant image does not fit within the constraints of the ITU-R-BT.656, then the resultant image will be cut off at the boundary points. The five graphics planes are shown in [Figure 11 on page 34](#).

### **Background Color Plane**

The background plane allows for the padding of a 24-bit YCbCr color around the MPEG display. Alpha blending is not enabled, therefore the background cannot be blended with the MPEG video.

### **MPEG Display Plane**

The MPEG display plane converts the 4:2:0 data to the 4:2:2 output format. It provides support for pan and scan, 1/2 and 1/4 decimation, up to 8x interpolation, and windowing.



**Figure 11 Graphics Plane Hierarchy**

### Graphics Planes

The two graphics planes are identical except for their ordering with respect to alpha blending. Both planes accept graphics input and allow for the following features:

- 2-, 4-, 8- and 24-bit color look-up tables (CLUT)
- Each graphics plane can have its own separate CLUT
- 32-bit ARGB and AYCbCr (alpha-blended RGB and YCbCr):
  - 8 bits alpha (256 levels of transparency)
  - 8 bits Y or R
  - 8 bits Cb or G
  - 8 bits Cr or B
- All input formats are stored in 4:4:4 chroma format in separate fields
- Each CLUT entry uses 32-bit wide ARGB or AYCbCr
- Multiple regions can exist within the graphics plane; however, the regions cannot overlap and two regions cannot be programmed on the same line.

### Cursor Plane

The cursor plane supports five programmable dimensions for the cursor:

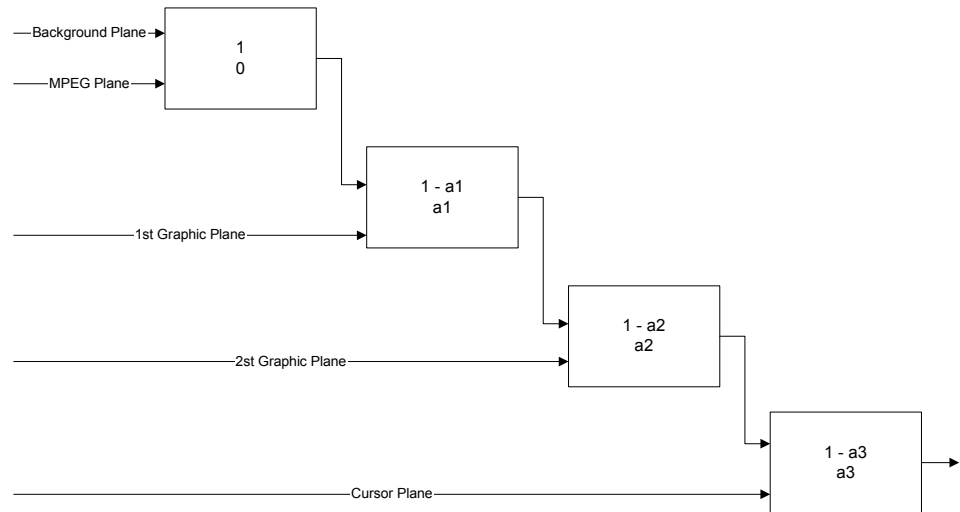
- 8x128 pixels
- 16x64 pixels
- 32x32 pixels
- 64x16 pixels
- 128x8 pixels

The cursor can be placed anywhere on the entire screen. It uses four bits per pixel (16-colors) and a transparency factor.

### Alpha Blending

The various graphics planes are mixed according to the blending scheme shown in [Figure 12 on page 35](#).





**Figure 12 Alpha-Blending Hierarchy**

### Anti-flickering

The VW2010 performs anti-flickering by using the two graphics planes in concert. The two planes must be programmed with the same configuration. A two-tap vertical filter is used to filter one line from each of the graphics planes. Three sets of coefficients are provided:

- $\{1/4, 3/4\}$
- $\{3/4, 1/4\}$
- $\{1/2, 1/2\}$

These three sets of coefficients represent the relative weightings of lines from each of the two graphics planes used in anti-flickering. The three sets of coefficients make possible three different anti-flicker schemes to be implemented using the two graphics planes, depending on the choice of the coefficients (1/4, 1/2 or 3/4) that can be applied to the starting line in the process. After that, the pairs of coefficients applied to subsequent lines are alternated. For example, the first line from plane 1 with coefficient 1/4 is combined with the first line from plane 2 with coefficient 3/4 to produce the first line of filtered output. To generate the second line of output, 3/4 is applied to the second line from plane 1 and 1/4 to the second line from plane 2.

### On-Screen Display (OSD)

The VOU includes two OSD engines, OSD\_0 and OSD\_1. Both can write user data to the two graphics planes described above. User data is written to an OSD engine by means of a PCI, Motorola or Intel interface described in “Host / PCI Interface” on page 41, using the signals described in “System Interface Signals” on page 75.

The operation of the OSD engine is described in the Vweb VW2010 Programmer’s Reference Manual.

## Audio Output Unit (AOU)

The AOU supports two independent output ports, I<sup>2</sup>S and S/P-DIF, of digital audio data output. Both ports support linear PCM audio data output. In addition, on the S/P-DIF port, the output data can be presented either as 2-channel uncompressed data using IEC-958, or as compressed non-linear PCM-encoded audio bit-stream data using IEC-61937 formatting (compressed audio bypass). The IEC-61937 bypass is set up under register control. The AOU generates its own audio timing signals from a single audio master input clock of either 24.576MHz or 16.9344MHz and PLL locked to the decoder video master clock.

The AOU supports the audio sampling frequencies (sampling rates from 8 KHz to 96 KHz) and the bits-per-channel, left/right modes (from 16 to 32 bits) shown in the “Feature List” on page 11. To this end, the audio PLL can generate the audio master clock frequencies shown in Table 7 on page 52.

The AOU also supports user-controlled data pause. During data pause, the output channel continues to send out the last left/right samples prior to the pause state. After the pause state has been cancelled, the audio data resumes its normal operation.

## Application Notes

The VW2010 decoder connects directly, seamlessly, without glue logic, to a video encoder such as the Philips SAA7120, and to an audio DAC such as the Cirrus CS4331, as illustrated in the following figure (based on the schematic of the VwebWin10 Evaluation Board).

The video encoder and audio DAC have their own requirements for input signal filtering and input power smoothing. These requirements are explained in the vendor’s data sheets.

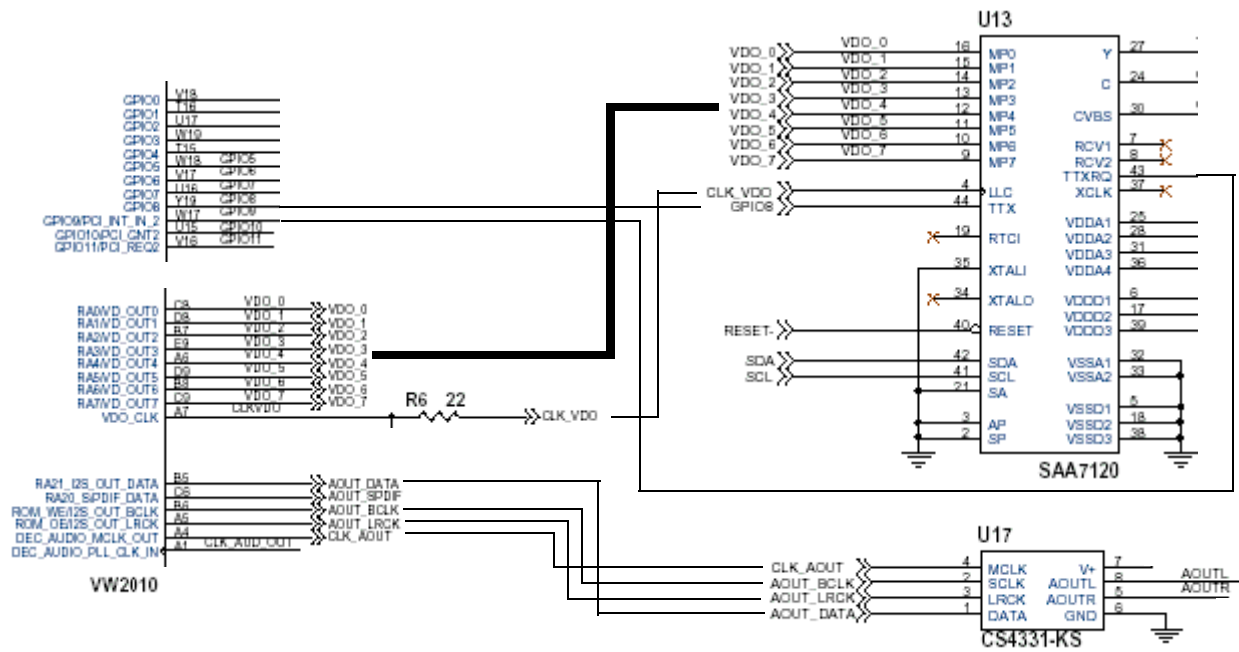


Figure 13 Connections between the MPEG Decoder, Video Encoder and Audio DAC

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## CHAPTER 5

## System Modules

This chapter presents more detailed descriptions of each individual system module's functions. Figure 14 on page 39 summarizes all the modules that constitute the VW2010, and their relationships to each other. The top row of modules (DMA ... PMU) plus the HIU, the RISC, the EMIU, and the DMIU perform system-level functions for the chip.

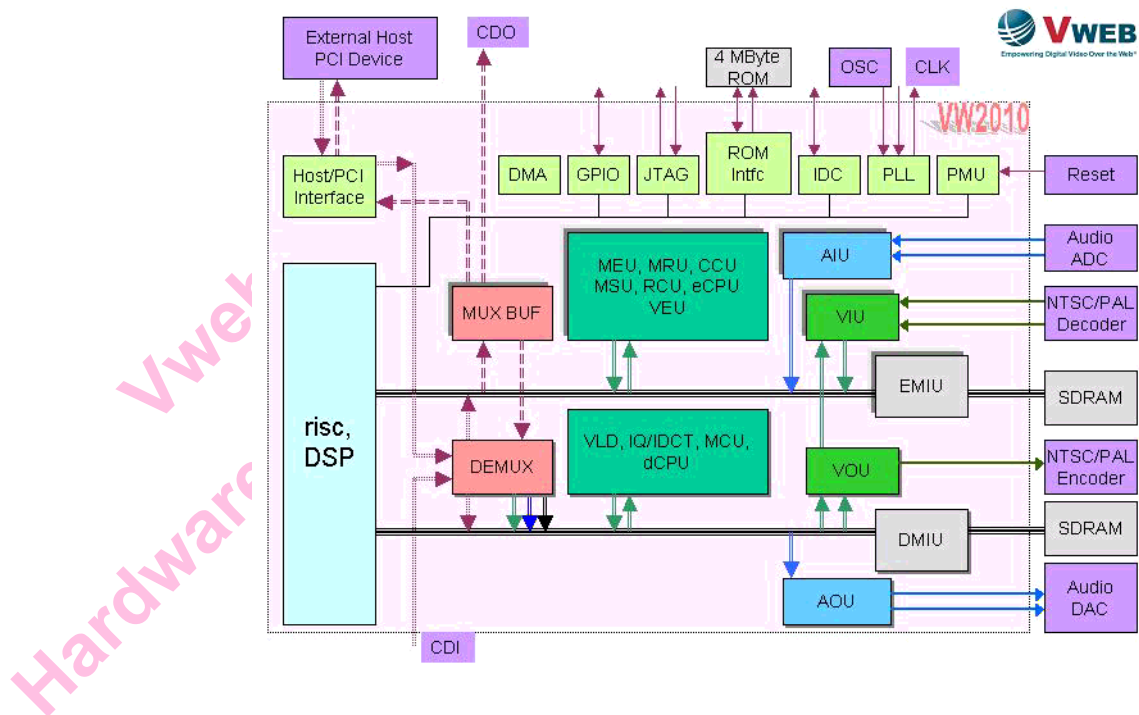


Figure 14 Modules of the VW2010

## Embedded Processor (RISC/DSP)

The embedded processor is a RISC-like RISC engine with extensions to function as an audio DSP. The RISC/DSP implements various functions, including overall control of the VW2010, as well as audio encoding, A/V multiplexing, A/V demultiplexing, and audio decoding.

### RISC Multiplexer

The RISC multiplexer works with the MUX and performs the following tasks:

- Combines the compressed audio, video and user data.
- Generates MPEG-1 system streams, MPEG-2 program streams, or MPEG-2 transport streams (TS, PS, SS or PES bitstreams) suitable for use as input to an off-chip decoder device.

The data can be presented as one of the following:

- MPEG transport stream
- System or program stream
- Independent MPEG elementary streams

### RISC Audio Encoder

The RISC/DSP audio encoder compresses the audio signal by calculating a transform and applying a psychoacoustic model to estimate the noticeable noise level. Then it quantizes and codes the audio data in a way to meet both the bit-rate and the masking requirements. The audio encoder supports the formats shown in the “[Feature List](#)” on [page 11](#).

The audio encoder presents the data to the multiplexer (in the RISC/DSP), where the audio data is multiplexed with video and user data, or processed for network delivery.

### RISC Demultiplexer

The RISC demultiplexer works with the DEMUX and performs the following tasks:

- The RISC processor separates the audio, video, and user data, and places them into separate FIFOs set up and configured by the DEMUX.
- The RISC processor extracts the other program identifiers (PIDs) into separate FIFOs set up and configured by the DEMUX.

### RISC Audio Decoder

The RISC/DSP audio decoder reconstructs the audio by performing an inverse quantization. The audio decoder supports the same formats as the encoder. The audio encoder presents the decompressed audio data to the audio output unit (AOU).

### Data Cache (dmem)

The dmem data cache is an active working memory of the RISC. Parts of dmem are dynamically assigned, as needed, as temporary buffers used by the RISC. This is shown in [Figure 17](#) on [page 48](#).

The section titled “[DMA Controller](#)” on [page 46](#) explains the role of dmem in DMA transfers. For additional details see also the sections titled “[Multiplexer \(MUX\)](#)” on [page 22](#), and “[Demultiplexer \(DEMUX\)](#)” on [page 30](#).

## Memory Interfaces

The VW2010 has two SDRAM interfaces; one for the encoder (EMIU), one for the decoder (DMIU). Each SDRAM interface performs the following functions:

- Provides all required signals to control an external memory device (two 1Mx16, or one 2Mx32).
- Includes a 32-bit data bus and 11-bit row and column address bus operating at 162 MHz.
- Acts as the memory access bandwidth arbitrator among the various modules.
- Supports the following style of 16-bit or 32-bit wide SDRAM parts on the market:
  - 200 MHz (or 5 ns)
  - CAS latency of 3-cycles
  - 11 bits for row and column addressing with up to 2 bank select bits
  - Micron-style power-up sequence

### Encoder Memory Interface Unit (EMIU)

The EMIU performs the functions listed above to control the 4 or 8 Mbytes of SDRAM needed to compress the video images.

### Decoder Memory Interface Unit (DMIU)

The DMIU performs the functions listed above to control the 4 or 8 Mbytes of SDRAM needed to uncompress the video images.

## Host / PCI Interface

### Architecture

The host/PCI interface consists of two internal modules, HIU and PCI. The HIU is a 16-bit core that allows glueless connection to a 16-bit Motorola 68K or Intel x86 type device or host bus; the HIU can be configured to run in one of these host modes. The PCI is a 32-bit 33 MHz core that supports the PCI Local Bus Specification version 2.2. The HIU and PCI both access the outside world via one set of shared pins; that is, the VW2010 can use either the HIU or the PCI interface, but not both at the same time. Therefore, the PCI interface appears as just another host mode (see “[Host Interface Modes](#)” on page 3; see also [Figure 29](#) on page 76).

The host/PCI interface is accessible from an external host or PCI device, as well as from the main RISC processor embedded in the VW2010. Internally, specific hosts (Motorola, Intel, PCI, and the main RISC embedded in the chip) appear simply as I/O devices sharing the same address bus and data bus into the HIU core module.

The host interface mode - that is, how the host/PCI interface is configured for external access - is selected as described in “[Host Mode](#)” on page 49.

### Applications

The versatility of the VW2010 host/PCI interface allows a variety of applications:

- In an embedded design, the VW2010 can access off-chip devices through the host/PCI interface.

- In a host-based design, the host/PCI interface connects the VW2010 to a standard PCI bus; that is, to the host motherboard and other plug-in cards.
- In stand-alone designs, the host/PCI interface allows glueless connection to a standard Motorola or Intel device, as well as to a ROM device. In this mode, the external host processor can communicate with the VW2010 using the appropriate HIU host mode running at a clock speed up to 30 MHz.

## Functions

The host/PCI interface allows access to the internal hardware registers in the VW2010, as well as to the encoder SDRAM and the decoder SDRAM. The host/PCI interface includes an interrupt controller that manages interrupts from the individual modules, A/V buffers and FIFOs in the chip, and allows the external host to determine the source of the interrupt. The host/PCI interface allows the external host to soft-reset individual modules in the encoder, the decoder, as well as the main RISC processor. The host/PCI interface responds to and facilitates DMA requests. And the host/PCI interface includes a set of internal registers that hold the parameters for the A/V capture and encoding process, as well as the control bits to start and stop the encoder and decoder.

The host/PCI interface is the controller and the conduit for different kinds of data that could appear on the host/PCI bus:

- Encoder and decoder parameters, such as quantization matrix, filter coefficients, etc.; encoder and decoder control signals
- Microcode for the main RISC, the encoder CPU and RCU, and decoder CPU
- Compressed A/V bitstream (CDI, CDO) in SS, TS, PS, ES or PES formats
- User data, VBI data

## Data Paths

The host/PCI interface sets up (can be set up to provide) the following data paths in either host or PCI mode:

- CDO write
- CDI read
- SDRAM read/write
- Register read/write
- Microcode download
- Boot-time download paths
- Soft reset

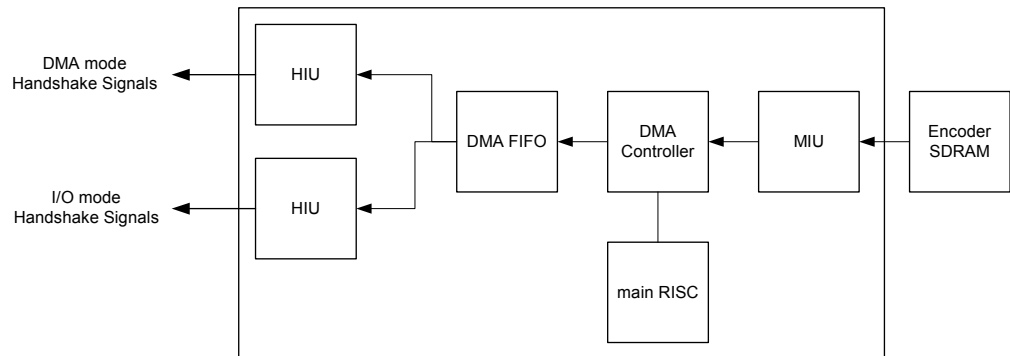
The following sections describe the physical data paths in each case. The actual implementation is set up and executed by means of the internal HIU registers, and is the topic for the VW2010 Register Specifications and the VW2010 Programmer's Reference manuals.

### CDO Write

Compressed, encoded data can be saved out the host/PCI interface, and written to external host memory or other storage device. The source of the data can be the A/V buffers (which are set up in encoder SDRAM), in which case registers are used to set up the buffer and FIFO watermarks and other controls. The source of the data can also be the encoder or decoder SDRAM in general (not restricted to A/V data).



The data path is shown in the following figure. CDO is passed from SDRAM, to the MIU, to the DMA controller / DMA FIFO, and to the HIU.



**Figure 15 CDO Data Path via the HIU**

The figure above is slightly misleading in the sense that there is only one HIU, but it can be set up in two modes, DMA or I/O. The main RISC microcode sets up the DMA transfer. The host sets up I/O read mode.

In DMA mode, the interface signals are the following:

- host\_hiu\_cdo\_req (out); the chip has data ready to send
- hiu\_host\_cdo\_ack (in); the host has received a line of data
- host data bus (out)
- hiu\_host\_dtack (out); the chip has sent all the data it had; the current cycle has finished.

In DMA mode, the chip sends the next line of data as soon as it sees cdo\_ack from the host; it does not send another cdo\_req.

In host I/O read mode, the interface signals are the following:

- host\_hiu\_cdo\_req (out)
- host\_hiu\_cs (in)
- host\_hiu\_as (in)
- host data bus (out)
- host address bus
- hiu\_host\_dtack (out)
- host\_hiu\_rw (in)

In host mode the full handshake protocol is set up and executed for every byte of data.

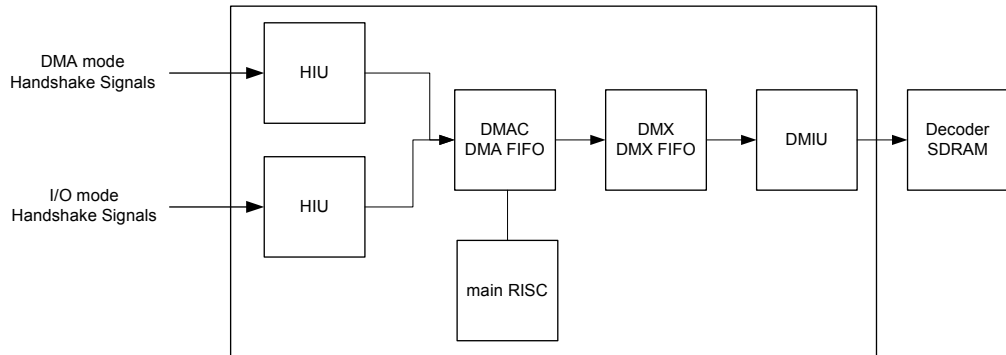
These handshake signals are described in the chapter titled “System Interface Signals” on page 75, and the interface timing signals are shown in “Electrical Characteristics” on page 147.

#### **CDI Read**

Compressed, encoded data can be captured from external host memory or other storage device via the host/PCI interface, and written to the decoder SDRAM. The desti-

nation of the data can be the A/V buffers (which are set up in decoder SDRAM), in which case registers are used to set up the buffer and FIFO watermarks and other controls. The destination of the data can also be the encoder or decoder SDRAM in general (not restricted to A/V data).

The data path is shown in the following figure. CDI is passed from the HIU, to the DMUX FIFO, to the DMIU, and to the SDRAM.



**Figure 16** CDI Data Path via the HIU

The figure above is slightly misleading in the sense that there is only one HIU, but it can be set up in two modes, DMA or I/O. The main RISC microcode sets up the DMA transfer. The host sets up I/O read mode.

In DMA mode, the interface signals are the following:

- host\_hiu\_cdi\_req (out); the chip is ready to receive data
- hiu\_host\_cdi\_ack (in); the host is ready to send data
- host data bus (out)
- hiu\_host\_dtack (out); the chip has received all the data it can handle; the current cycle has finished.

In DMA mode the chip accepts data as fast as the host can send it.

In host I/O read mode, the interface signals are the following:

- host\_hiu\_cdi\_req (out)
- host\_hiu\_cs (in)
- host\_hiu\_as (in)
- host data bus (in)
- host address bus
- hiu\_host\_dtack (out)
- host\_hiu\_rw (in)

In host mode the full handshake protocol is set up and executed for every byte of data.

These handshake signals are described in the chapter titled “[System Interface Signals](#)” on page 75, and the interface timing signals are shown in “[Electrical Characteristics](#)” on page 147.

**SDRAM Read/Write**

The data path for SDRAM access is as shown in the figures above. The HIU can access encoder SDRAM after the SDRAM has been initialized by the VW2010, which is about 12000 clock cycles after reset or power-up. Data between the HIU and SDRAM is passed via a set of HIU registers, with appropriate adjustments for the 16-bit register widths, and the 32 bits for data and 20 bits for address.

SDRAM addressing through the HIU is word-aligned; that is, 32 bits wide. For example, by putting 0x0001 on host\_hiu\_data, the host is trying to access physical SDRAM location 0x0004.

The HIU can also access the decoder SDRAM, but through a different set of registers. In addition, decoder SDRAM is 64 bits wide and is addressed by 24 bits. Therefore, the 16-bit registers must be used in the appropriate combinations to accommodate these bus widths.

**Register Read/Write**

The HIU provides an I/O path to the chip’s internal hardware registers. The HIU gains access by issuing a register\_read or register\_write command. An HIU command consists of two parts, the HIU command code (such as read or write) and the register address. The HIU can access those registers that are shown in the VW2010 Register Specifications with the legend “Access: Host R/W.” The register addresses are also shown in that manual. The HIU commands are described in the VW2010 Programmer’s Reference Manual.

**Soft Reset**

The HIU allows an external host to reset individual modules in the chip, either by hardware reset at power up, or by software at any time (“soft-reset”). Soft-reset is implemented by means of a reset register for the encoder modules and another reset register for the decoder modules.

**Microcode Download**

The HIU provides a path to download microcode into the encoder CPU, decoder CPU, and the main RISC. Microcode download is similar to register access and SDRAM access: it requires an HIU command (of the form, load\_[target\_module]\_microcode and microcode\_download\_done), and the HIU must accommodate the differences between the instruction lengths (24 bits for the RCU, 20 bits for the eCPU and the dCPU), the data-in bus width (16 bits), and the widths of the internal registers (16 bits).

The microcode download is a module-specific multi-step process, and is described in the VW2010 Programmer’s Reference Manual.

**Boot-time Download Paths**

The VW2010 supports three boot modes:

- Boot from ROM
- Boot from ICI
- Boot from host

In all three cases, microcode for the main RISC, the encoder CPU and the decoder CPU is loaded into decoder SDRAM.

**Boot from ROM** - When this option is used, all microcode should reside in external ROM. After reset is removed from the chip, all modules need to be initialized. At this time the main RISC performs a hardware jump to a location that is mapped to the ROM area. The code inside the ROM must include a small bootstrap program that will copy a code image into decoder SDRAM, then perform a jump to the beginning of the code image. This code image will be responsible for the rest of the encoder and decoder initialization. This mode is used in stand-alone applications.

**Boot from ICI** - When this option is used, a bootstrap loader resides in an SEEPROM. Since the SEEPROM is small (128 bytes), the rest of the microcode must be downloaded through the HIU. Therefore, this option is not used in stand-alone applications.

**Boot from host** - When this mode is used, all microcode is downloaded through the HIU. There is no need for either ROM or SEEPROM in the system.

In this mode, the external host is responsible for the downloading procedure. Once all of the microcode is download and all of the modules are being initalized, the external host can start the encoder, decoder and the main RISC.

## DMA Controller

### DMA Features

The DMA controller in the VW2010 chip transfers blocks of data, independent of the embedded main RISC processor or the external PCI host. Data is moved on the host/PCI interface port and the internal encoder or decoder SDRAM buses shown in [Figure 2 on page 5](#). The following is a summary of DMA features:

- The DMA engine uses two DMA channels, 0 and 1. The two DMA channels operate completely independently from each other.
- The DMA engine operates by executing link lists. It can execute up to eight link lists, 0-7. Each link list consists of any number of descriptors. Each descriptor consists of four consecutive 4-byte (32-bit) fields that specify transfer parameters. Each link list has a specific starting address. Link lists and descriptors are described in the Vweb VW2010 Programmer's Reference Manual.
- The DMA transfer size is 1024 bytes per descriptor in a link list. The total amount of data per DMA transfer is the buffer size or available memory (depending on the source of data for the transfer). The DMA will flush any remaining data, even if less than the 1KB transfer size, using the last descriptor in the link list.
- The DMA engine is controlled by eight identical sets of registers; one set per link list. The DMA registers are described in the Vweb VW2010 Register Specifications.
- The DMA engine can operate in direct or in chaining (scatter/gather) mode.

- The DMA engine supports word-aligned (32-bit aligned) transfers only.
- The DMA arbiter manages the DMA channels, link lists and descriptors in a round-robin / time-multiplexed fashion. The DMA arbiter is implemented fully in hardware, with no microcode overhead.  
The operation of the DMA arbiter is described in the Vweb VW2010 Programmer's Reference Manual.
- The DMA engine generates an interrupt upon completion of a transfer.

Note the following:

- A DMA channel is the logical assignment of a link list to a DMA engine, and the specific configuration of the physical data paths in the chip so that a physical connection would be established between the source and destination device to effect the data transfer specified in a particular descriptor in the link list.
- The operation of the DMA controller is totally transparent to the external host processor.
- The DMA controller, the DMA arbiter, the DMA channels and the link lists are accessible only by the RISC processor embedded in the VW2010.
- External host access to the DMA controller, and external host control of a DMA transfer, are implemented by means of high-level protocols and APIs, not by direct access to the DMA controller and its internal workings.  
The API is described in the Vweb VW2010 Programmer's Reference Manual.
- The link lists are generated and stored in SDRAM by the main RISC.
- The DMA configuration registers are set by the main RISC.
- The descriptors are downloaded into the other DMA registers by the main RISC.
- All hardware and software handshake is controlled by the main RISC. In hardware the DMA transfer specified in a descriptor proceeds with the usual handshake of DMA\_Request and DMA\_Grant signals.
- The DMA arbiter resolves race conditions (two channels issuing simultaneous bus requests), as well as simultaneous memory hits (two channels accessing the same address), by allowing one channel to go first, and making sure the other one goes next, ahead of any additional descriptors on the first channel that may be waiting.

## DMA Data Paths

In the VW2010, DMA transfers can take place between the devices shown in the following figure. However, that not all of the possible data paths between these devices make sense, and therefore some of them are not supported in firmware (see the Vweb VW2010 Programmer's Reference Manual for details).

A DMA channel is actually established between dedicated buffers set up in the encoder or decoder SDRAM (or in host memory) and the dmem (data cache memory) in the main RISC processor (see [“Encoder Buffers” on page 22](#) and [“Decoder Buffers” on page 30](#)); that is, between

- (1) the video, audio, user and other buffers in encoder or decoder SDRAM (or corresponding areas set up in host memory), and
- (2) the host/PCI, MUX or DEMUX areas in dmem.

This is illustrated in [Figure 17 on page 48](#).

Dmem is a 16 KB cache, which is implemented as dual-port memory; therefore it can DMA 8 KB at a time.

Note that there are two paths from the DMA engine into encoder or decoder SDRAM:

- Directly into the SDRAM controller (EMIU or DMIU), or
- Via the buffer controller (BUF or DEMUX) into the SDRAM controller (EMIU or DMIU).

The significance of the difference between these two paths is explained in the Vweb VW2010 Programmer's Reference Manual

In either case, the SDRAM controller (EMIU or DMIU) is always the hardware interface to the external (encoder or decoder) SDRAM. The HIU is always the controller for the external host/PCI RAM.

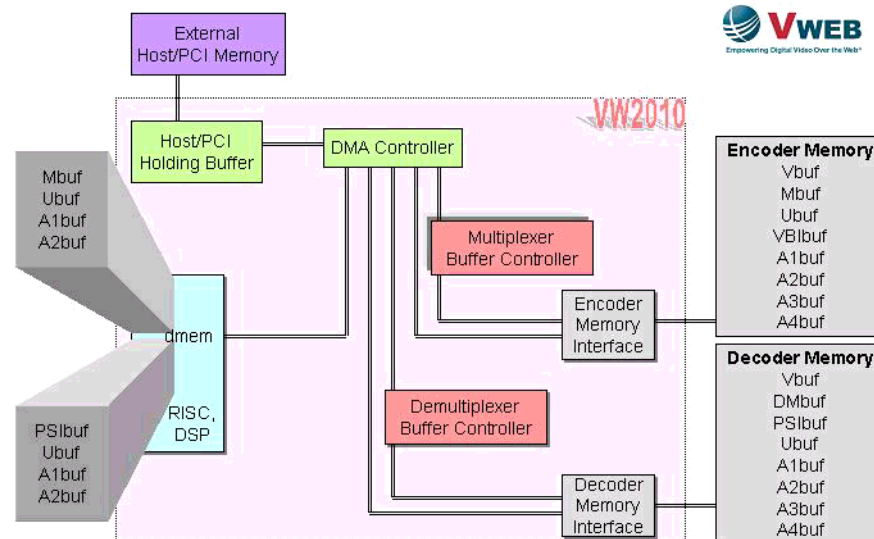


Figure 17 SDRAM and dmem Buffers Active in DMA Transfers in the VW2010

## ROM Interface (RIU)

An external ROM may be used to store the bootstrap code and the initial values for internal registers. If so, the ROM may be used either by the embedded main RISC processor or by the external host processor. The VW2010 supports physical ROM sizes up to 4M bytes (1M typical).

When the ROM is selected and its output is enabled, using the rom\_cs and rom\_oe signals from the VW2010 chip, the ROM puts its contents onto the rom\_data bus. When

the rom\_cs and rom\_oe signals are not active, the rom\_data bus is used to specify the VW2010 chip's power-up modes.

## Power-Up Modes

The ROM data bus is used for specific functions at power-up reset, as specified below. The state of the ROM data bus pins is latched into registers at reset; the registers can then be read by software.

### Boot Mode

rom\_data[2] selects the boot mode:

1 = Boot from ROM

0 = Boot from host (via ICI or HIU, set by rom\_data[6])

rom\_data[6] further refines the selection of the boot mode:

1 = Boot from ICI

0 = Boot from host (in PCI, Motorola or Intel mode, set by rom\_data[1:0])

### Host Mode

rom\_data[1:0] select the HIU's host mode:

00 = reserved

01 = Motorola 16-bit async mode

10 = PCI mode

11 = Intel 16-bit mode

### PCI Mode

rom\_data[4] selects the PCI mode:

1 = reserved

0 = Target mode (PCI slave mode; the VW2010 is DMA bus master)

### Boot Mode Stuffing Options

The rom\_data pins have internal pull-up resistors (~100K ohms); therefore, at boot time the rom\_data pins default to high (1). This is an invalid configuration state; therefore the chip's configuration must be set by using external 10K pull-down resistors ("stuffing option") to pull the appropriate pins low (0).

Example:

Select the PCI host interface mode by setting rom\_data[1:0] to 10; that is, not stuffing the external pull-down resistor option on rom\_data[1] to leave it high, and stuffing it on rom\_data[0] to pull it low.

**Table 5 Boot Mode Selection Truth Table**

rom_data [ ]								Boot Mode
7	6	5	4	3	2	1	0	
	0		x		1	x	x	See "Boot from ROM" on page 46
	1		x		0	x	x	See "Boot from ICI" on page 46
	0		x		0	0	1	Boot from host in Motorola mode
	0		0		0	1	0	Boot from host in PCI target mode
	0		x		0	1	1	Boot from host in Intel mode

**Table 6 Boot Mode Pull-Down Resistor Stuffing Option**

rom_data [ ]								Boot Mode
7	6	5	4	3	2	1	0	
	in							See “Boot from ROM” on page 46
					in			See “Boot from ICI” on page 46
	in				in	in		Boot from host in Motorola mode
	in		in		in		in	Boot from host in PCI target mode
	in				in			Boot from host in Intel mode

**EJTAG Enable**

rom\_data[3] enables the EJTAG port (switches between EJTAG and VBI):

1 = Enable (the VW2010 chip runs in EJTAG mode)

0 = Disable (the VW2010 chip runs in VBI mode)

And, accordingly, rom\_data[3] switches the direction of the VBI bus:

1 = Output (the VW2010 chip outputs EJTAG data)

0 = Input (the VW2010 chip accepts VBI data)

*Note:* See important comments under “EJTAG Mode” on page 62.

**Chip Mode Select**

rom\_data[5] selects where the Vweb firmware resides:

0 = Microcode resides in decoder SDRAM

In other words:

Set the chip in VW2010 mode by stuffing the external pull-down resistor option on the ROM\_DATA[5] pin to pull it low. This has the effect of loading the Vweb firmware into the chip’s decoder SDRAM.

## General Purpose I/O (GPIO)

The VW2010 supports 12 pins of GPIO, which can be used as desired or reassigned to specific functions, under firmware control; for example:

- Pairs of GPIO pins can be assigned (by firmware) to serve a second ICI port. See “GPIO Signals” on page 82. The actual GPIO pins selected for this purpose depend on the specific board design; for example, pins 1:0, 2:1, 11:10, etc., have been used on various Vweb VW2010-based boards.
- GPIO pins 11:8 can be assigned (by firmware) to control the PCI port when the chip is in PCI host mode. See “GPIO Signals” on page 82.



- These and all other GPIO pins can, of course, be also used as general input, output or bi-directional (I/O) pins.

The GPIO module is controlled by two registers, data and direction. All GPIO pins default to inputs after a reset, and can be independently reconfigured as input or output by the GPIO registers.

Reading from and writing to a GPIO port is a two-step process. First, the GPIO direction register must be programmed (as input for read, output for write) in the bit position that corresponds to the GPIO pin. Then the data is read from (or written to) the GPIO data register.

*Note:* Any use of GPIO pins requires appropriate firmware support.

## Inter-Chip Communication Interface (ICI)

The VW2010 supports two pins for ICI, which is functionally similar to Philips I<sup>2</sup>C master mode. The VW2010 can be booted from a 128-byte SEEPROM which is connected to the ICI bus at boottime. After booting up, the VW2010 resumes normal operation in ICI master mode, to program I<sup>2</sup>C slave devices such as the SAA7115, for example.

*Note:* The current version of the Vweb software supports two ICI ports.

The port on the SDA and SCL pins is of the type that sends one byte of data on every ICI cycle, or a series of subaddress+data pairs on every ICI cycle.

The port implemented on GPIO pins (see “GPIO Signals” on page 82) is of the type that sends 2-256 data bytes on every ICI cycle.

See the Vweb VW2010 Programmer’s Reference Manual for details.

## Main Phase Locked Loop (PLL)

The main PLL generates the 162 MHz system clock and all other internal high-frequency clocks used in the VW2010. The PLL requires a 27 MHz external oscillator to run it.

The internal PLL can be disabled (bypassed) by asserting a bypass signal. In such a case, the 162 MHz system clock from an external source can be applied on the same input that is normally used for the 27 MHz oscillator input.

## Audio PLL

The audio PLL generates the audio master clocks shown in [Table 7 on page 52](#) to drive the external audio ADC and DAC devices. The audio output clock is derived from the 27 MHz clock source, and is always equal to 256 times the selected sampling rate.

**Table 7 Audio PLL Output Frequencies**

Sampling Frequency (kHz)	PLL Output (MHz)
8	2.048
16	4.096
22.05	5.6558
24	6.144
32	8.192
44.1	11.289
48	12.288
96	24.576

If the audio PLL is not used, similar clock signals can be generated on the board and used as inputs to the VW2010's audio input and audio output modules.

## Power Management (PMU)

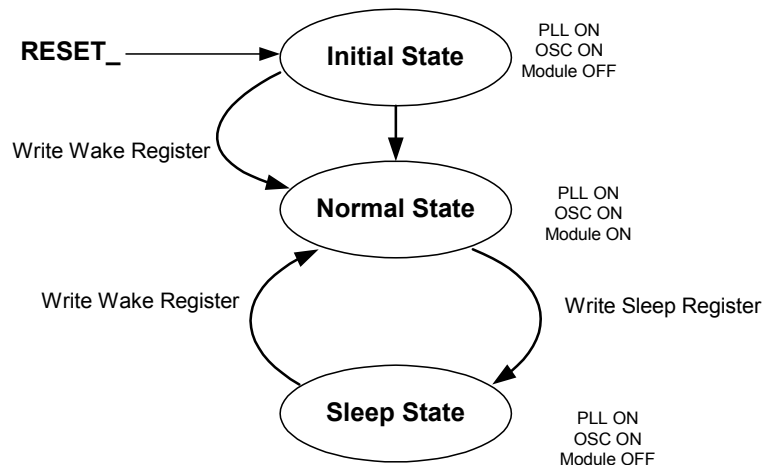
The VW2010 uses the techniques described below to reduce the operating power requirements of the device. The goal is to keep the standard operational power under 1 W. Its core operates at 1.8 V, and its I/O operates at 3.3 V with 5 V tolerance. The VW2010 has three basic power states: initial, sleep and normal, as summarized in [Figure 18 on page 53](#) and described in the following sections.

### Initial State

After applying power or resetting the VW2010, the VW2010 enters the initial state. The external power-up or software reset generates an internal system reset that remains asserted for 32 clocks after the reset input is de-asserted. In the initial state, the system clock (162 MHz) is on, allowing the embedded or external host processor to configure the system. In this state:

- The PLL is on.
- The oscillator is operating at 162MHz.
- The system clock is on.
- The embedded or external host is on.
- The subsystem clocks are off.

- The VW2010 modules are off.



**Figure 18 Power-On / Reset States of the VW2010**

### Normal State

As soon as the embedded or external host turns on the subsystem clocks (by writing to the wake-up register either from the initial state or from the sleep state), the VW2010 enters the normal (working) state.

In the normal state, the VW2010 is processing data. In this state:

- The PLL is generating high-frequency clocks.
- The oscillator is operating at 162MHz.
- The system clock is on.
- The embedded or external host is on.
- The subsystem clocks are on.
- The VW2010 modules are on.

Note that, in the normal state, selected subsystem clocks may be turned on or off by writing to the clock control registers.

### Sleep State

The VW2010 enters the sleep state when the embedded or external host writes to the sleep register. In the sleep state, the system clock is off. In this state:

- The PLL is on.
- The oscillator is operating at 162MHz.
- The system clock is off.
- The embedded or external host is on.
- The subsystem clocks are off.
- The VW2010 modules are off.

Note that, by writing to clock control registers, selected subsystem clocks may be on or off, and the SDRAM auto-refresh may be set on or off, as desired in order to manage the chip's power consumption.

## JTAG

The VW2010 provides a test access port per IEEE Standard 1149.1, "Test Access Port and Boundary Scan Architecture." This port allows for boundary scan testing of the VW2010 on the board on which it is installed.

## Extended JTAG

The VW2010 also provides an extended test access port with additional functions that a JTAG emulator can use to test or control the chip, in accordance with the EPI (Embedded Performance, Inc.) EJTAG 2.0 protocol.

*Note:* EJTAG is for internal Vweb use only.

## Application Notes

### Basic Design

#### **Design Example**

A board design using the components described above is the Vweb Win10 Evaluation Board. The glueless connections between the Vweb part and the vendor parts is shown on the Win10 schematics. Excerpts from the schematics of this and other Vweb boards are shown in the following figures.

#### **Clock Source**

The VW2010 requires one external crystal oscillator to generate the basic 27 MHz clock, as illustrated in the next figure. The VW2010 generates internal and external clocks from this input.

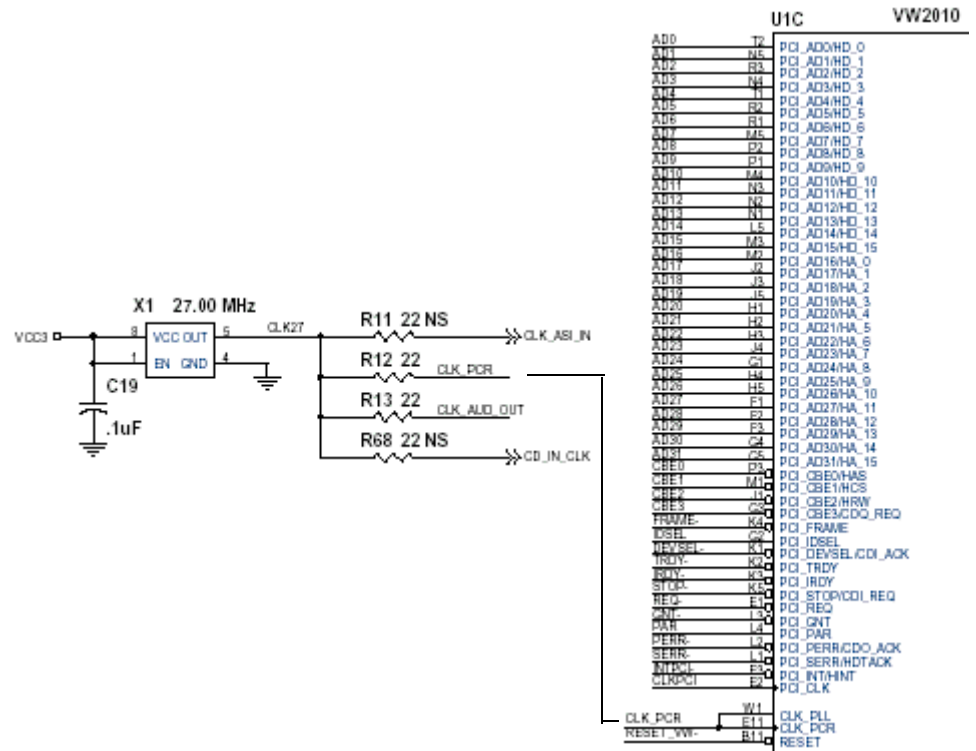


Figure 19 VW2010 External Clock Oscillator

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SDRAM Interface

The VW2010 encoder connects directly, seamlessly, without glue logic, to SDRAM chip(s) such as the Micron MT48LC2M32 as illustrated in the next figure.

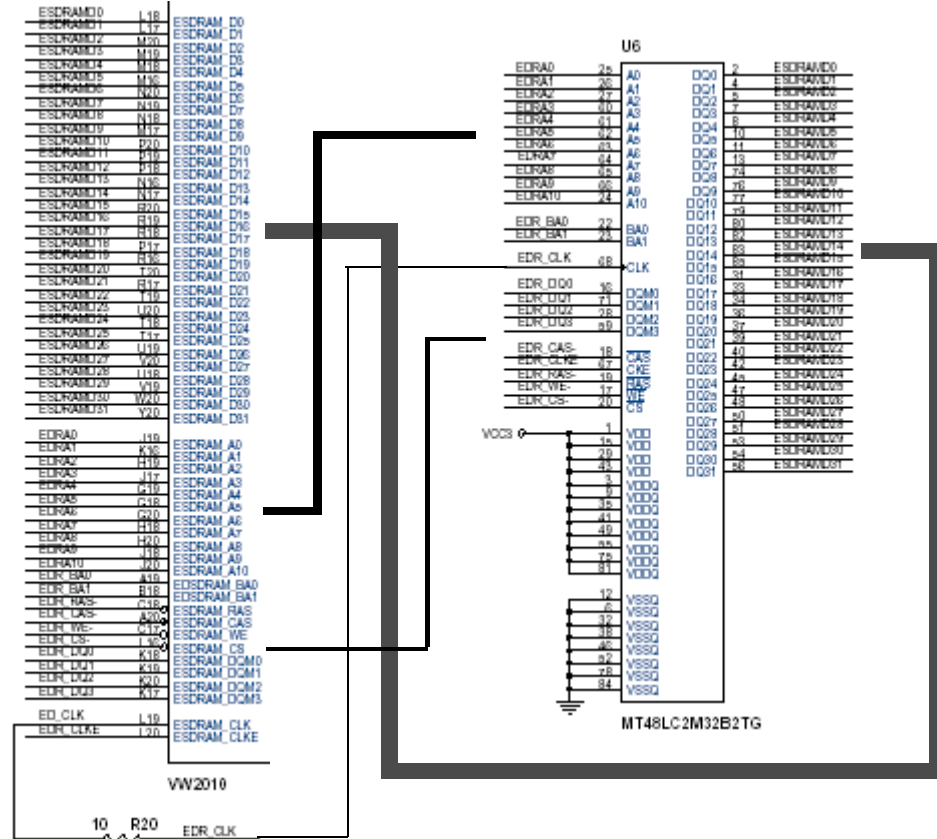


Figure 20 VW2010 Encoder 2M32 SDRAM Interface

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Hardware Reference

The VW2010 decoder connects directly, seamlessly, without glue logic, to SDRAM chip(s) such as the Micron MT48LC1M16 or MT48MC2M32 as illustrated in the next two figures.

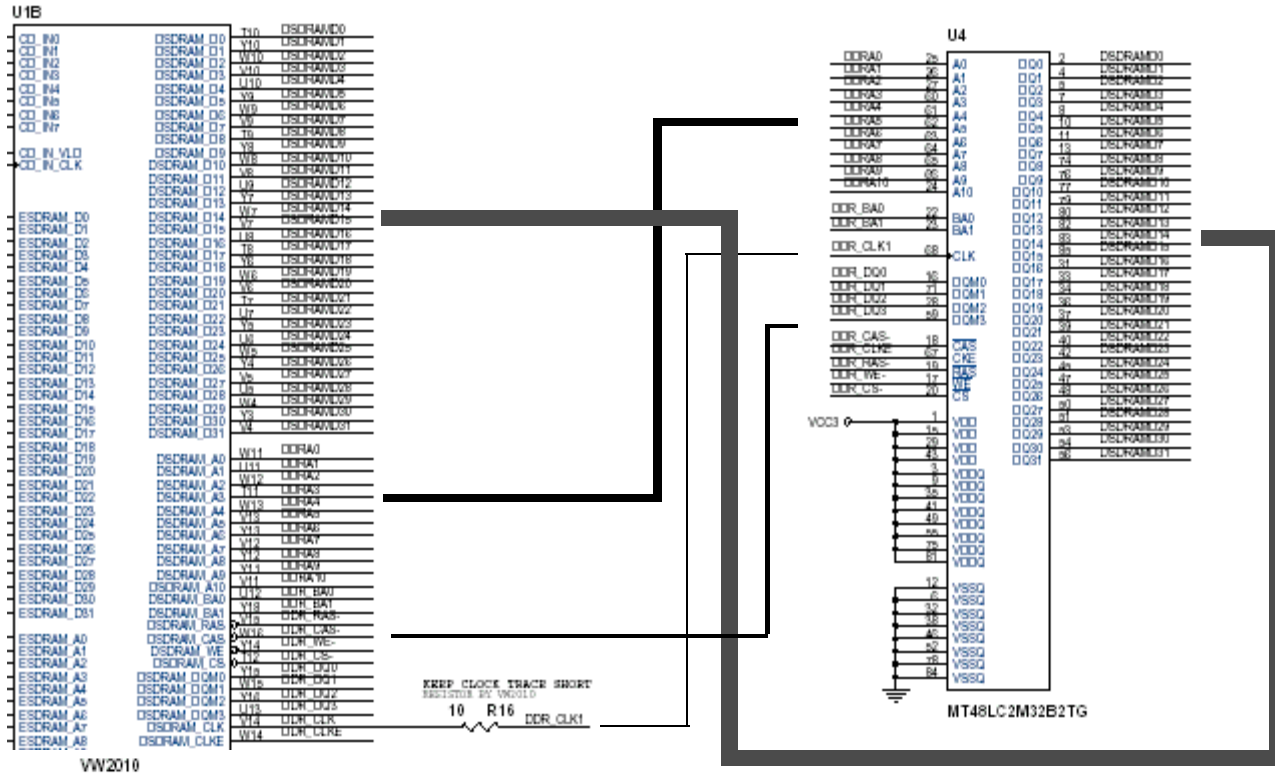


Figure 21 VW2010 Decoder 2M32 SDRAM Interface

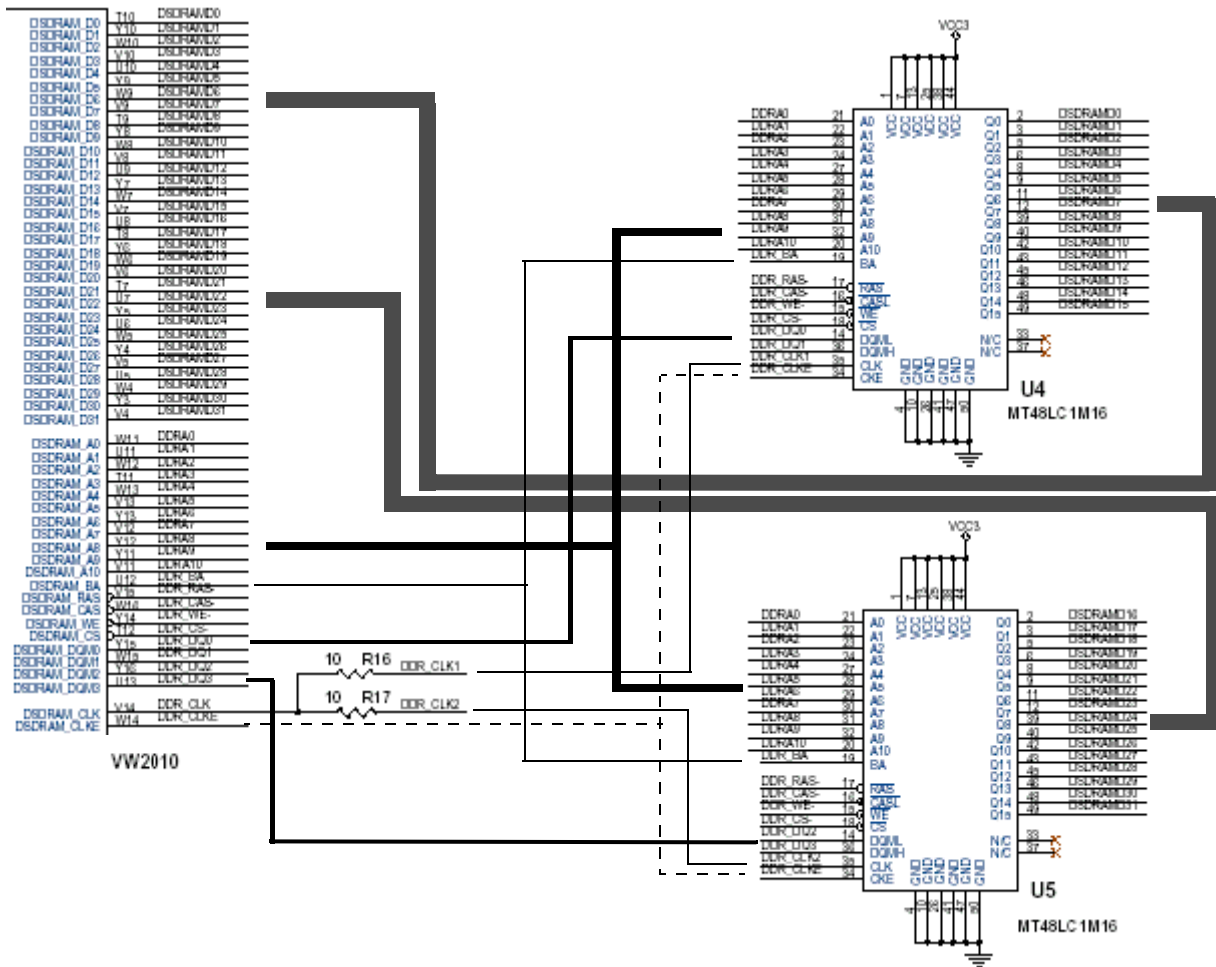


Figure 22 VW2010 Decoder 1M16 SDRAM Interface

**ROM Interface**

The VW2010 ROM interface connects directly, seamlessly, without glue logic, to a ROM chip such as the Atmel AT49BV1614 which is used to store all of the VW2010 microcode. This is illustrated in the next figure. However, because the ROM signal lines are active only at boot time, they are used for other purposes at other times. This is also illustrated in the next figure.



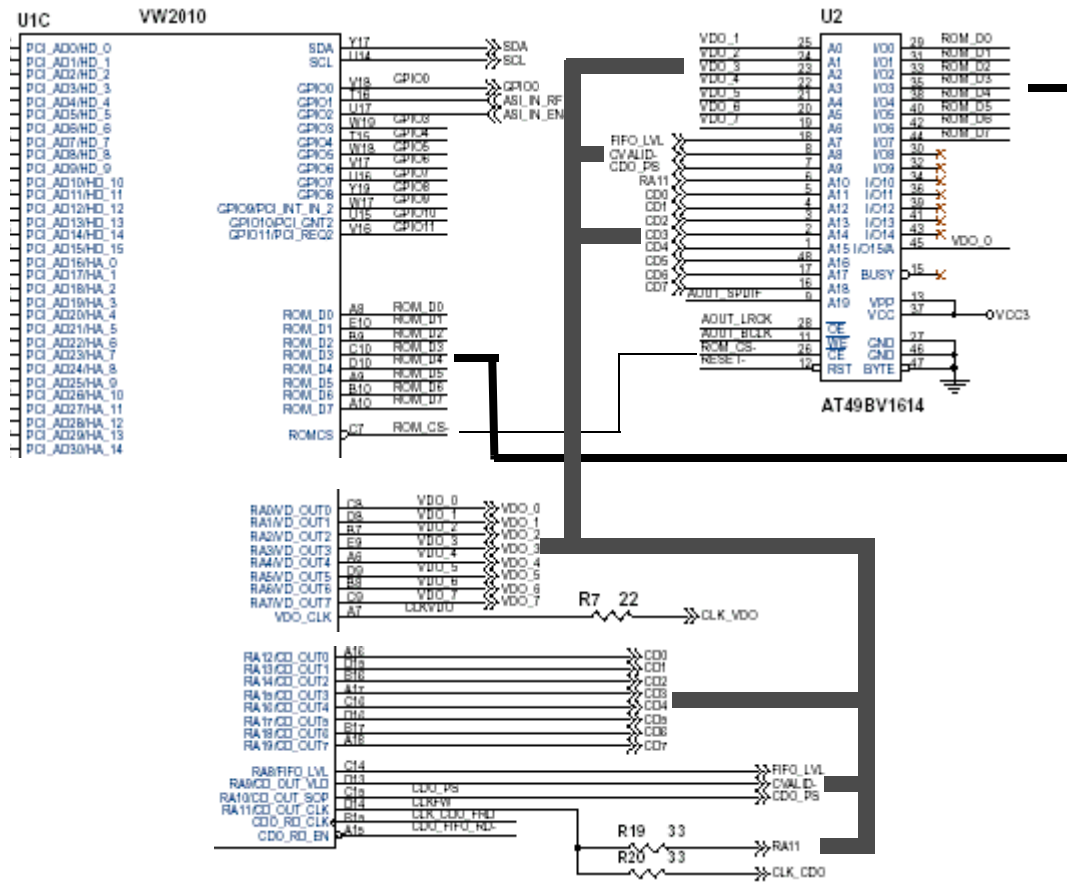


Figure 23 VW2010 ROM Interface

However, in some designs the user may decide to use a smaller EEPROM, such as the Xicor X24F032, to store only boot code (and download the full microcode at boot time from the external host via the host/PCI bus). This is illustrated in the next figure.

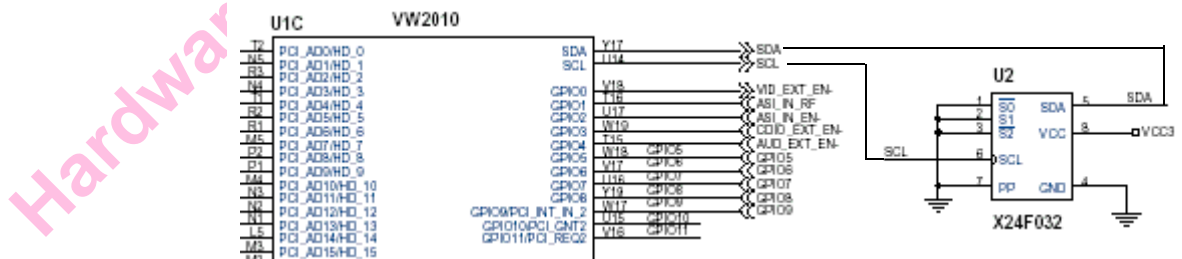


Figure 24 VW2010 EEPROM Interface

Multiple Devices

Two or more VW2010 devices can be connected to a single host bus or PCI bus.

- If connected to a PCI bus, the VW2010 devices must be configured as PCI slave (target) and the external host must be PCI host.
- If the VW2010 devices are connected to a Motorola- or Intel-style host, an external address decoder is required.

PCI Interface

The VW2010 HIU connects directly, seamlessly, without glue logic, to a host/PCI port such as the typical edge connector on a PCI card as illustrated in the next figure. To put the VW2010 in PCI mode, proceed as follows:

- Set the ROM-Data pins [6:0] to b'0x0x010, to select PCI mode (see Table 5 and Table 6 on page 50).

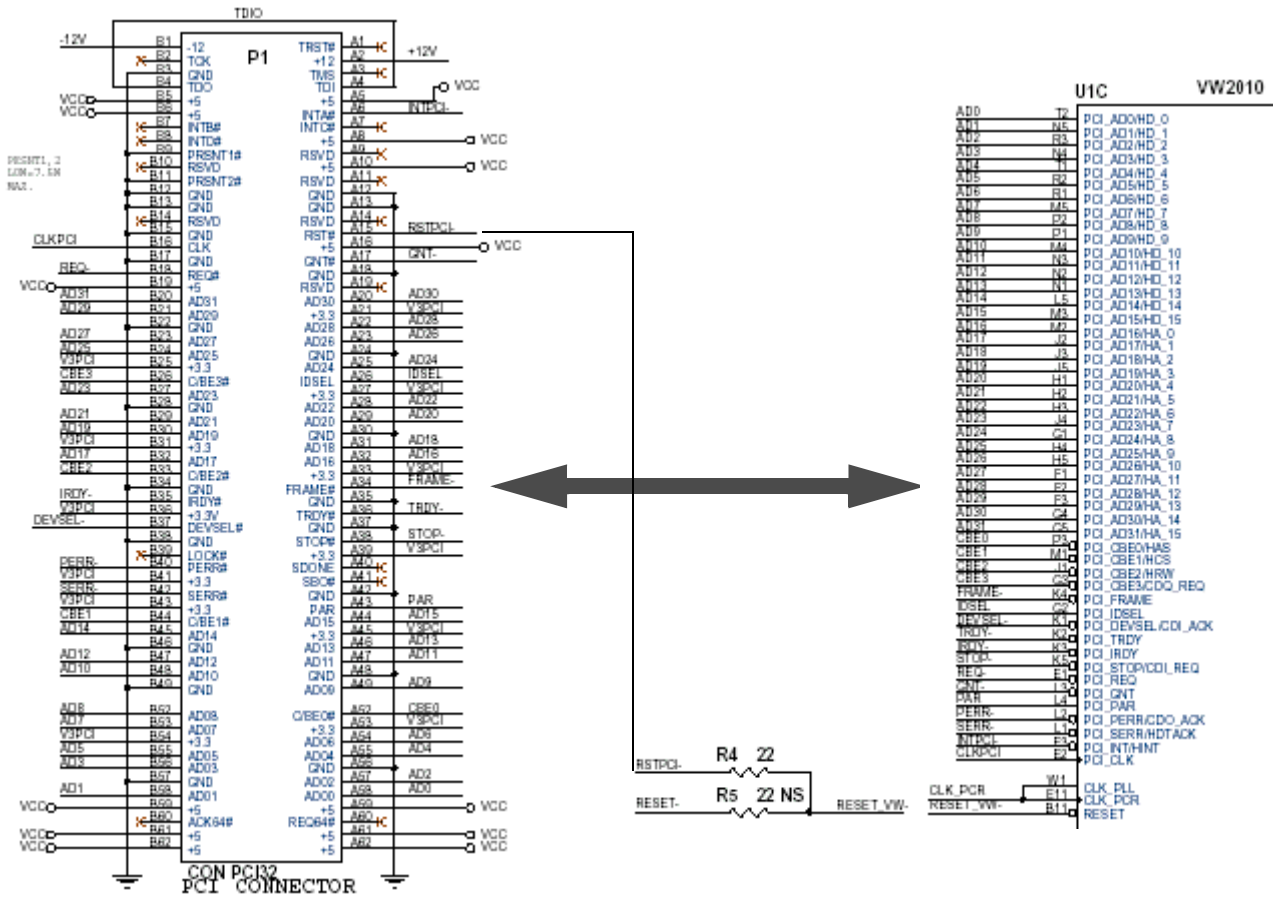


Figure 25 VW2010 PCI Interface

### Host Interface

The same set of pins that comprise the chip's PCI port are also used as the HIU port in Motorola or Intel mode. The VW2010 HIU connects directly, seamlessly, without glue logic, to a host interface such as USB chip, as illustrated in the next figure. To put the VW2010 in host mode, proceed as follows:

- Set the ROM-Data pins [6:0] to b'0x1x001 to select Motorola mode, or to b'0x1x011 to select Intel mode (see Table 5 and Table 6 on page 50).
- Tie the unused input pins to ground (see Table 15 on page 142).

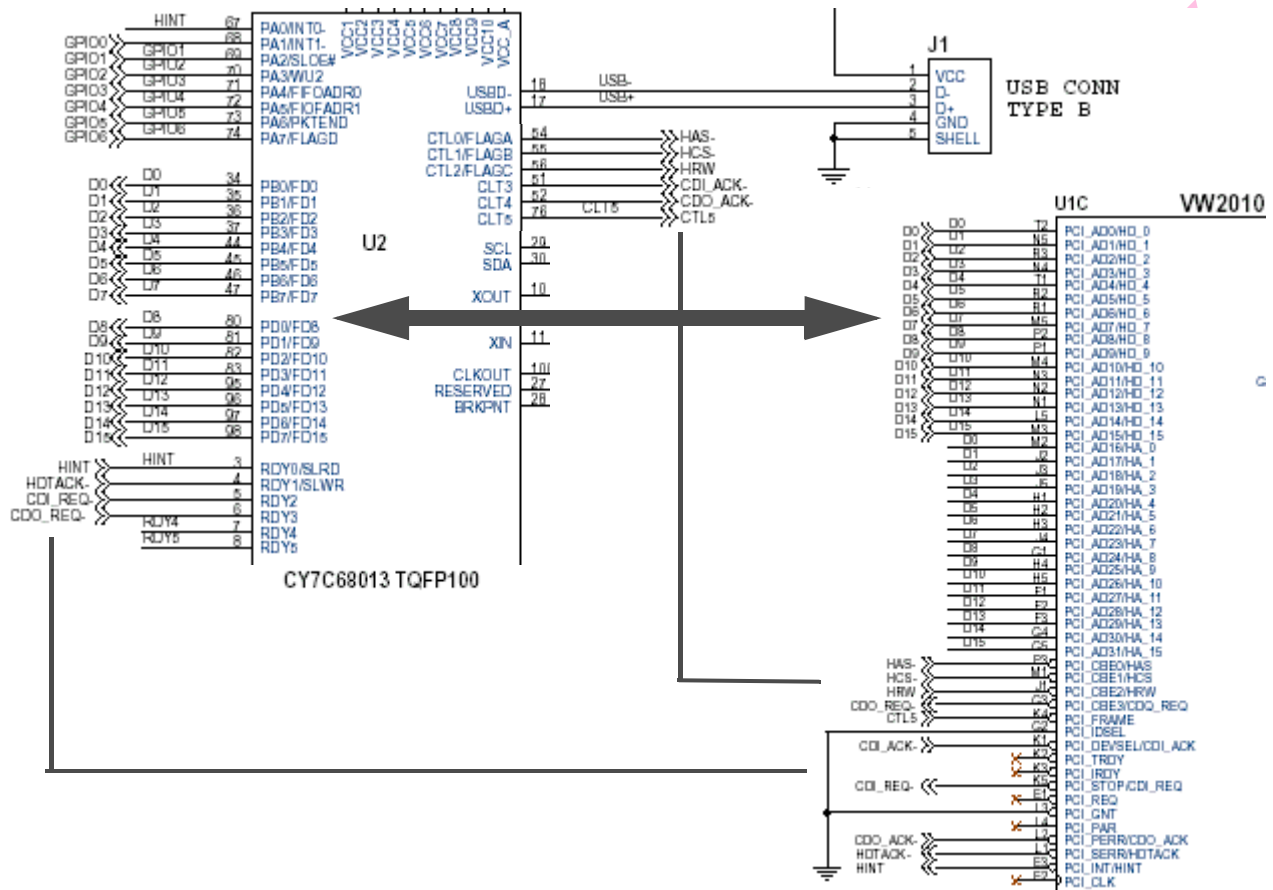


Figure 26 VW2010 Host Interface (USB)

### Embedded Host Mode

The VW2010 can be used in a completely embedded application that requires no external host. To put the VW2010 in this no-host mode, proceed as follows:

- Set the ROM-Data[1:0] pins to b'0x1x011 to select Intel mode (see Table 5 and Table 6 on page 50).
- Tie the unused input pins to ground (see Table 15 on page 142).
- Tie the intel\_ad[15:0] pins to ground (see Table 16 on page 144).
- Tie the following pins high to disable them:

- intel\_cs\_
- intel\_as\_
- intel\_rd\_
- intel\_wr\_ (see [Table 17 on page 145](#))

## EJTAG Mode

When the EJTAG port is enabled, as described under “[Power-Up Modes](#)” on [page 49](#),

- The VBI\_data bus is switched from input to output. (The drive attributes of the pins are tri-state, and the direction of the bus is switched.)
- The VBI\_data bus carries the signals of the ejtag\_pcst3 and ejtag\_pcst4 bus (instead of VBI input).
- If a hardware design calls for being able to switch the VBI\_data bus between VBI data in and EJTAG data out, then external tri-state buffers are required to gate off the VBI data input.
- However, if the hardware design calls for using only one mode of these two modes (and never switch to the other mode), then the pins can be left unconnected (see also “[Unused Pins](#)” on [page 92](#) and [Table 15 on page 142](#)).

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## CHAPTER 6

# Encoder Interface Signals

This chapter gives a brief description of the external input and output signals of the VW2010 encoder modules.

Note the following:

- Signal names that end in \_ (the underscore character) indicate pins that are active low.
- Signals may also be multiplexed; that is, two or more signals may be assigned to the same physical pin. The multiplexing scheme is shown in [Table 14 on page 141](#).
- The electrical properties of the I/O pads (pull-up, pull-down, tri-state, etc.) are shown in “[Pin Lists](#)” on page 87.

[Figure 27 on page 64](#) identifies the video and audio I/O and control signals of the encoder in the VW2010.

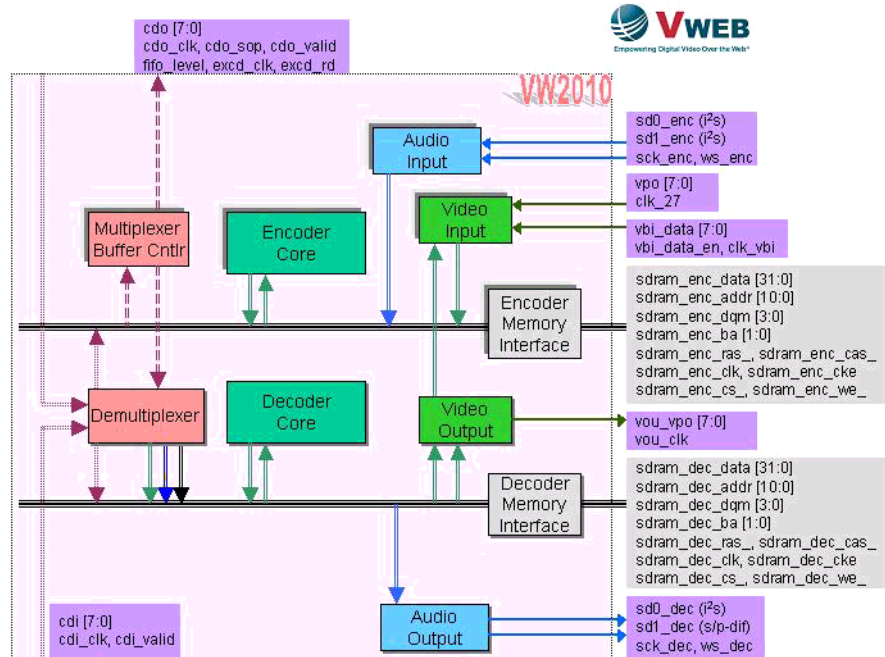


Figure 27 Audio and Video I/O Signals of the VW2010

## Video Input Interface

The VIU's external interface consists of the following signals.

Signal	Description	Direction
<i>vpo [7:0]</i>	<i>Video Input Data</i> These pins capture the interleaved luma and chroma sample (in 4:2:2 format).	<i>Input</i>
<i>clk_27</i>	<i>Video Input Clock</i> This is the 27 MHz clock from D1 (ITU-R.BT.656).	<i>Input</i>

## Audio Input Interface

The AIU's external interface consists of the following signals.

<i>sd0_enc</i>	<i>Encoder Audio Input Channel 1</i> Serial I <sup>2</sup> S data is transmitted in two's complement with MSB first.	<i>Input</i>
<i>sd1_enc</i>	<i>Encoder Audio Input Channel 2</i> Serial I <sup>2</sup> S data is transmitted in two's complement with MSB first.	<i>Input</i>
<i>sck_enc</i>	<i>Encoder Audio Clock</i>	<i>I/O</i>
<i>ws_enc</i>	<i>Encoder Audio Channel Select</i> The word select line indicates the channel being transmitted: 0 = Channel 1 (Left) 1 = Channel 2 (Right)	<i>I/O</i>

## VBI Input Interface

The VBI input interface consists of the following signals.

<i>vbi_data [7:0]</i>	<i>VBI Data In</i>	<i>Input</i>
<i>clk_vbi</i>	<i>External VBI Clock</i> 27 MHz Clock for VBI data.	<i>Input</i>
<i>vbi_data_en</i>	<i>VBI Data Enable</i> The external VBI data is valid.	<i>Input</i>

## Encoder Memory Interface

The EMIU's external interface consists of the following signals.

<i>sdram_enc_data [31:0]</i>	<i>SDRAM Data</i> Read and write data are transferred between the VW2010 and SDRAM on these pins.	<i>I/O</i>
<i>sdram_enc_addr [10:0]</i>	<i>SDRAM Address</i> This output connects directly to the corresponding SDRAM address inputs.	<i>Output</i>

<i>sdram_enc_dqm [3:0]</i>	<b>SDRAM Input/Output Mask</b> The DQM is an input mask signal for write accesses, and an output enable signal for read accesses. The input data is masked when DQM is sampled high during a write cycle. The output buffers are placed in a high-Z state (with a two-clock latency) when DQM is sampled high during a read cycle. DQM [0] corresponds to SDRAM_DATA[7:0]. DQM [1] corresponds to SDRAM_DATA[15:8]. DQM [2] corresponds to SDRAM_DATA[23:16]. DQM [3] corresponds to SDRAM_DATA[31:24].	<b>Output</b>
<i>sdram_enc_ba [1:0]</i>	<b>SDRAM Bank Select</b> This output determines which SDRAM bank is selected. See comment in “Application Notes” on page 67.	<b>Output</b>
<i>sdram_enc_ras_</i>	<b>SDRAM Row Address Strobe</b> The memory interface asserts this signal when the SDRAM row address is on the SDRAM_ADDR[10:0] bus.	<b>Output</b>
<i>sdram_enc_cas_</i>	<b>SDRAM Column Address Strobe</b> The memory interface asserts this signal when the SDRAM column address is on the SDRAM_ADDR[10:0] bus.	<b>Output</b>
<i>sdram_enc_clk</i>	<b>SDRAM Clock</b> This output connects directly to the SDRAM clock input.	<b>Output</b>
<i>sdram_enc_cke</i>	<b>SDRAM Clock Enable</b> This output connects directly to the SDRAM clock-enable input.	<b>Output</b>
<i>sdram_enc_we_</i>	<b>SDRAM Write Enable</b>	<b>Output</b>
<i>sdram_enc_cs_</i>	<b>SDRAM Chip Select</b> CS_ enables (low) or disables (high) the SDRAM commands.	<b>Output</b>

## Multiplexer Interface

The multiplexer’s external interface consists of the following signals.



<i>cdo [7:0]</i>	<b>Compressed Data Out</b> This is the bus for compressed data output from the VW2010.	<i>Output</i>
<i>cdo_clk</i>	<b>Compressed Data Out Clock</b> 27 MHz compressed data output clock; rising edge for strobing CDO signals. This clock can be programmed to 6.75, 13.5, or 27 MHz. The external device reading <i>cdo[7:0]</i> must be slaved to <i>cdo_clk</i> .	<i>Output</i>
<i>cdo_sop</i>	<b>Compressed Data Out Start Of Packet</b> Packet start code	<i>Output</i>
<i>cdo_valid</i>	<b>Compressed Data Out Valid</b> This is the CDO valid signal.	<i>Output</i>
<i>fifo_level</i>	<b>MUX FIFO Level</b> This pin reports the status of the multiplexer's FIFO.	<i>Output</i>
<i>excd_clk</i>	<b>MUX External Clock</b> This is an external clock. The multiplexer's compressed data can be output to an external device at this externally generated clock rate (instead of <i>cdo_clk</i> ). The maximum frequency of this clock cannot exceed 27 MHz.	<i>Input</i>
<i>excd_rd</i>	<b>MUX External Read Enable</b> This is the read enable for the multiplexer's compressed data output.	<i>Input</i>

## Application Notes

### Drive Attributes

See the chapter titled “[Pin Lists](#)” on [page 87](#) for the drive attributes of the signals, the use of multiplexed pins, and the board-level requirements for unused pins.

### AC Timing

See the chapter titled “[Electrical Characteristics](#)” on [page 147](#) for AC timing information.

### SDRAM Bank Select

Both bank-selects *sdram\_enc\_ba[1:0]* are needed for 8 MB (2Mx32), only one bank-select is needed for 4 MB (1Mx16).

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## CHAPTER 7

# Decoder Interface Signals

This chapter gives a brief description of the external input and output signals of the VW2010 encoder modules.

Note the following:

- Signal names that end in \_ (the underscore character) indicate pins that are active low.
- Signals may also be multiplexed; that is, two or more signals may be assigned to the same physical pin. The multiplexing scheme is shown in “Pin Lists” on page 87.
- The electrical properties of the I/O pads (pull-up, pull-down, tri-state, etc.) are shown in “Pin Lists” on page 87.

Figure 28 on page 70 identifies the video and audio I/O and control signals of the encoder and decoder in the VW2010. The bottom row of modules belong to the decoder.

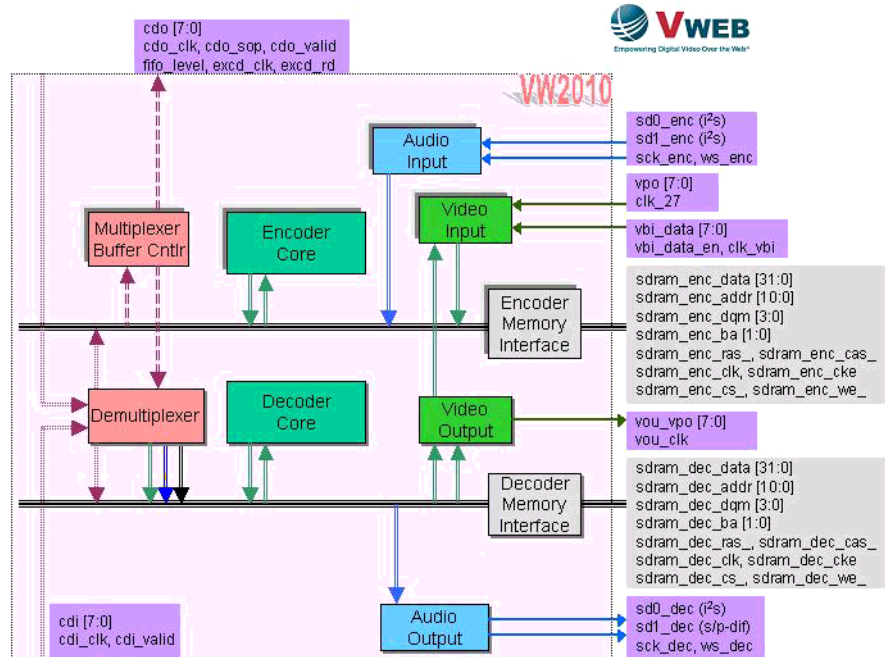


Figure 28 Audio and Video I/O Signals of the VW2010

## Demultiplexer Interface

The demultiplexer's external interface consists of the following signals.

*cdi [7:0]*

*Demux Data In*

*Input*

CDI[7:0] is input compressed data from a device such as an MPEG encoder. The data is latched on the rising edge of CDI\_CLK if CDI\_VALID is high. (There is no handshake or confirmation that data was transferred.) The port can be programmed to operate in serial (1-bit) or parallel (8-bit) mode. In parallel mode, all 8 bits of data are latched on the rising edge of CDI\_CLK.

In serial mode, only CDI[0] is used as input, and it is latched on the rising edge of CDI\_CLK; all others are ignored.

<i>cdi_valid</i>	<b>Demux Input Data Enable</b> CDI_VALID is an active-high input signal used to indicate that valid data is on the CDI[7:0] input data bus. Data is latched on the rising edge of CDI_CLK.	<i>Input</i>
<i>cdi_clk</i>	<b>Demux Input Data Clock</b> CDI_CLK is a clock input. The positive edge of this clock is used to latch the data CDI[7:0] into the VW2010.	<i>Input</i>

## Decoder Memory Interface

The DMIU's external interface consists of the following signals.

<i>sdram_dec_data [31:0]</i>	<b>SDRAM data bus</b> This 32-bit I/O data bus is connected directly to SDRAM.	<i>I/O</i>
<i>sdram_dec_addr [10:0]</i>	<b>SDRAM Address Bus</b> The row/column address bus for SDRAM memory.	<i>Output</i>
<i>sdram_dec_dqm [3:0]</i>	<b>SDRAM Input/Output Mask</b> The DQM is an input mask signal for write accesses, and an output enable signal for read accesses. The input data is masked when DQM is sampled high during a write cycle. The output buffers are placed in a high-Z state (with two-clock latency) when DQM is sampled high during a read cycle. DQM [0] corresponds to SDRAM_DATA[7:0]. DQM [1] corresponds to SDRAM_DATA[15:8]. DQM [2] corresponds to SDRAM_DATA[23:16]. DQM [3] corresponds to SDRAM_DATA[31:24].	<i>Output</i>
<i>sdram_dec_ba [1:0]</i>	<b>SDRAM Bank Select</b> BA selects the bank to which the Active, Read, Write or Pre-charge command is being applied. See comment in <a href="#">“Application Notes” on page 73</a> .	<i>Output</i>
<i>sdram_dec_ras_</i>	<b>SDRAM Row Address Strobe</b> The memory interface asserts this signal when the SDRAM row address is on the SDRAM_ADDR[10:0] bus.	<i>Output</i>

<i>sdram_dec_cas_</i>	<b>SDRAM Column Address Strobe</b> The memory interface asserts this signal when the SDRAM column address is on the SDRAM_ADDR[10:0] bus.	<b>Output</b>
<i>sdram_dec_clk</i>	<b>SDRAM Clock</b> This is the 162 MHz SDRAM clock. This signal should be connected as close as possible to the PLL_CLK pin of the VW2010.	<b>I/O</b>
<i>sdram_dec_cke</i>	<b>SDRAM Clock Enable</b> This output connects directly to the SDRAM's clock enable input.	<b>Output</b>
<i>sdram_dec_we_</i>	<b>SDRAM Write Enable</b> The memory interface asserts WE_ for SDRAM write cycles and holds it deasserted for SDRAM read cycles.	<b>Output</b>
<i>sdram_dec_cs_</i>	<b>SDRAM Chip Select</b> CS_ enables (low) and disables (high) the command decoder.	<b>Output</b>

## Video Output Interface

The VOU's external interface consists of the following signals.

<i>vou_vpo [7:0]</i>	<b>Video Data Out</b> This is the output data that represents the pixel data of the reconstructed picture. The pixel data is in CCIR-601 (ITU-R.BT.656) YCbCr format.	<b>Output</b>
<i>vou_clk</i>	<b>Video Out Clock</b> This is the video output sampling clock at a nominal frequency of 27 MHz. The output data is driven on the rising edge of this clock.	<b>Output</b>

## Audio Output Interface

The AOU's external interface consists of the following signals.

<i>sd0_dec</i>	<b>Audio Out Channel 1 - I2S</b> Serial audio data is transmitted in two's complement with the MSB first.	<b>Output</b>
----------------	--------------------------------------------------------------------------------------------------------------	---------------

<i>sd1_dec</i>	<i>Audio Out Channel 2- S/P-DIF</i> Serial audio data is transmitted in two's complement with the MSB first. The actual bitstream is either S/P-DIF uncompressed digital audio, or IEC-61937 compressed audio.	<i>Output</i>
<i>sck_dec</i>	<i>Audio Out Clock</i> Audio clock	<i>Output</i>
<i>ws_dec</i>	<i>Audio Out Channel Select</i> The word select line indicates the channel being transmitted : 0 = Channel 1 (Left) 1 = Channel 2 (Right)	<i>Output</i>

## Application Notes

### Drive Attributes

See the chapter titled “Pin Lists” on page 87 for the drive attributes of the signals, the use of multiplexed pins, and the board-level requirements for unused pins.

### AC Timing

See the chapter titled “Electrical Characteristics” on page 147 for AC timing information.

### SDRAM Bank Select

Both bank-selects *sdram\_dec\_ba[1:0]* are needed for 8 MB (2Mx32), only one bank-select is needed for 4 MB (1Mx16).

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## CHAPTER 8

# System Interface Signals

This chapter gives a brief description of the external input and output signals of the VW2010 system modules.

Note the following:

- Signal names that end in \_ (the underscore character) indicate pins that are active low.
- Signals may also be multiplexed; that is, two or more signals may be assigned to the same physical pin. The multiplexing scheme is shown in [Table 14 on page 141](#).
- The electrical properties of the I/O pads (pull-up, pull-down, tri-state, etc.) are shown in [“Pin Lists” on page 87](#).
- The HIU and the PCI access the outside world via shared pins (that is, the VW2010 can use either the HIU or the PCI, but not both at the same time).<sup>1</sup>
- Similarly, the ROM address bus shares pins with (is multiplexed with) the encoder's video output signals, with the decoder's video output signals, and with the decoder's audio output signals.<sup>2</sup>

[Figure 29 on page 76](#) identifies the system I/O and control signals of the VW2010.

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1. The host interface modes of the VW2010 are listed in [“Host Interface Modes” on page 3](#), and the host interface mode is selected as described in [“Host Mode” on page 49](#). The host interface signals of the VW2010 are described in the following sections, and the pin sharing and electrical characteristics are shown in [Table 16](#) and [Table 17 on page 145](#)

2. The signal multiplexing scheme of the VW2010 is described in [Table 14 on page 141](#).

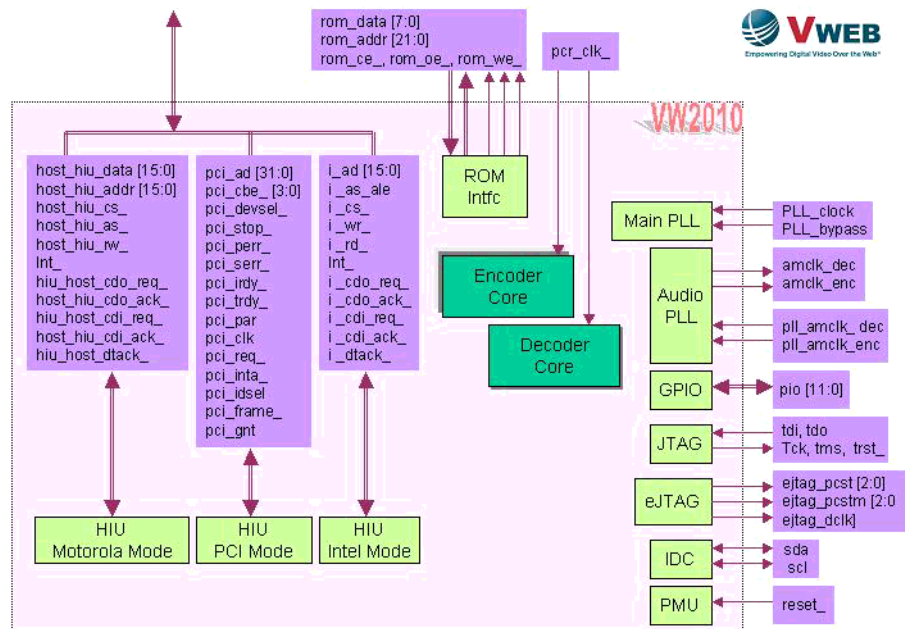


Figure 29 System I/O Signals of the VW2010

## Host Interface, Motorola Mode

The HIU's external interface in the Motorola (68K) mode consists of the following signals.

*Note:* The Motorola interface is always in 16-bit mode. Therefore, the UDS and LDS signals of a typical Motorola interface are not used.

*Note:* Motorola mode is big-endian. For example, 0x1234 is stored as 0x1234; the most significant bit comes first in memory.

<b>host_hiu_data [15:0]</b>	<b>Host Data</b>	<b>I/O</b>
	This is the data bus to/from the external host, to read or write data.	
<b>host_hiu_addr [15:0]</b>	<b>Host Address</b>	<b>Input</b>
	This is the address bus from the external host, used in an HIU command to access internal registers or memory locations.	

<i>host_hiu_as_</i>	<b>Host Address Select</b> This is the host address select pin, used to indicate the validity of the address bus.	<i>Input</i>
<i>host_hiu_cs_</i>	<b>Host Chip Select</b> This is the host chip select pin, used to indicate that the bus is being used by the VW2010.	<i>Input</i>
<i>host_hiu_rw_</i>	<b>Host Read/Write</b> This is the host read/write select pin (read high, write low).	<i>Input</i>
<i>int_</i>	<b>Host Interrupt</b> This pin indicates that an interrupt has occurred. The host can check the interrupt source by reading the INTS Source Register after an interrupt is detected.	<i>Output</i>
<i>hiu_host_cdo_req_</i>	<b>Compressed Data Out Request</b> Host DMA control. This is the request from the HIU to the external host, when the chip has compressed data ready to send to the host.	<i>Output</i>
<i>host_hiu_cdo_ack_</i>	<b>Compressed Data Out Acknowledge</b> Host DMA control. This is the acknowledge from the external host to the HIU when the host is ready to accept the compressed data. The data is put on the host bus one clock later.	<i>Input</i>
<i>hiu_host_cdi_req_</i>	<b>Compressed Data In Request</b> Host DMA control. This is the request from the HIU to the external host, when the chip is ready to accept compressed data from the host.	<i>Output</i>
<i>host_hiu_cdi_ack_</i>	<b>Compressed Data In Acknowledge</b> Host DMA control. This is the acknowledge from the external host to the HIU that the host is sending the compressed data. The data is put on the host bus one clock later.	<i>Input</i>
<i>hiu_host_dtack_</i>	<b>Host CDO Transfer Acknowledge</b> This is the host input data acknowledge, used to indicate the completion of the external host's read/write operation.	<i>Output</i>

For the pin-out and electrical characteristics of the pins, see [Table 16](#) and [Table 17](#) on [page 145](#), and the other tables in the chapter titled “Pin Lists” on [page 87](#).

For interface timing diagrams, see [Figure 34](#) and [Figure 35](#) on [page 150](#).

## Host Interface, Intel Mode

The HIU's external interface consists of the following signals.

*Note:* Intel mode is little-endian. For example, 0x1234 is stored as 0x3412; the least significant bit comes first in memory.

*Note:* The internal buses of the VW2010 are big-endian; therefore, to store data as 0x1234 in VW2010 registers or SDRAM, in Intel mode the input data must be organized as 0x3412.

<i>intel_ad</i> [15:0]	<b>Host Data/Address</b> This is the data/address bus to/from the external host, used in an HIU command to access internal registers or memory locations.	<b>I/O</b>
<i>intel_as_ale_</i>	<b>Host Address Select / Address Latch Enable</b> This is the host address select pin, used to indicate the validity of the data/address bus.	<b>Input</b>
<i>intel_cs_</i>	<b>Host Chip Select</b> This is the host chip select pin, used to indicate that the data/addressbus is being used by the VW2010.	<b>Input</b>
<i>intel_wr_</i>	<b>Host Write</b> This is the host write select pin.	<b>Input</b>
<i>intel_rd_</i>	<b>Host Read</b> This is the host read select pin.	<b>Input</b>
<i>int_</i>	<b>Host Interrupt</b> This pin indicates that an interrupt has occurred. The host can check the interrupt source by reading the INTS Source Register after an interrupt is detected.	<b>Output</b>
<i>intel_cdo_req_</i>	<b>Compressed Data Out Request</b> Host DMA control. This is the request from the HIU to the external host, when the chip has compressed data ready to send to the host.	<b>Output</b>
<i>intel_cdo_ack_</i>	<b>Compressed Data Out Acknowledge</b> Host DMA control. This is the acknowledge from the external host to the HIU when the host is ready to accept the compressed data. The data is put on the host bus one clock later.	<b>Input</b>

<i>intel_cdi_req_</i>	<b>Compressed Data In Request</b>	<b>Output</b>
	Host DMA control. This is the request from the HIU to the external host, when the chip is ready to accept compressed data from the host.	
<i>intel_cdi_ack_</i>	<b>Compressed Data In Acknowledge</b>	<b>Input</b>
	Host DMA control. This is the acknowledge from the external host to the HIU that the host is sending the compressed data. The data is put on the host bus one clock later.	
<i>intel_dtack_</i>	<b>Host CDO Transfer Acknowledge</b>	<b>Output</b>
	This is the host input data acknowledge, used to indicate the completion of the external host's read/write operation.	

For the pin-out and electrical characteristics of the pins, see [Table 16](#) and [Table 17](#) on [page 145](#), and the other tables in the chapter titled “Pin Lists” on [page 87](#).

For interface timing diagrams, see [Figure 36](#) and [Figure 37](#) on [page 152](#).

## Host Interface, PCI Mode

The PCI port's external interface consists of the following signals.

<i>pci_ad [31:0]</i>	<b>Address/Data Bus</b>	<b>I/O</b>
	This 32-bit bus multiplexes the PCI address and data bus. A bus transaction on this bus starts with an address phase (PCI_FRAME_ is asserted), followed by at least one data phase (PCI_FRAME_ is deasserted during the last data phase). During data phase, PCI_AD[7:0] contain the least-significant byte and PCI_AD[31:24] contain the most-significant byte. Write data is valid when PCI_IRDY_ is asserted; read data is valid when PCI_TRDY_ is asserted.	
<i>pci_clk</i>	<b>Bus Clock</b>	<b>Input</b>
	This is the PCI bus clock. All PCI transactions are clocked with respect to PCI_CLK. It supports clock speeds up to 66 MHz. PCI_CLK is asynchronous to all other clocks. This input should be tied low when VW2010 is not connected to the PCI bus.	
<i>pci_cbe_[3:0]</i>	<b>Bus Command / Byte Enables</b>	<b>I/O</b>
	This four-bit bus multiplexes the bus command byte-enables. During the address phase of a bus transaction (when	

PCI\_FRAME\_ is asserted), these pins contain the bus command. During the data phase, these pins are byte-enables.

<i>pci_devsel_</i>	<b>Device Select</b> A low driven onto this input indicates whether any device on the bus has been selected. When actively driven, it indicates that the driving device has decoded its address as the target of the current access.	<i>I/O</i>
<i>pci_frame_</i>	<b>Frame Transaction</b> PCI_FRAME_ indicates the beginning and duration of a bus transaction. A high-to-low transition on PCI_FRAME_ indicates that a bus transaction is starting. A low-to-high transition on PCI_FRAME_ indicates that the transaction is in its final data phase, or is completed.	<i>I/O</i>
<i>pci_gnt_</i>	<b>Bus Grant</b> Assertion of this input indicates that the agent has been granted use of the PCI bus. The agent ignores this input when PCI_RST_ is asserted.	<i>Input</i>
<i>pci_idsel</i>	<b>Initialization Device Select</b> This input is the active-high chip select during configuration reads and writes.	<i>Input</i>
<i>pci_inta_</i>	<b>Interrupt A</b> The processor asserts this output low to request attention from its device driver. The processor asserts PCI_INT_ asynchronously to PCI_CLK.	<i>I/O</i>
<i>pci_irdy_</i>	<b>Initiator Ready</b> This signal is used in conjunction with PCI_TRDY_. During a write transaction, a low on PCI_IRDY_ indicates that valid data is present on PCI_AD[31:0]. During a read transaction, a low on PCI_IRDY_ indicates the current master is ready to accept data. The data phase is completed when PCI_TRDY_ and PCI_IRDY_ are both sampled asserted.	<i>I/O</i>
<i>pci_par</i>	<b>Parity</b> PCI_PAR provides even parity across PCI_AD[31:0] and PCI_CBE[3:0].	<i>I/O</i>
<i>pci_perr_</i>	<b>Parity Error</b> Assertion of this signal indicates that a data parity error occurred during a PCI transaction.	<i>I/O</i>

Bit 6 in the PCI Command Register must be set to 1 for this signal to be asserted.

<i>Pci_req_</i>	<b>Bus Request</b> The processor asserts this output to the bus arbiter when it wants control of the PCI bus.	<i>Output</i>
<i>pci_serr_</i>	<b>System Error</b> Assertion of this signal indicates that an address parity error occurred during a PCI transaction. Bit 8 in the PCI Command Register must be set to 1 for this signal to be asserted.	<i>Output</i>
<i>pci_stop_</i>	<b>Stop Transaction</b> A low on PCI_STOP_ indicates that the current target is requesting that the master halt the current transaction.	<i>I/O</i>
<i>pci_trdy_</i>	<b>Target Ready</b> This signal is used in conjunction with PCI_IRDY_. During a read transaction, a low on PCI_TRDY_ indicates that valid data is present on PCI_AD[31:0]. During a write transaction, a low on PCI_TRDY_ indicates the target is ready to accept data. The data phase is completed when PCI_TRDY_ and PCI_IRDY_ are both sampled asserted.	<i>I/O</i>

For the pin-out and electrical characteristics of the pins, see [Table 16](#) and [Table 17](#) on [page 145](#), and the other tables in the chapter titled “[Pin Lists](#)” on [page 87](#).

For interface timing diagrams, see [Figure 38](#) and [Figure 39](#) on [page 154](#). For additional details, see the PCI 2.2 specification.

In PCI host mode, firmware can configure GPIO pins to control a second PCI port. See “[GPIO Signals](#)” on [page 82](#).

## ROM Interface

The ROM port’s external interface consists of the following signals.

<i>rom_data [7:0]</i>	<b>ROM Data</b> These bits have special functions at boot/reset time; for details, see “ <a href="#">ROM Interface (RIU)</a> ” on <a href="#">page 48</a> .	<i>I/O</i>
<i>rom_addr [21:0]</i>	<b>ROM Address</b>	<i>Output</i>

<i>rom_ce_</i>	<i>ROM Chip Enable</i>	<i>Output</i>
<i>rom_oe_</i>	<i>ROM Output Enable</i>	<i>Output</i>
<i>rom_we_</i>	<i>ROM Write Enable</i>	<i>Output</i>

## Global Signals

The following input signals affect all modules in the VW2010.

<i>pcr_clk</i>	<i>PCR CLOCK</i> 27 MHz reference clock source for program clock recovery.	<i>Input</i>
<i>reset_</i>	<i>Global Reset</i> This is the chip's global reset pin.	<i>Input</i>

## GPIO Signals

The GPIO interface consists of the following signals.

<i>gpio [11:0]</i>	<i>General Purpose I/O</i> These pins can be individually programmed as inputs or outputs through the GPIO registers.	<i>I/O</i>
<i>gpio [11:8]</i>	<i>PCI port 2</i> <b>In PCI Host Mode only</b> , these three pins can be assigned by firmware to control a second PCI port, as follows: GPIO[11] - Host PCI Request 2 GPIO[10] - Host PCI Grant 2 GPIO[9] - n/a GPIO[8] - Host PCI Interrupt 2 These are functionally identical to the request, grant and interrupt signals, respectively, described in <a href="#">“Host Interface, PCI Mode”</a> on page 79.	<i>I/O</i>



<i>gpio [11:10]</i>	<b>ICI port 2</b>	<i>I/O</i>
	These two pins can be assigned by firmware to control a second ICI port, as follows GPIO[11] - SCL 2 GPIO[10] - SDA 2 These are functionally identical to the I <sup>2</sup> C clock and I <sup>2</sup> C data signal, respectively, described in the next section (“ICI Signals”).	

## ICI Signals

The ICI interface consists of the following signals.

<i>sda</i>	<b>ICI Data</b>	<i>I/O</i>
	The VW2010 inter-device communication interface (ICI) is a slave at reset, so the device can read boot code from the ROM. In normal mode, the device is ICI master.	
<i>scl</i>	<b>ICI Clock</b>	<i>I/O</i>

## Main PLL Signals

The main PLL's external interface consists of the following signals.

<i>PLL_clock</i>	<b>PLL Reference Clock</b>	<i>Input</i>
	This is the 27 MHz input from an external crystal oscillator, from which the PLL generates the 162 MHz system clock and other subsystem clocks in the chip.	
<i>PLL_bypass</i>	<b>PLL Disable</b>	<i>Input</i>
	Test pin only. This pin should be tied to ground during normal operation. This signal disables the PLL. Then an external 162 MHz system clock can be applied as input to the chip directly on the PLL-clock pin.	

## Audio PLL Signals

The audio PLL's external interface consists of the following signals.

<i>amclk_enc</i>	<b>Audio In Master Clock</b> This is the audio master clock from the encoder, to drive the external audio ADC. For the frequencies generated by the PLL, see <a href="#">Table 7 on page 52</a> .	<b>Output</b>
<i>amclk_dec</i>	<b>Audio Out Master Clock</b> This is the audio master clock from the decoder, to drive the external audio DAC. For the frequencies generated by the PLL, see <a href="#">Table 7 on page 52</a> .	<b>Output</b>
<i>PLL_amclk_enc</i>	<b>External Audio In Master Clock</b> This is the PLL bypass clock for the encoder, if the audio PLL is not used.	<b>Input</b>
<i>PLL_amclk_dec</i>	<b>External Audio Out Master Clock</b> This is the PLL bypass clock for the decoder, if the audio PLL is not used.	<b>Input</b>

## JTAG Signals

The JTAG interface consists of the following signals.

<i>tdi</i>	<b>Test Data In</b> Test data and test instructions are shifted serially into this input during a TAP operation.	<b>Input</b>
<i>tdo</i>	<b>Test Data Out</b> Test data and test instructions are shifted serially out of this output during a TAP operation.	<b>Output</b>
<i>tclk</i>	<b>Test Clock</b> This input clocks the state information, boundary scan instructions, and test data into and out of the processor during a TAP operation. If the JTAG port is not used, this input should be tied low.	<b>Input</b>
<i>tms</i>	<b>Test Mode Select</b> This input controls the state of the processor's TAP controller.	<b>Input</b>

<i>trst_</i>	<b>Test Reset</b> Asynchronous assertion of this input causes the processor to initialize the TAP controller. If the JTAG port is not used, this input should be tied low.	<i>Input</i>
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## Extended JTAG Signals

The extended JTAG interface consists of the following signals.

*Note:* EJTAG is for internal Vweb use only.

<i>ejtag_pcst [2:0]</i>	<i>Program Counter Status Trace</i>	<i>Output</i>
<i>ejtag_pcst2 [2:0]</i>	<i>Program Counter Status Trace</i>	<i>Output</i>
<i>ejtag_pcst3 [2:0]</i>	<i>Program Counter Status Trace</i>	<i>Output</i>
<i>ejtag_pcs4 [2:0]</i>	<i>Program Counter Status Trace</i>	<i>Output</i>
<i>ejtag_dclk</i>	<i>Debug Clock</i>	<i>Output</i>

## Application Notes

### Drive Attributes

See the chapter titled “[Pin Lists](#)” on page 87 for the drive attributes of the signals, the use of multiplexed pins, and the board-level requirements for unused pins.

### AC Timing

See the chapter titled “[Electrical Characteristics](#)” on page 147 for AC timing information.

### Signal Multiplexing

Note the following:

- All host interface modes share the same set of I/O pins.
- The ROM data pins assume special functions at reset time.
- The ROM address pins are used as the I/O of other modules after reset.
- The GPIO pins can be programmed for specific purposes of the user’s choosing.

- Some EJTAG pins are normally used for VBI data input.

For further information, see “Signal Multiplexing” on page 91 in general; for details, see Table 14, “Signal Multiplexing Scheme,” on page 141 or Table 14 on page 141.

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## CHAPTER 9

*Pin Lists*

## Summary of the Contents

This chapter presents the following information:

- Package dimensions
- Pin-out diagram
- Pin lists
- Signal multiplexing scheme
- Application notes

**Package Dimensions**

The VW2010 comes in a 365-pin BGA package, with dimensions shown in the following table:

**Table 8 365L BGA Package Dimensions**

Dimension	Measurement
Package	27 x 27 x 2.33 mm
Ball pitch	1.27 mm
Ball diameter	0.75 mm
Substrate thickness	0.56 mm
Mold thickness	1.17 mm
Other dimensions	See <a href="#">Figure 30 on page 88</a> , <a href="#">Figure 31 on page 88</a> , <a href="#">Figure 32 on page 89</a>

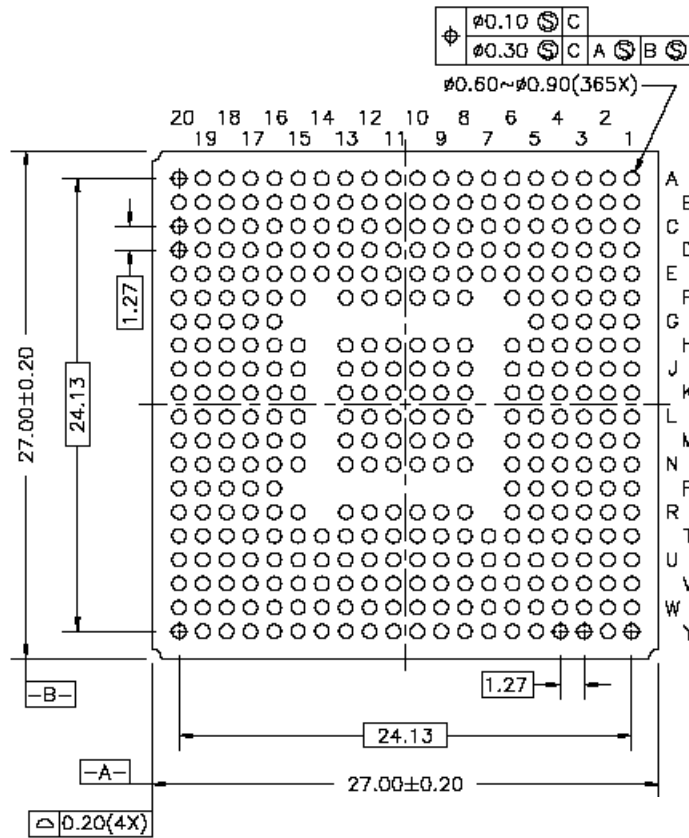


Figure 30 Package and Ball Array Dimensions (bottom --> up view)

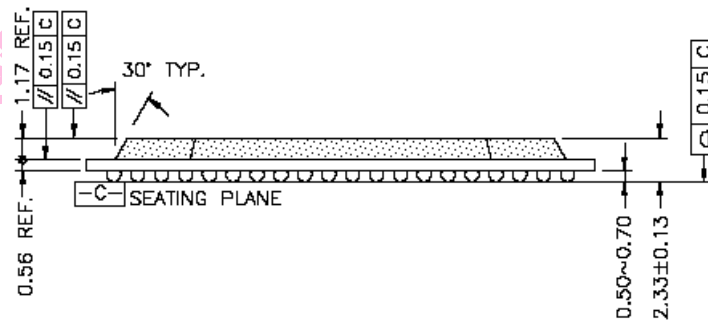


Figure 31 Package Thickness Dimensions

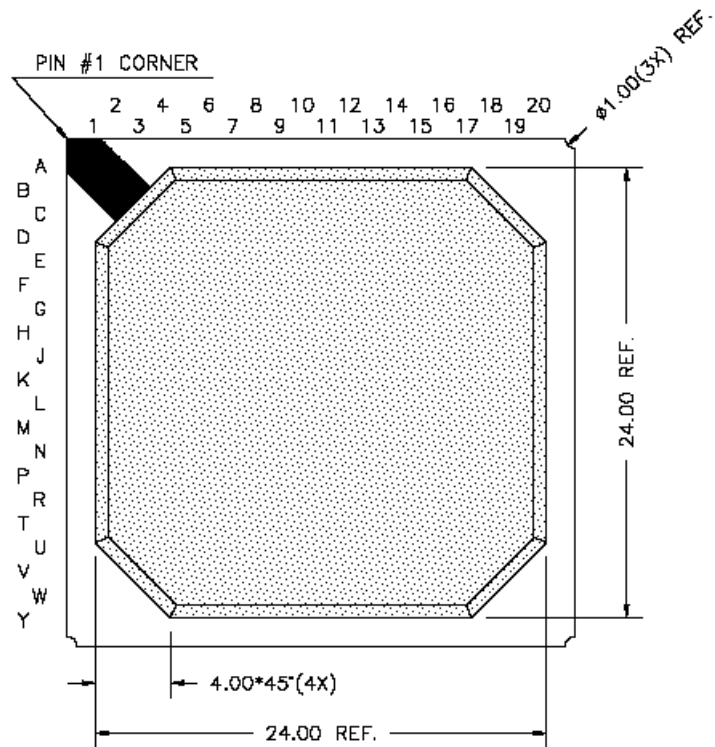


Figure 32 Package Dimensions (top --> down view)

## Pin-out Diagram

The pin-out diagram of the VW2010 is shown in [Figure 33 on page 90](#). In the pin-out diagram, note the following:

- Balls numbered from 1 to 300 are the chip's I/O connections.
- Some of these numbered balls are also used for 1.8V core VDD, 1.8V PLL VDD, PLL VSS, 3.3V I/O VDD and I/O VSS.
- P1 are the 1VDD power ring (12 balls), used for 1.8V core VDD.
- P2 are the 0VDDA power ring (3 balls), used for 3.3V I/O VDD.
- P3 are the 0VDDM power ring (6 balls) used for 3.3V I/O VDD.
- P4 are the 0VDD3 power ring (4 balls) used for 3.3V I/O VDD.
- P5 are the PVDD power ring (4 balls), used for 3.3V I/O VDD.
- G/T are the ground/thermal connections (36 balls), used for core and I/O VSS.

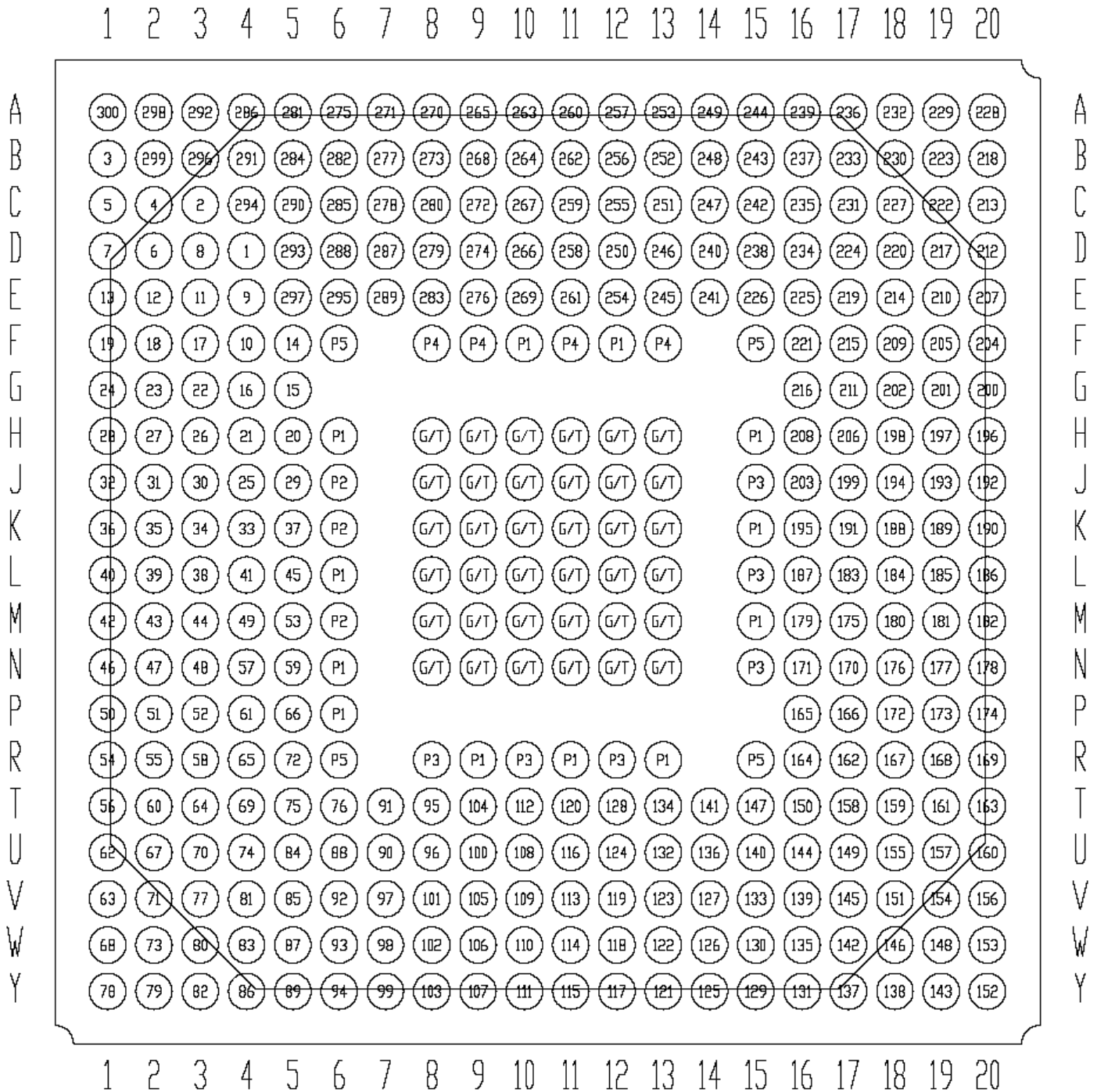


Figure 33 BGA Ball Map of the VW2010 (top --> down view)



## Pin Lists

The pin-out of the VW2010 is shown in pin lists sorted by various criteria:

- [Table 9, “I/O Signals, Sorted by Pad Number,” on page 93](#)
- [Table 10, “I/O Signals, Sorted by BGA Coordinates,” on page 104](#)
- [Table 11, “I/O Signals, Sorted by Module,” on page 115](#)
- [Table 12, “I/O Signals, Sorted by Signal Name,” on page 126](#)
- [Table 13, “Power and Ground Connections,” on page 137](#)

## Signal Multiplexing

[Table 14, “Signal Multiplexing Scheme,” on page 141](#) summarizes the VW2010 chip’s use of the same pins for multiple purposes.

The signal multiplexing scheme can also be inferred from [Table 9, “I/O Signals, Sorted by Pad Number,” on page 93](#), and [Table 10, “I/O Signals, Sorted by BGA Coordinates,” on page 104](#), where you may see two or three signals assigned to the same pad number or BGA coordinate, respectively.

The presentation of this information should not be automatically interpreted to mean that any one set of signals is necessarily “primary” or “secondary.” Signal multiplexing simply means the use of the same set of pins for alternate purposes of the user’s choosing.

The following are general cases of signal multiplexing in the VW2010 chip:

- The ROM data and address buses are used by the ROM at boot time, when microcode is being downloaded from the ROM into the VW2010 chip; at all other times the same pins are used for the chip’s other, “normal” purposes.
- Again at boot time, the ROM data bus pins are used to set the host mode and other power-up modes of the VW2010 chip, as described in [“ROM Interface \(RIU\)” on page 48](#).
- After power-up, the ROM address bus is not used by the ROM, and is available to support other functions. The upper bits of the ROM address bus are used for the compressed data out (CDO) data bus and its control signals. The low byte of the ROM address bus is used as the video output bus from the decoder. The two high bits of the ROM address bus are the audio outputs from the decoder.
- The host/PCI interface pins are shared by the VW2010 chip’s HIU and PCI modules, and, as far as external devices are concerned, the VW2010 may look like a PCI, Motorola or Intel device, depending on how the chip’s host mode is set at boot time. See [Table 16 on page 144](#), [Table 17 on page 145](#). This flexibility imposes a chip design requirement on the drive attributes of the chip’s host interface pins, which is discussed in [“Drive Attributes in Host Mode” on page 92](#).

## Application Notes

### Drive Strengths

In the pin list Tables, a drive strength of “PCI” means that the VW2010 is PCI 66 core-compliant, and can work with standard loads of 2, 4, 8 or 16 ma. The actual drive strength is user-selectable.

### Drive Attributes

The drive attribute shown in the pin list tables is a property of the pad; it is not a recommendation or requirement imposed on the design of a circuit using the VW2010.

For example, “pull-up” means that the pad has a built-in, internal pull-up resistor, and therefore normally the board designer using this chip does not have to put an external pull-up resistor on the pin. “Tri-state” means that the pad has built-in, internal logic to make the pin go tri-state when appropriate.

### Drive Attributes in Host Mode

The VW2010 chip’s host interface pins can be set to operate in one of the host modes listed in “Host Interface Modes” on page 3, and shown in detail in Table 16 on page 144 and Table 17 on page 145. The chip’s corresponding I/O pads are designed so that the pins will always behave as required by the standard for the interface mode that was selected. For example, in PCI mode the same pin will behave as a standard PCI pin and go to tri-state as required by the PCI 2.2 specification. In another host mode, the same pin will be an input or an output, whichever is the correct behavior in the other host mode, and therefore the part of the pad’s circuit that allowed the pad to go tri-state in PCI mode will be bypassed in the other host mode. See Table 16 on page 144, Table 17 on page 145.

### Clock Pins

It is good board-design practice to route an active clock output signal through a series resistor connected to the pin.

### Unused Pins

Unused output pins can be left unconnected / floating. In general, unused bi-directional pins can also be left unconnected / floating. Unused inputs should always be tied to their inactive state; that is, if the signal is active low, tie it high; if it is active high, tie it low. Exceptions are noted in Table 15 on page 142.

Note the following:

- Bi-directional pins of the host/PCI bus, if not used in a particular host mode, are automatically defaulted to tri-state in PCI mode, and to input-only or output-only in the other host modes. See “Drive Attributes in Host Mode” above; see also Table 16 on page 144, and Table 17 on page 145.
- See also “Embedded Host Mode” on page 61.
- It is good board-design practice to tie unused clock pins to ground.

### Termination Rules

JTAG and EJTAG signals have their own external pull-up/pull-down/termination requirements, depending on the specific emulator used to test the board.

The ICI pins have their own termination rules, as described in the Philips I<sup>2</sup>C bus specification.

Table 9 I/O Signals, Sorted by Pad Number

Pad No.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Ball Coord.
1	cdi[7]	Demux	Compressed data in [7:0]	Input		Pull-up	D4
2	cdi[6]	Demux	Compressed data in [7:0]	Input		Pull-up	C3
3	cdi[5]	Demux	Compressed data in [7:0]	Input		Pull-up	B1
4	cdi[4]	Demux	Compressed data in [7:0]	Input		Pull-up	C2
5	cdi[3]	Demux	Compressed data in [7:0]	Input		Pull-up	C1
6	cdi[2]	Demux	Compressed data in [7:0]	Input		Pull-up	D2
7	cdi[1]	Demux	Compressed data in [7:0]	Input		Pull-up	D1
8	cdi[0]	Demux	Compressed data in [7:0]	Input		Pull-up	D3
9	cdi_valid	Demux	Compressed data in enable	Input		Pull-up	E4
10	cdi_clk	Demux	Compressed data in clock	Input		Pull-up	F4
11	int_	HIU / Moto	Host interrupt	Output	PCI	Open-drain	E3
11	int_	HIU / Intel	Host interrupt	Output	PCI	Open-drain	E3
11	pci_inta_	HIU / PCI	PCI interrupt A	Output	PCI	Open-drain	E3
12	pci_clk	HIU / PCI	PCI clock	Input	PCI		E2
13	pci_req_	HIU / PCI	PCI bus request	Bi-Dir	PCI	Tri-state	E1
15	host_hiu_addr[15]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	G5
15	pci_ad[31]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	G5
16	host_hiu_addr[14]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	G4
16	pci_ad[30]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	G4
17	host_hiu_addr[13]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	F3
17	pci_ad[29]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	F3
18	host_hiu_addr[12]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	F2
18	pci_ad[28]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	F2
19	host_hiu_addr[11]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	F1
19	pci_ad[27]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	F1
20	host_hiu_addr[10]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	H5
20	pci_ad[26]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	H5
21	host_hiu_addr[9]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	H4
21	pci_ad[25]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	H4
22	hiu_host_cdo_req_	HIU / Moto	Compressed data out request	Bi-Dir	PCI	Tri-state	G3
22	intel_cdo_req_	HIU / Intel	Compressed data out request	Bi-Dir	PCI	Tri-state	G3
22	pci_cbe_[3]	HIU / PCI	PCI bus command / byte enables	Bi-Dir	PCI	Tri-state	G3
23	pci_idsel	HIU / PCI	PCI init. device select	Input	PCI		G2
24	host_hiu_addr[8]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	G1
24	pci_ad[24]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	G1

Table 9 I/O Signals, Sorted by Pad Number (Continued)

Pad No.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Ball Coord.
25	host_hiu_addr[ 7]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	J4
25	pci_ad[23]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	J4
26	host_hiu_addr[ 6]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	H3
26	pci_ad[22]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	H3
27	host_hiu_addr[ 5]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	H2
27	pci_ad[21]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	H2
28	host_hiu_addr[ 4]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	H1
28	pci_ad[20]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	H1
29	host_hiu_addr[ 3]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	J5
29	pci_ad[19]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	J5
30	host_hiu_addr[ 2]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	J3
30	pci_ad[18]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	J3
31	host_hiu_addr[ 1]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	J2
31	pci_ad[17]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	J2
32	host_hiu_rw_	HIU / Moto	Host read/write	Bi-Dir	PCI	Tri-state	J1
32	intel_wr_	HIU / Intel	Host write	Bi-Dir	PCI	Tri-state	J1
32	pci_cbe_[2]	HIU / PCI	PCI bus command / byte enables	Bi-Dir	PCI	Tri-state	J1
33	intel_rd_	HIU / Intel	Host read	Bi-Dir	PCI	Tri-state	K4
33	pci_frame_	HIU / PCI	PCI cycle frame / transaction	Bi-Dir	PCI	Tri-state	K4
34	pci_irdy_	HIU / PCI	PCI initiator ready	Bi-Dir	PCI	Tri-state	K3
35	pci_trdy_	HIU / PCI	PCI target ready	Bi-Dir	PCI	Tri-state	K2
36	host_hiu_cdi_ack_	HIU / Moto	Host CDI acknowledge	Bi-Dir	PCI	Tri-state	K1
36	intel_cdi_ack_	HIU / Intel	Host CDI acknowledge	Bi-Dir	PCI	Tri-state	K1
36	pci_devsel_	HIU / PCI	PCI device select	Bi-Dir	PCI	Tri-state	K1
37	hiu_host_cdi_req_	HIU / Moto	Host CDI request	Bi-Dir	PCI	Tri-state	K5
37	intel_cdi_req_	HIU / Intel	Host CDI request	Bi-Dir	PCI	Tri-state	K5
37	pci_stop_	HIU / PCI	PCI stop transaction	Bi-Dir	PCI	Tri-state	K5
38	pci_gnt_	HIU / PCI	PCI grant	Input	PCI	Tri-state	L3
39	host_hiu_cdo_ack_	HIU / Moto	Host CDO acknowledge	Bi-Dir	PCI	Tri-state	L2
39	intel_cdo_ack_	HIU / Intel	Host CDO acknowledge	Bi-Dir	PCI	Tri-state	L2
39	pci_perr_	HIU / PCI	PCI parity error	Bi-Dir	PCI	Tri-state	L2
40	hiu_host_dtrack_	HIU / Moto	Host CDO transfer acknowledge	Bi-Dir	PCI	Open-drain	L1
40	intel_dtrack_	HIU / Intel	Host CDO transfer acknowledge	Bi-Dir	PCI	Open-drain	L1
40	pci_serr_	HIU / PCI	PCI system error	Bi-Dir	PCI	Open-drain	L1
41	pci_par	HIU / PCI	PCI parity	Bi-Dir	PCI	Tri-state	L4
42	host_hiu_cs_	HIU / Moto	Host chip select	Bi-Dir	PCI	Tri-state	M1

Table 9 I/O Signals, Sorted by Pad Number (Continued)

Pad No.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Ball Coord.
42	intel_cs_	HIU / Intel	Host chip select	Bi-Dir	PCI	Tri-state	M1
42	pci_cbe_[1]	HIU / PCI	PCI bus command / byte enables	Bi-Dir	PCI	Tri-state	M1
43	host_hiu_addr[ 0]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	M2
43	pci_ad[16]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	M2
44	host_hiu_data[15]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	M3
44	intel_ad[15]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	M3
44	pci_ad[15]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	M3
45	host_hiu_data[14]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	L5
45	intel_ad[14]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	L5
45	pci_ad[14]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	L5
46	host_hiu_data[13]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	N1
46	intel_ad[13]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	N1
46	pci_ad[13]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	N1
47	host_hiu_data[12]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	N2
47	intel_ad[12]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	N2
47	pci_ad[12]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	N2
48	host_hiu_data[11]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	N3
48	intel_ad[11]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	N3
48	pci_ad[11]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	N3
49	host_hiu_data[10]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	M4
49	intel_ad[10]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	M4
49	pci_ad[10]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	M4
50	host_hiu_data[ 9]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	P1
50	intel_ad[ 9]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	P1
50	pci_ad[ 9]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	P1
51	host_hiu_data[ 8]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	P2
51	intel_ad[ 8]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	P2
51	pci_ad[ 8]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	P2
52	host_hiu_as_	HIU / Moto	Host address select	Bi-Dir	PCI	Tri-state	P3
52	intel_as_ale_	HIU / Intel	Host address select / address latch enable	Bi-Dir	PCI	Tri-state	P3
52	pci_cbe_[0]	HIU / PCI	PCI bus command / byte enables	Bi-Dir	PCI	Tri-state	P3
53	host_hiu_data[ 7]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	M5
53	intel_ad[ 7]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	M5
53	pci_ad[ 7]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	M5
54	host_hiu_data[ 6]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	R1
54	intel_ad[ 6]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	R1

Table 9 I/O Signals, Sorted by Pad Number (Continued)

Pad No.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Ball Coord.
54	pci_ad[ 6]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	R1
55	host_hiu_data[ 5]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	R2
55	intel_ad[ 5]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	R2
55	pci_ad[ 5]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	R2
56	host_hiu_data[ 4]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	T1
56	intel_ad[ 4]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	T1
56	pci_ad[ 4]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	T1
57	host_hiu_data[ 3]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	N4
57	intel_ad[ 3]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	N4
57	pci_ad[ 3]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	N4
58	host_hiu_data[ 2]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	R3
58	intel_ad[ 2]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	R3
58	pci_ad[ 2]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	R3
59	host_hiu_data[ 1]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	N5
59	intel_ad[ 1]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	N5
59	pci_ad[ 1]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	N5
60	host_hiu_data[ 0]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	T2
60	intel_ad[ 0]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	T2
60	pci_ad[ 0]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	T2
61	trst_	JTAG	Test reset	Input		Pull-down	P4
62	tms	JTAG	Test mode select	Input		Pull-up	U1
63	tck	JTAG	Test clock	Input		Pull-up	V1
64	tdi	JTAG	Test data in	Input		Pull-up	T3
65	tdo	JTAG	Test data out	Output	4	Pull-up/ tri-state	R4
66	ejtag_dclk	EJTAG	Debug clock	Output	8		P5
67	ejtag_pcst2[0]	EJTAG	Program counter status trace2[2:0]	Output	8		U2
68	PLL_clock	mPLL	Main PLL clock	Input			W1
69	PLL_bypass	mPLL	Main PLL disable / bypass	Input			T4
76	ejtag_pcst2[1]	EJTAG	Program counter status trace2[2:0]	Output	8		T6
77	ejtag_pcst2[2]	EJTAG	Program counter status trace2[2:0]	Output	8		V3
78	ejtag_pcst[0]	EJTAG	Program counter status trace[2:0]	Output	8		Y1
79	ejtag_pcst[1]	EJTAG	Program counter status trace[2:0]	Output	8		Y2
80	ejtag_pcst[2]	EJTAG	Program counter status trace[2:0]	Output	8		W3
81	sdram_dec_data[31]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	V4
82	sdram_dec_data[30]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	Y3
83	sdram_dec_data[29]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	W4

Table 9 I/O Signals, Sorted by Pad Number (Continued)

Pad No.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Ball Coord.
84	sdram_dec_data[28]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	U5
85	sdram_dec_data[27]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	V5
86	sdram_dec_data[26]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	Y4
87	sdram_dec_data[25]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	W5
88	sdram_dec_data[24]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	U6
89	sdram_dec_data[23]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	Y5
90	sdram_dec_data[22]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	U7
91	sdram_dec_data[21]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	T7
92	sdram_dec_data[20]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	V6
93	sdram_dec_data[19]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	W6
94	sdram_dec_data[18]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	Y6
95	sdram_dec_data[17]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	T8
96	sdram_dec_data[16]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	U8
97	sdram_dec_data[15]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	V7
98	sdram_dec_data[14]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	W7
99	sdram_dec_data[13]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	Y7
100	sdram_dec_data[12]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	U9
101	sdram_dec_data[11]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	V8
102	sdram_dec_data[10]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	W8
103	sdram_dec_data[ 9]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	Y8
104	sdram_dec_data[ 8]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	T9
105	sdram_dec_data[ 7]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	V9
106	sdram_dec_data[ 6]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	W9
107	sdram_dec_data[ 5]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	Y9
108	sdram_dec_data[ 4]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	U10
109	sdram_dec_data[ 3]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	V10
110	sdram_dec_data[ 2]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	W10
111	sdram_dec_data[ 1]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	Y10
112	sdram_dec_data[ 0]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	T10
113	sdram_dec_addr[10]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	V11
114	sdram_dec_addr[ 0]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	W11
115	sdram_dec_addr[ 9]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	Y11
116	sdram_dec_addr[ 1]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	U11
117	sdram_dec_addr[ 8]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	Y12
118	sdram_dec_addr[ 2]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	W12
119	sdram_dec_addr[ 7]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	V12

Table 9 I/O Signals, Sorted by Pad Number (Continued)

Pad No.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Ball Coord.
120	sdram_dec_addr[ 3]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	T11
121	sdram_dec_addr[ 6]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	Y13
122	sdram_dec_addr[ 4]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	W13
123	sdram_dec_addr[ 5]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	V13
124	sdram_dec_ba[0]	DMIU	Decoder SDRAM bank select[1:0]	Output	8	Slew rate cont.	U12
125	sdram_dec_we_	DMIU	Decoder SDRAM write enable	Output	8	Slew rate cont.	Y14
126	sdram_dec_cke	DMIU	Decoder SDRAM clock enable	Output	8	Slew rate cont.	W14
127	sdram_dec_clk	DMIU	Decoder SDRAM clock	Bi-Dir	24		V14
128	sdram_dec_cs_	DMIU	Decoder SDRAM chip select	Output	8	Slew rate cont.	T12
129	sdram_dec_dqm[0]	DMIU	Decoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	Y15
130	sdram_dec_dqm[1]	DMIU	Decoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	W15
131	sdram_dec_dqm[2]	DMIU	Decoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	Y16
132	sdram_dec_dqm[3]	DMIU	Decoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	U13
133	sdram_dec_ras_	DMIU	Decoder SDRAM row address strobe	Output	8	Slew rate cont.	V15
135	sdram_dec_cas_	DMIU	Decoder SDRAM column address strobe	Output	8	Slew rate cont.	W16
136	scl	ICI	ICI clock	Bi-Dir	4	Schmitt trig.	U14
137	sda	ICI	ICI data	Bi-Dir	4	Schmitt trig.	Y17
138	sdram_dec_ba[1]	DMIU	Decoder SDRAM bank select[1:0]	Output	8	Slew rate cont.	Y18
139	pio[11]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	V16
140	pio[10]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	U15
142	pio[ 9]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	W17
143	pio[ 8]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	Y19
144	pio[ 7]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	U16
145	pio[ 6]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	V17
146	pio[ 5]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	W18
147	pio[ 4]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	T15
148	pio[ 3]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	W19
149	pio[ 2]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	U17
150	pio[ 1]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	T16
151	pio[ 0]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	V18
152	sdram_enc_data[31]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	Y20
153	sdram_enc_data[30]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	W20
154	sdram_enc_data[29]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	V19
155	sdram_enc_data[28]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	U18
156	sdram_enc_data[27]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	V20



Table 9 I/O Signals, Sorted by Pad Number (Continued)

Pad No.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Ball Coord.
157	sdram_enc_data[26]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	U19
158	sdram_enc_data[25]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	T17
159	sdram_enc_data[24]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	T18
160	sdram_enc_data[23]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	U20
161	sdram_enc_data[22]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	T19
162	sdram_enc_data[21]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	R17
163	sdram_enc_data[20]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	T20
164	sdram_enc_data[19]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	R16
166	sdram_enc_data[18]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	P17
167	sdram_enc_data[17]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	R18
168	sdram_enc_data[16]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	R19
169	sdram_enc_data[15]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	R20
170	sdram_enc_data[14]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	N17
171	sdram_enc_data[13]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	N16
172	sdram_enc_data[12]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	P18
173	sdram_enc_data[11]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	P19
174	sdram_enc_data[10]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	P20
175	sdram_enc_data[ 9]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	M17
176	sdram_enc_data[ 8]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	N18
177	sdram_enc_data[ 7]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	N19
178	sdram_enc_data[ 6]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	N20
179	sdram_enc_data[ 5]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	M16
180	sdram_enc_data[ 4]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	M18
181	sdram_enc_data[ 3]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	M19
182	sdram_enc_data[ 2]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	M20
183	sdram_enc_data[ 1]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	L17
184	sdram_enc_data[ 0]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	L18
185	sdram_enc_clk	EMIU	Encoder SDRAM clock	Bi-Dir	24		L19
186	sdram_enc_cke	EMIU	Encoder SDRAM clock enable	Output	8	Slew rate cont.	L20
187	sdram_enc_cs_	EMIU	Encoder SDRAM chip select	Output	8	Slew rate cont.	L16
188	sdram_enc_dqm[0]	EMIU	Encoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	K18
189	sdram_enc_dqm[1]	EMIU	Encoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	K19
190	sdram_enc_dqm[2]	EMIU	Encoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	K20
191	sdram_enc_dqm[3]	EMIU	Encoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	K17
192	sdram_enc_addr[10]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	J20
193	sdram_enc_addr[ 0]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	J19

Table 9 I/O Signals, Sorted by Pad Number (Continued)

Pad No.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Ball Coord.
194	sdram_enc_addr[ 9]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	J18
195	sdram_enc_addr[ 1]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	K16
196	sdram_enc_addr[ 8]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	H20
197	sdram_enc_addr[ 2]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	H19
198	sdram_enc_addr[ 7]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	H18
199	sdram_enc_addr[ 3]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	J17
200	sdram_enc_addr[ 6]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	G20
201	sdram_enc_addr[ 4]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	G19
202	sdram_enc_addr[ 5]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	G18
203	vbi_data[7]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	J16
204	vbi_data[6]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	F20
205	ehtag_pcst4[2]	EJTAG	Program counter status trace4[2:0]	Bi-Dir	8	Pull-up	F19
205	vbi_data[5]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	F19
206	ehtag_pcst4[1]	EJTAG	Program counter status trace4[2:0]	Bi-Dir	8	Pull-up	H17
206	vbi_data[4]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	H17
207	ehtag_pcst4[0]	EJTAG	Program counter status trace4[2:0]	Bi-Dir	8	Pull-up	E20
207	vbi_data[3]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	E20
208	ehtag_pcst3[2]	EJTAG	Program counter status trace3[2:0]	Bi-Dir	8	Pull-up	H16
208	vbi_data[2]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	H16
209	ehtag_pcst3[1]	EJTAG	Program counter status trace3[2:0]	Bi-Dir	8	Pull-up	F18
209	vbi_data[1]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	F18
210	ehtag_pcst3[0]	EJTAG	Program counter status trace3[2:0]	Bi-Dir	8	Pull-up	E19
210	vbi_data[0]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	E19
211	vbi_data_en	VIU	VBI data enable	Input		Pull-up	G17
212	amclk_enc	AIU	Audio in master clock	Output	8		D20
213	PLL_amclk_enc	AIU	External audio in master clock	Input			C20
226	clk_vbi	VIU	External VBI clock 27 MHz	Input		Pull-up	E15
227	sdram_enc_ras_	EMIU	Encoder SDRAM row address strobe	Output	8	Slew rate cont.	C18
228	sdram_enc_cas_	EMIU	Encoder SDRAM column address strobe	Output	8	Slew rate cont.	A20
229	sdram_enc_ba[0]	EMIU	Encoder SDRAM bank select [1:0]	Output	8	Slew rate cont.	A19
230	sdram_enc_ba[1]	EMIU	Encoder SDRAM bank select [1:0]	Output	8	Slew rate cont.	B18
231	sdram_enc_we_	EMIU	Encoder SDRAM write enable	Output	8	Slew rate cont.	C17
232	cdo[7]	Mux	Compressed data out [7:0]	Output	8		A18
232	rom_addr[19]	ROM	ROM address [21:0]	Output	8		A18

Table 9 I/O Signals, Sorted by Pad Number (Continued)

Pad No.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Ball Coord.
233	cdo[6]	Mux	Compressed data out [7:0]	Output	8		B17
233	rom_addr[18]	ROM	ROM address [21:0]	Output	8		B17
234	cdo[5]	Mux	Compressed data out [7:0]	Output	8		D16
234	rom_addr[17]	ROM	ROM address [21:0]	Output	8		D16
235	cdo[4]	Mux	Compressed data out [7:0]	Output	8		C16
235	rom_addr[16]	ROM	ROM address [21:0]	Output	8		C16
236	cdo[3]	Mux	Compressed data out [7:0]	Output	8		A17
236	rom_addr[15]	ROM	ROM address [21:0]	Output	8		A17
237	cdo[2]	Mux	Compressed data out [7:0]	Output	8		B16
237	rom_addr[14]	ROM	ROM address [21:0]	Output	8		B16
238	cdo[1]	Mux	Compressed data out [7:0]	Output	8		D15
238	rom_addr[13]	ROM	ROM address [21:0]	Output	8		D15
239	cdo[0]	Mux	Compressed data out [7:0]	Output	8		A16
239	rom_addr[12]	ROM	ROM address [21:0]	Output	8		A16
240	cdo_clk	Mux	Compressed data out clock	Output	8		D14
240	rom_addr[11]	ROM	ROM address [21:0]	Output	8		D14
242	cdo_sop	Mux	Compressed data start of packet	Output	8		C15
242	rom_addr[10]	ROM	ROM address [21:0]	Output	8		C15
243	excd_clk	Mux	External compressed data clock	Input		Pull-down	B15
244	excd_rd	Mux	External compressed data read	Input		Pull-up	A15
246	cdo_valid	Mux	Compressed data out valid	Output	8		D13
246	rom_addr[ 9]	ROM	ROM address [21:0]	Output	8		D13
247	fifo_level	Mux	Mux FIFO level	Output	8		C14
247	rom_addr[ 8]	ROM	ROM address [21:0]	Output	8		C14
248	sd0_enc	AIU	I <sup>2</sup> S Audio in channel 1	Input		Pull-up	B14
249	sd1_enc	AIU	I <sup>2</sup> S Audio in channel 2	Input		Pull-up	A14
250	sck_enc	AIU	I <sup>2</sup> S Audio in clock	Bi-Dir	8	Pull-up	D12
251	ws_enc	AIU	I <sup>2</sup> S Audio in channel select	Bi-Dir	8	Pull-up	C13
252	vpo[7]	VIU	Video input data [7:0]	Input			B13
253	vpo[6]	VIU	Video input data [7:0]	Input			A13
254	vpo[5]	VIU	Video input data [7:0]	Input			E12
255	vpo[4]	VIU	Video input data [7:0]	Input			C12
256	vpo[3]	VIU	Video input data [7:0]	Input			B12
257	vpo[2]	VIU	Video input data [7:0]	Input			A12
258	vpo[1]	VIU	Video input data [7:0]	Input			D11
259	vpo[0]	VIU	Video input data [7:0]	Input			C11

Table 9 I/O Signals, Sorted by Pad Number (Continued)

Pad No.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Ball Coord.
260	clk_27	VIU	Video input clock 27 MHz	Input			A11
261	pcr_clk	Chip	PCR clock	Input			E11
262	reset_	Chip	Global reset	Input		Schmitt trig.	B11
263	rom_data[7]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	A10
264	rom_data[6]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	B10
265	rom_data[5]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	A9
266	rom_data[4]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	D10
267	rom_data[3]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	C10
268	rom_data[2]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	B9
269	rom_data[1]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	E10
270	rom_data[0]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	A8
271	vou_clk	VOU	Video output clock 27 MHz	Output	8		A7
272	rom_addr[ 7]	ROM	ROM address [21:0]	Output	8		C9
272	vou_vpo[7]	VOU	Video output data [7:0]	Output	8		C9
273	rom_addr[ 6]	ROM	ROM address [21:0]	Output	8		B8
273	vou_vpo[6]	VOU	Video output data [7:0]	Output	8		B8
274	rom_addr[ 5]	ROM	ROM address [21:0]	Output	8		D9
274	vou_vpo[5]	VOU	Video output data [7:0]	Output	8		D9
275	rom_addr[ 4]	ROM	ROM address [21:0]	Output	8		A6
275	vou_vpo[4]	VOU	Video output data [7:0]	Output	8		A6
276	rom_addr[ 3]	ROM	ROM address [21:0]	Output	8		E9
276	vou_vpo[3]	VOU	Video output data [7:0]	Output	8		E9
277	rom_addr[ 2]	ROM	ROM address [21:0]	Output	8		B7
277	vou_vpo[2]	VOU	Video output data [7:0]	Output	8		B7
278	rom_ce_	ROM	ROM chip enable	Output	8		C7
279	rom_addr[ 1]	ROM	ROM address [21:0]	Output	8		D8
279	vou_vpo[1]	VOU	Video output data [7:0]	Output	8		D8
280	rom_addr[ 0]	ROM	ROM address [21:0]	Output	8		C8
280	vou_vpo[0]	VOU	Video output data [7:0]	Output	8		C8
281	rom_oe_	ROM	ROM output enable	Output	8		A5
281	ws_dec	AOU	Audio out channel select	Output	8		A5
282	rom_we_	ROM	ROM write enable	Output	8		B6
282	sck_dec	AOU	Audio out clock	Output	8		B6
284	rom_addr[21]	ROM	ROM address [21:0]	Output	8		B5
284	sd0_dec	AOU	Audio out channel 1 - I <sup>2</sup> S	Output	8		B5

**Table 9 I/O Signals, Sorted by Pad Number (Continued)**

Pad No.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Ball Coord.
285	rom_addr[20]	ROM	ROM address [21:0]	Output	8		C6
285	sd1_dec	AOU	Audio out channel 2 - S/P-DIF	Output	8		C6
286	amclk_dec	AOU	Audio out master clock	Output	8		A4
300	PLL_amclk_dec	AOU	External audio out master clock	Input			A1

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Table 10 I/O Signals, Sorted by BGA Coordinates

Ball Coord.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.
A1	PLL_amclk_dec	AOU	External audio out master clock	Input			300
A4	amclk_dec	AOU	Audio out master clock	Output	8		286
A5	rom_oe_	ROM	ROM output enable	Output	8		281
A5	ws_dec	AOU	Audio out channel select	Output	8		281
A6	rom_addr[4]	ROM	ROM address [21:0]	Output	8		275
A6	vou_vpo[4]	VOU	Video output data [7:0]	Output	8		275
A7	vou_clk	VOU	Video output clock 27 MHz	Output	8		271
A8	rom_data[0]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	270
A9	rom_data[5]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	265
A10	rom_data[7]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	263
A11	clk_27	VIU	Video input clock 27 MHz	Input			260
A12	vpo[2]	VIU	Video input data [7:0]	Input			257
A13	vpo[6]	VIU	Video input data [7:0]	Input			253
A14	sd1_enc	AIU	I <sup>2</sup> S Audio in channel 2	Input		Pull-up	249
A15	excd_rd	Mux	External compressed data read	Input		Pull-up	244
A16	cdo[0]	Mux	Compressed data out [7:0]	Output	8		239
A16	rom_addr[12]	ROM	ROM address [21:0]	Output	8		239
A17	cdo[3]	Mux	Compressed data out [7:0]	Output	8		236
A17	rom_addr[15]	ROM	ROM address [21:0]	Output	8		236
A18	cdo[7]	Mux	Compressed data out [7:0]	Output	8		232
A18	rom_addr[19]	ROM	ROM address [21:0]	Output	8		232
A19	sdram_enc_ba[0]	EMIU	Encoder SDRAM bank select [1:0]	Output	8	Slew rate cont.	229
A20	sdram_enc_cas_	EMIU	Encoder SDRAM column address strobe	Output	8	Slew rate cont.	228
B1	cdi[5]	Demux	Compressed data in [7:0]	Input		Pull-up	3
B5	rom_addr[21]	ROM	ROM address [21:0]	Output	8		284
B5	sd0_dec	AOU	Audio out channel 1 - I <sup>2</sup> S	Output	8		284
B6	rom_we	ROM	ROM write enable	Output	8		282
B6	sck_dec	AOU	Audio out clock	Output	8		282
B7	rom_addr[2]	ROM	ROM address [21:0]	Output	8		277
B7	vou_vpo[2]	VOU	Video output data [7:0]	Output	8		277
B8	rom_addr[6]	ROM	ROM address [21:0]	Output	8		273
B8	vou_vpo[6]	VOU	Video output data [7:0]	Output	8		273
B9	rom_data[2]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	268

Table 10 I/O Signals, Sorted by BGA Coordinates (Continued)

Ball Coord.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.
B10	rom_data[6]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	264
B11	reset_	Chip	Global reset	Input		Schmitt trig.	262
B12	vpo[3]	VIU	Video input data [7:0]	Input			256
B13	vpo[7]	VIU	Video input data [7:0]	Input			252
B14	sd0_enc	AIU	I <sup>2</sup> S Audio in channel 1	Input		Pull-up	248
B15	excd_clk	Mux	External compressed data clock	Input		Pull-down	243
B16	cdo[2]	Mux	Compressed data out [7:0]	Output	8		237
B16	rom_addr[14]	ROM	ROM address [21:0]	Output	8		237
B17	cdo[6]	Mux	Compressed data out [7:0]	Output	8		233
B17	rom_addr[18]	ROM	ROM address [21:0]	Output	8		233
B18	sdram_enc_ba[1]	EMIU	Encoder SDRAM bank select [1:0]	Output	8	Slew rate cont.	230
C1	cdi[3]	Demux	Compressed data in [7:0]	Input		Pull-up	5
C2	cdi[4]	Demux	Compressed data in [7:0]	Input		Pull-up	4
C3	cdi[6]	Demux	Compressed data in [7:0]	Input		Pull-up	2
C6	rom_addr[20]	ROM	ROM address [21:0]	Output	8		285
C6	sd1_dec	AOU	Audio out channel 2 - S/P-DIF	Output	8		285
C7	rom_ce_	ROM	ROM chip enable	Output	8		278
C8	rom_addr[0]	ROM	ROM address [21:0]	Output	8		280
C8	vou_vpo[0]	VOU	Video output data [7:0]	Output	8		280
C9	rom_addr[7]	ROM	ROM address [21:0]	Output	8		272
C9	vou_vpo[7]	VOU	Video output data [7:0]	Output	8		272
C10	ejtag_enable	EJTAG	Enable EJTAG ports	Bi-Dir	4	Pull-up	267
C10	rom_data[3]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	267
C11	vpo[0]	VIU	Video input data [7:0]	Input			259
C12	vpo[4]	VIU	Video input data [7:0]	Input			255
C13	ws_enc	AIU	I <sup>2</sup> S Audio in channel select	Bi-Dir	8	Pull-up	251
C14	fifo_level	Mux	Mux FIFO level	Output	8		247
C14	rom_addr[8]	ROM	ROM address [21:0]	Output	8		247
C15	cdo_sop	Mux	Compressed data start of packet	Output	8		242
C15	rom_addr[10]	ROM	ROM address [21:0]	Output	8		242
C16	cdo[4]	Mux	Compressed data out [7:0]	Output	8		235
C16	rom_addr[16]	ROM	ROM address [21:0]	Output	8		235
C17	sdram_enc_we_	EMIU	Encoder SDRAM write enable	Output	8	Slew rate cont.	231
C18	sdram_enc_ras_	EMIU	Encoder SDRAM row address strobe	Output	8	Slew rate cont.	227
C20	PLL_amclk_enc	AIU	External audio in master clock	Input			213

Table 10 I/O Signals, Sorted by BGA Coordinates (Continued)

Ball Coord.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.
D1	cdi[1]	Demux	Compressed data in [7:0]	Input		Pull-up	7
D2	cdi[2]	Demux	Compressed data in [7:0]	Input		Pull-up	6
D3	cdi[0]	Demux	Compressed data in [7:0]	Input		Pull-up	8
D4	cdi[7]	Demux	Compressed data in [7:0]	Input		Pull-up	1
D8	rom_addr[1]	ROM	ROM address [21:0]	Output	8		279
D8	vou_vpo[1]	VOU	Video output data [7:0]	Output	8		279
D9	rom_addr[5]	ROM	ROM address [21:0]	Output	8		274
D9	vou_vpo[5]	VOU	Video output data [7:0]	Output	8		274
D10	rom_data[4]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	266
D11	vpo[1]	VIU	Video input data [7:0]	Input			258
D12	sck_enc	AIU	I <sup>2</sup> S Audio in clock	Bi-Dir	8	Pull-up	250
D13	cdo_valid	Mux	Compressed data out valid	Output	8		246
D13	rom_addr[9]	ROM	ROM address [21:0]	Output	8		246
D14	cdo_clk	Mux	Compressed data out clock	Output	8		240
D14	rom_addr[11]	ROM	ROM address [21:0]	Output	8		240
D15	cdo[1]	Mux	Compressed data out [7:0]	Output	8		238
D15	rom_addr[13]	ROM	ROM address [21:0]	Output	8		238
D16	cdo[5]	Mux	Compressed data out [7:0]	Output	8		234
D16	rom_addr[17]	ROM	ROM address [21:0]	Output	8		234
D20	amclk_enc	AIU	Audio in master clock	Output	8		212
E1	pci_req_	HIU / PCI	PCI bus request	Bi-Dir	PCI	Tri-state	13
E2	pci_clk	HIU / PCI	PCI clock	Input	PCI		12
E3	int_	HIU / Moto	Host interrupt	Output	PCI	Open-drain	11
E3	int_	HIU / Intel	Host interrupt	Output	PCI	Open-drain	11
E3	pci_inta_	HIU / PCI	PCI interrupt A	Output	PCI	Open-drain	11
E4	cdi_valid	Demux	Compressed data in enable	Input		Pull-up	9
E9	rom_addr[3]	ROM	ROM address [21:0]	Output	8		276
E9	vou_vpo[3]	VOU	Video output data [7:0]	Output	8		276
E10	rom_data[1]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	269
E11	pcr_clk	Chip	PCR clock	Input			261
E12	vpo[5]	VIU	Video input data [7:0]	Input			254
E15	clk_vbi	VIU	External VBI clock 27 MHz	Input		Pull-up	226
E19	ejtag_pcst3[0]	EJTAG	Program counter status trace3[2:0]	Bi-Dir	8	Pull-up	210
E19	vbi_data[0]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	210
E20	ejtag_pcst4[0]	EJTAG	Program counter status trace4[2:0]	Bi-Dir	8	Pull-up	207
E20	vbi_data[3]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	207



Table 10 I/O Signals, Sorted by BGA Coordinates (Continued)

Ball Coord.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.
F1	host_hiu_addr[11]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	19
F1	pci_ad[27]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	19
F2	host_hiu_addr[12]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	18
F2	pci_ad[28]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	18
F3	host_hiu_addr[13]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	17
F3	pci_ad[29]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	17
F4	cdi_clk	Demux	Compressed data in clock	Input		Pull-up	10
F18	ejtag_pcst3[1]	EJTAG	Program counter status trace3[2:0]	Bi-Dir	8	Pull-up	209
F18	vbi_data[1]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	209
F19	ejtag_pcst4[2]	EJTAG	Program counter status trace4[2:0]	Bi-Dir	8	Pull-up	205
F19	vbi_data[5]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	205
F20	vbi_data[6]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	204
G1	host_hiu_addr[8]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	24
G1	pci_ad[24]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	24
G2	pci_idsel	HIU / PCI	PCI init. device select	Input	PCI		23
G3	hiu_host_cdo_req_	HIU / Moto	Compressed data out request	Bi-Dir	PCI	Tri-state	22
G3	intel_cdo_req_	HIU / Intel	Compressed data out request	Bi-Dir	PCI	Tri-state	22
G3	pci_cbe_[3]	HIU / PCI	PCI bus command / byte enables	Bi-Dir	PCI	Tri-state	22
G4	host_hiu_addr[14]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	16
G4	pci_ad[30]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	16
G5	host_hiu_addr[15]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	15
G5	pci_ad[31]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	15
G17	vbi_data_en	VIU	VBI data enable	Input		Pull-up	211
G18	sdram_enc_addr[5]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	202
G19	sdram_enc_addr[4]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	201
G20	sdram_enc_addr[6]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	200
H1	host_hiu_addr[4]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	28
H1	pci_ad[20]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	28
H2	host_hiu_addr[5]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	27
H2	pci_ad[21]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	27
H3	host_hiu_addr[6]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	26
H3	pci_ad[22]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	26
H4	host_hiu_addr[9]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	21
H4	pci_ad[25]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	21
H5	host_hiu_addr[10]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	20
H5	pci_ad[26]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	20

Table 10 I/O Signals, Sorted by BGA Coordinates (Continued)

Ball Coord.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.
H16	ejtag_pcst3[2]	EJTAG	Program counter status trace3[2:0]	Bi-Dir	8	Pull-up	208
H16	vbi_data[2]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	208
H17	ejtag_pcst4[1]	EJTAG	Program counter status trace4[2:0]	Bi-Dir	8	Pull-up	206
H17	vbi_data[4]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	206
H18	sdram_enc_addr[7]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	198
H19	sdram_enc_addr[2]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	197
H20	sdram_enc_addr[8]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	196
J1	host_hiu_rw_	HIU / Moto	Host read/write	Bi-Dir	PCI	Tri-state	32
J1	intel_wr_	HIU / Intel	Host write	Bi-Dir	PCI	Tri-state	32
J1	pci_cbe_[2]	HIU / PCI	PCI bus command / byte enables	Bi-Dir	PCI	Tri-state	32
J2	host_hiu_addr[1]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	31
J2	pci_ad[17]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	31
J3	host_hiu_addr[2]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	30
J3	pci_ad[18]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	30
J4	host_hiu_addr[7]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	25
J4	pci_ad[23]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	25
J5	host_hiu_addr[3]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	29
J5	pci_ad[19]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	29
J16	vbi_data[7]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	203
J17	sdram_enc_addr[3]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	199
J18	sdram_enc_addr[9]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	194
J19	sdram_enc_addr[0]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	193
J20	sdram_enc_addr[10]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	192
K1	host_hiu_cdi_ack_	HIU / Moto	Host CDI acknowledge	Bi-Dir	PCI	Tri-state	36
K1	intel_cdi_ack_	HIU / Intel	Host CDI acknowledge	Bi-Dir	PCI	Tri-state	36
K1	pci_devsel_	HIU / PCI	PCI device select	Bi-Dir	PCI	Tri-state	36
K2	pci_trdy_	HIU / PCI	PCI target ready	Bi-Dir	PCI	Tri-state	35
K3	pci_irdy_	HIU / PCI	PCI initiator ready	Bi-Dir	PCI	Tri-state	34
K4	intel_rd_	HIU / Intel	Host read	Bi-Dir	PCI	Tri-state	33
K4	pci_frame_	HIU / PCI	PCI cycle frame / transaction	Bi-Dir	PCI	Tri-state	33
K5	hiu_host_cdi_req_	HIU / Moto	Host CDI request	Bi-Dir	PCI	Tri-state	37
K5	intel_cdi_req_	HIU / Intel	Host CDI request	Bi-Dir	PCI	Tri-state	37
K5	pci_stop_	HIU / PCI	PCI stop transaction	Bi-Dir	PCI	Tri-state	37
K16	sdram_enc_addr[1]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	195
K17	sdram_enc_dqm[3]	EMIU	Encoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	191
K18	sdram_enc_dqm[0]	EMIU	Encoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	188

Table 10 I/O Signals, Sorted by BGA Coordinates (Continued)

Ball Coord.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.
K19	sdram_enc_dqm[1]	EMIU	Encoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	189
K20	sdram_enc_dqm[2]	EMIU	Encoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	190
L1	hiu_host_dtack_	HIU / Moto	Host CDO transfer acknowledge	Bi-Dir	PCI	Open-drain	40
L1	intel_dtack_	HIU / Intel	Host CDO transfer acknowledge	Bi-Dir	PCI	Open-drain	40
L1	pci_serr_	HIU / PCI	PCI system error	Bi-Dir	PCI	Open-drain	40
L2	host_hiu_cdo_ack_	HIU / Moto	Host CDO acknowledge	Bi-Dir	PCI	Tri-state	39
L2	intel_cdo_ack_	HIU / Intel	Host CDO acknowledge	Bi-Dir	PCI	Tri-state	39
L2	pci_perr_	HIU / PCI	PCI parity error	Bi-Dir	PCI	Tri-state	39
L3	pci_gnt_	HIU / PCI	PCI grant	Input	PCI	Tri-state	38
L4	pci_par	HIU / PCI	PCI parity	Bi-Dir	PCI	Tri-state	41
L5	host_hiu_data[14]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	45
L5	intel_ad[14]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	45
L5	pci_ad[14]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	45
L16	sdram_enc_cs_	EMIU	Encoder SDRAM chip select	Output	8	Slew rate cont.	187
L17	sdram_enc_data[1]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	183
L18	sdram_enc_data[0]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	184
L19	sdram_enc_clk	EMIU	Encoder SDRAM clock	Bi-Dir	24		185
L20	sdram_enc_cke	EMIU	Encoder SDRAM clock enable	Output	8	Slew rate cont.	186
M1	host_hiu_cs_	HIU / Moto	Host chip select	Bi-Dir	PCI	Tri-state	42
M1	intel_cs_	HIU / Intel	Host chip select	Bi-Dir	PCI	Tri-state	42
M1	pci_cbe_[1]	HIU / PCI	PCI bus command / byte enables	Bi-Dir	PCI	Tri-state	42
M2	host_hiu_addr[0]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	43
M2	pci_ad[16]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	43
M3	host_hiu_data[15]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	44
M3	intel_ad[15]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	44
M3	pci_ad[15]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	44
M4	host_hiu_data[10]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	49
M4	intel_ad[10]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	49
M4	pci_ad[10]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	49
M5	host_hiu_data[7]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	53
M5	intel_ad[7]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	53
M5	pci_ad[7]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	53
M16	sdram_enc_data[5]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	179
M17	sdram_enc_data[9]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	175
M18	sdram_enc_data[4]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	180
M19	sdram_enc_data[3]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	181

Table 10 I/O Signals, Sorted by BGA Coordinates (Continued)

Ball Coord.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.
M20	sdram_enc_data[2]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	182
N1	host_hiu_data[13]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	46
N1	intel_ad[13]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	46
N1	pci_ad[13]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	46
N2	host_hiu_data[12]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	47
N2	intel_ad[12]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	47
N2	pci_ad[12]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	47
N3	host_hiu_data[11]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	48
N3	intel_ad[11]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	48
N3	pci_ad[11]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	48
N4	host_hiu_data[3]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	57
N4	intel_ad[3]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	57
N4	pci_ad[3]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	57
N5	host_hiu_data[1]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	59
N5	intel_ad[1]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	59
N5	pci_ad[1]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	59
N16	sdram_enc_data[13]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	171
N17	sdram_enc_data[14]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	170
N18	sdram_enc_data[8]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	176
N19	sdram_enc_data[7]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	177
N20	sdram_enc_data[6]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	178
P1	host_hiu_data[9]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	50
P1	intel_ad[9]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	50
P1	pci_ad[9]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	50
P2	host_hiu_data[8]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	51
P2	intel_ad[8]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	51
P2	pci_ad[8]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	51
P3	host_hiu_as_	HIU / Moto	Host address select	Bi-Dir	PCI	Tri-state	52
P3	intel_as_ale_	HIU / Intel	Host address select / address latch enable	Bi-Dir	PCI	Tri-state	52
P3	pci_cbe_[0]	HIU / PCI	PCI bus command / byte enables	Bi-Dir	PCI	Tri-state	52
P4	trst_	JTAG	Test reset	Input		Pull-down	61
P5	ehtag_delk	EJTAG	Debug clock	Output	8		66
P17	sdram_enc_data[18]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	166
P18	sdram_enc_data[12]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	172
P19	sdram_enc_data[11]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	173
P20	sdram_enc_data[10]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	174

Table 10 I/O Signals, Sorted by BGA Coordinates (Continued)

Ball Coord.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.
R1	host_hiu_data[6]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	54
R1	intel_ad[6]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	54
R1	pci_ad[6]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	54
R2	host_hiu_data[5]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	55
R2	intel_ad[5]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	55
R2	pci_ad[5]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	55
R3	host_hiu_data[2]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	58
R3	intel_ad[2]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	58
R3	pci_ad[2]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	58
R4	tdo	JTAG	Test data out	Output	4	Pull-up/ tri-state	65
R16	sdram_enc_data[19]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	164
R17	sdram_enc_data[21]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	162
R18	sdram_enc_data[17]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	167
R19	sdram_enc_data[16]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	168
R20	sdram_enc_data[15]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	169
T1	host_hiu_data[4]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	56
T1	intel_ad[4]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	56
T1	pci_ad[4]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	56
T2	host_hiu_data[0]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	60
T2	intel_ad[0]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	60
T2	pci_ad[0]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	60
T20	sdram_enc_data[20]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	163
T3	tdi	JTAG	Test data in	Input		Pull-up	64
T4	PLL_bypass	mPLL	Main PLL disable / bypass	Input			69
T6	ejtag_pcast2[1]	EJTAG	Program counter status trace2[2:0]	Output	8		76
T7	sdram_dec_data[21]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	91
T8	sdram_dec_data[17]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	95
T9	sdram_dec_data[8]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	104
T10	sdram_dec_data[0]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	112
T11	sdram_dec_addr[3]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	120
T12	sdram_dec_cs_	DMIU	Decoder SDRAM chip select	Output	8	Slew rate cont.	128
T15	pio[4]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	147
T16	pio[1]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	150
T17	sdram_enc_data[25]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	158
T18	sdram_enc_data[24]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	159
T19	sdram_enc_data[22]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	161

Table 10 I/O Signals, Sorted by BGA Coordinates (Continued)

Ball Coord.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.
U1	tms	JTAG	Test mode select	Input		Pull-up	62
U2	ejtag_pcast2[0]	EJTAG	Program counter status trace2[2:0]	Output	8		67
U5	sdram_dec_data[28]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	84
U6	sdram_dec_data[24]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	88
U7	sdram_dec_data[22]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	90
U8	sdram_dec_data[16]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	96
U9	sdram_dec_data[12]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	100
U10	sdram_dec_data[4]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	108
U11	sdram_dec_addr[1]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	116
U12	sdram_dec_ba[0]	DMIU	Decoder SDRAM bank select[1:0]	Output	8	Slew rate cont.	124
U13	sdram_dec_dqm[3]	DMIU	Decoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	132
U14	scl	ICI	ICI clock	Bi-Dir	4	Schmitt trig.	136
U15	host_pci_grant2	HIU / Moto	Host bus grant	Bi-Dir	8	Pull-up	140
U15	intel_pci_grant2	HIU / Intel	Host bus grant	Bi-Dir	8	Pull-up	140
U15	pio[10]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	140
U16	pio[7]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	144
U17	pio[2]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	149
U18	sdram_enc_data[28]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	155
U19	sdram_enc_data[26]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	157
U20	sdram_enc_data[23]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	160
V1	tck	JTAG	Test clock	Input		Pull-up	63
V3	ejtag_pcast2[2]	EJTAG	Program counter status trace2[2:0]	Output	8		77
V4	sdram_dec_data[31]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	81
V5	sdram_dec_data[27]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	85
V6	sdram_dec_data[20]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	92
V7	sdram_dec_data[15]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	97
V8	sdram_dec_data[11]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	101
V9	sdram_dec_data[7]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	105
V10	sdram_dec_data[3]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	109
V11	sdram_dec_addr[10]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	113
V12	sdram_dec_addr[7]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	119
V13	sdram_dec_addr[5]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	123
V14	sdram_dec_clk	DMIU	Decoder SDRAM clock	Bi-Dir	24		127
V15	sdram_dec_ras_	DMIU	Decoder SDRAM row address strobe	Output	8	Slew rate cont.	133
V16	host_pci_req2	HIU /Moto	Host bus request	Bi-Dir	8	Pull-up	139
V16	intel_pci_req2	HIU / Intel	Host bus request	Bi-Dir	8	Pull-up	139

Table 10 I/O Signals, Sorted by BGA Coordinates (Continued)

Ball Coord.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.
V16	pio[11]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	139
V17	pio[6]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	145
V18	pio[0]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	151
V19	sdram_enc_data[29]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	154
V20	sdram_enc_data[27]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	156
W1	PLL_clock	mPLL	Main PLL clock	Input			68
W3	ejtag_pcst[2]	EJTAG	Program counter status trace[2:0]	Output	8		80
W4	sdram_dec_data[29]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	83
W5	sdram_dec_data[25]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	87
W6	sdram_dec_data[19]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	93
W7	sdram_dec_data[14]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	98
W8	sdram_dec_data[10]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	102
W9	sdram_dec_data[6]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	106
W10	sdram_dec_data[2]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	110
W11	sdram_dec_addr[0]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	114
W12	sdram_dec_addr[2]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	118
W13	sdram_dec_addr[4]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	122
W14	sdram_dec_cke	DMIU	Decoder SDRAM clock enable	Output	8	Slew rate cont.	126
W15	sdram_dec_dqm[1]	DMIU	Decoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	130
W16	sdram_dec_cas_	DMIU	Decoder SDRAM column address strobe	Output	8	Slew rate cont.	135
W17	pio[9]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	142
W18	pio[5]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	146
W19	pio[3]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	148
W20	sdram_enc_data[30]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	153
Y1	ejtag_pcst[0]	EJTAG	Program counter status trace[2:0]	Output	8		78
Y2	ejtag_pcst[1]	EJTAG	Program counter status trace[2:0]	Output	8		79
Y3	sdram_dec_data[30]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	82
Y4	sdram_dec_data[26]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	86
Y5	sdram_dec_data[23]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	89
Y6	sdram_dec_data[18]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	94
Y7	sdram_dec_data[13]	DMIU	Decoder DRAM data [31:0]	Bi-Dir	8	Slew rate cont.	99
Y8	sdram_dec_data[9]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	103
Y9	sdram_dec_data[5]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	107
Y10	sdram_dec_data[1]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	111
Y11	sdram_dec_addr[9]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	115
Y12	sdram_dec_addr[8]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	117

Table 10 I/O Signals, Sorted by BGA Coordinates (Continued)

Ball Coord.	Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.
Y13	sdram_dec_addr[6]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	121
Y14	sdram_dec_we_	DMIU	Decoder SDRAM write enable	Output	8	Slew rate cont.	125
Y15	sdram_dec_dqm[0]	DMIU	Decoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	129
Y16	sdram_dec_dqm[2]	DMIU	Decoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	131
Y17	sda	ICI	ICI data	Bi-Dir	4	Schmitt trig.	137
Y18	sdram_dec_ba[1]	DMIU	Decoder SDRAM bank select[1:0]	Output	8	Slew rate cont.	138
Y19	host_pci_int2	HIU / Moto	Host bus interrupt	Bi-Dir	8	Pull-up	143
Y19	intel_pci_int2	HIU / Intel	Host bus interrupt	Bi-Dir	8	Pull-up	143
Y19	pio[8]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	143
Y20	sdram_enc_data[31]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	152

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Table 11 I/O Signals, Sorted by Module

Module	Signal Name	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
AIU	amclk_enc	Audio in master clock	Output	8		212	D20
AIU	PLL_amclk_enc	External audio in master clock	Input			213	C20
AIU	sck_enc	I <sup>2</sup> S Audio in clock	Bi-Dir	8	Pull-up	250	D12
AIU	sd0_enc	I <sup>2</sup> S Audio in channel 1	Input		Pull-up	248	B14
AIU	sd1_enc	I <sup>2</sup> S Audio in channel 2	Input		Pull-up	249	A14
AIU	ws_enc	I <sup>2</sup> S Audio in channel select	Bi-Dir	8	Pull-up	251	C13
AOU	amclk_dec	Audio out master clock	Output	8		286	A4
AOU	PLL_amclk_dec	External audio out master clock	Input			300	A1
AOU	sck_dec	Audio out clock	Output	8		282	B6
AOU	sd0_dec	Audio out channel 1 - I <sup>2</sup> S	Output	8		284	B5
AOU	sd1_dec	Audio out channel 2 - S/P-DIF	Output	8		285	C6
AOU	ws_dec	Audio out channel select	Output	8		281	A5
Chip	pcr_clk	PCR clock	Input			261	E11
Chip	reset_	Global reset	Input		Schmitt trig.	262	B11
Demux	cdi[0]	Compressed data in [7:0]	Input		Pull-up	8	D3
Demux	cdi[1]	Compressed data in [7:0]	Input		Pull-up	7	D1
Demux	cdi[2]	Compressed data in [7:0]	Input		Pull-up	6	D2
Demux	cdi[3]	Compressed data in [7:0]	Input		Pull-up	5	C1
Demux	cdi[4]	Compressed data in [7:0]	Input		Pull-up	4	C2
Demux	cdi[5]	Compressed data in [7:0]	Input		Pull-up	3	B1
Demux	cdi[6]	Compressed data in [7:0]	Input		Pull-up	2	C3
Demux	cdi[7]	Compressed data in [7:0]	Input		Pull-up	1	D4
Demux	cdi_clk	Compressed data in clock	Input		Pull-up	10	F4
Demux	cdi_valid	Compressed data in enable	Input		Pull-up	9	E4
DMIU	sdram_dec_addr[ 0]	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	114	W11
DMIU	sdram_dec_addr[ 1]	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	116	U11
DMIU	sdram_dec_addr[ 2]	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	118	W12
DMIU	sdram_dec_addr[ 3]	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	120	T11
DMIU	sdram_dec_addr[ 4]	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	122	W13
DMIU	sdram_dec_addr[ 5]	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	123	V13
DMIU	sdram_dec_addr[ 6]	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	121	Y13
DMIU	sdram_dec_addr[ 7]	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	119	V12
DMIU	sdram_dec_addr[ 8]	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	117	Y12
DMIU	sdram_dec_addr[ 9]	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	115	Y11
DMIU	sdram_dec_addr[10]	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	113	V11

Table 11 I/O Signals, Sorted by Module (Continued)

Module	Signal Name	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
DMIU	sdram_dec_ba[0]	Decoder SDRAM bank select[1:0]	Output	8	Slew rate cont.	124	U12
DMIU	sdram_dec_ba[1]	Decoder SDRAM bank select[1:0]	Output	8	Slew rate cont.	138	Y18
DMIU	sdram_dec_cas_	Decoder SDRAM column address strobe	Output	8	Slew rate cont.	135	W16
DMIU	sdram_dec_cke	Decoder SDRAM clock enable	Output	8	Slew rate cont.	126	W14
DMIU	sdram_dec_clk	Decoder SDRAM clock	Bi-Dir	24		127	V14
DMIU	sdram_dec_cs_	Decoder SDRAM chip select	Output	8	Slew rate cont.	128	T12
DMIU	sdram_dec_data[ 0]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	112	T10
DMIU	sdram_dec_data[ 1]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	111	Y10
DMIU	sdram_dec_data[ 2]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	110	W10
DMIU	sdram_dec_data[ 3]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	109	V10
DMIU	sdram_dec_data[ 4]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	108	U10
DMIU	sdram_dec_data[ 5]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	107	Y9
DMIU	sdram_dec_data[ 6]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	106	W9
DMIU	sdram_dec_data[ 7]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	105	V9
DMIU	sdram_dec_data[ 8]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	104	T9
DMIU	sdram_dec_data[ 9]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	103	Y8
DMIU	sdram_dec_data[10]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	102	W8
DMIU	sdram_dec_data[11]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	101	V8
DMIU	sdram_dec_data[12]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	100	U9
DMIU	sdram_dec_data[13]	Decoder DRAM data [31:0]	Bi-Dir	8	Slew rate cont.	99	Y7
DMIU	sdram_dec_data[14]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	98	W7
DMIU	sdram_dec_data[15]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	97	V7
DMIU	sdram_dec_data[16]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	96	U8
DMIU	sdram_dec_data[17]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	95	T8
DMIU	sdram_dec_data[18]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	94	Y6
DMIU	sdram_dec_data[19]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	93	W6
DMIU	sdram_dec_data[20]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	92	V6
DMIU	sdram_dec_data[21]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	91	T7
DMIU	sdram_dec_data[22]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	90	U7
DMIU	sdram_dec_data[23]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	89	Y5
DMIU	sdram_dec_data[24]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	88	U6
DMIU	sdram_dec_data[25]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	87	W5
DMIU	sdram_dec_data[26]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	86	Y4
DMIU	sdram_dec_data[27]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	85	V5
DMIU	sdram_dec_data[28]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	84	U5
DMIU	sdram_dec_data[29]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	83	W4

Table 11 I/O Signals, Sorted by Module (Continued)

Module	Signal Name	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
DMIU	sdram_dec_data[30]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	82	Y3
DMIU	sdram_dec_data[31]	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	81	V4
DMIU	sdram_dec_dqm[0]	Decoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	129	Y15
DMIU	sdram_dec_dqm[1]	Decoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	130	W15
DMIU	sdram_dec_dqm[2]	Decoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	131	Y16
DMIU	sdram_dec_dqm[3]	Decoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	132	U13
DMIU	sdram_dec_ras_	Decoder SDRAM row address strobe	Output	8	Slew rate cont.	133	V15
DMIU	sdram_dec_we_	Decoder SDRAM write enable	Output	8	Slew rate cont.	125	Y14
EJTAG	ejtag_dclk	Debug clock	Output	8		66	P5
EJTAG	ejtag_pcst[0]	Program counter status trace[2:0]	Output	8		78	Y1
EJTAG	ejtag_pcst[1]	Program counter status trace[2:0]	Output	8		79	Y2
EJTAG	ejtag_pcst[2]	Program counter status trace[2:0]	Output	8		80	W3
EJTAG	ejtag_pcst2[0]	Program counter status trace2[2:0]	Output	8		67	U2
EJTAG	ejtag_pcst2[1]	Program counter status trace2[2:0]	Output	8		76	T6
EJTAG	ejtag_pcst2[2]	Program counter status trace2[2:0]	Output	8		77	V3
EJTAG	ejtag_pcst3[0]	Program counter status trace3[2:0]	Bi-Dir	8	Pull-up	210	E19
EJTAG	ejtag_pcst3[1]	Program counter status trace3[2:0]	Bi-Dir	8	Pull-up	209	F18
EJTAG	ejtag_pcst3[2]	Program counter status trace3[2:0]	Bi-Dir	8	Pull-up	208	H16
EJTAG	ejtag_pcst4[0]	Program counter status trace4[2:0]	Bi-Dir	8	Pull-up	207	E20
EJTAG	ejtag_pcst4[1]	Program counter status trace4[2:0]	Bi-Dir	8	Pull-up	206	H17
EJTAG	ejtag_pcst4[2]	Program counter status trace4[2:0]	Bi-Dir	8	Pull-up	205	F19
EMIU	sdram_enc_addr[ 0]	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	193	J19
EMIU	sdram_enc_addr[ 1]	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	195	K16
EMIU	sdram_enc_addr[ 2]	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	197	H19
EMIU	sdram_enc_addr[ 3]	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	199	J17
EMIU	sdram_enc_addr[ 4]	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	201	G19
EMIU	sdram_enc_addr[ 5]	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	202	G18
EMIU	sdram_enc_addr[ 6]	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	200	G20
EMIU	sdram_enc_addr[ 7]	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	198	H18
EMIU	sdram_enc_addr[ 8]	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	196	H20
EMIU	sdram_enc_addr[ 9]	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	194	J18
EMIU	sdram_enc_addr[10]	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	192	J20
EMIU	sdram_enc_ba[0]	Encoder SDRAM bank select [1:0]	Output	8	Slew rate cont.	229	A19
EMIU	sdram_enc_ba[1]	Encoder SDRAM bank select [1:0]	Output	8	Slew rate cont.	230	B18

Table 11 I/O Signals, Sorted by Module (Continued)

Module	Signal Name	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
EMIU	sdram_enc_cas_	Encoder SDRAM column address strobe	Output	8	Slew rate cont.	228	A20
EMIU	sdram_enc_cke	Encoder SDRAM clock enable	Output	8	Slew rate cont.	186	L20
EMIU	sdram_enc_clk	Encoder SDRAM clock	Bi-Dir	24		185	L19
EMIU	sdram_enc_cs_	Encoder SDRAM chip select	Output	8	Slew rate cont.	187	L16
EMIU	sdram_enc_data[ 0]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	184	L18
EMIU	sdram_enc_data[ 1]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	183	L17
EMIU	sdram_enc_data[ 2]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	182	M20
EMIU	sdram_enc_data[ 3]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	181	M19
EMIU	sdram_enc_data[ 4]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	180	M18
EMIU	sdram_enc_data[ 5]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	179	M16
EMIU	sdram_enc_data[ 6]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	178	N20
EMIU	sdram_enc_data[ 7]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	177	N19
EMIU	sdram_enc_data[ 8]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	176	N18
EMIU	sdram_enc_data[ 9]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	175	M17
EMIU	sdram_enc_data[10]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	174	P20
EMIU	sdram_enc_data[11]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	173	P19
EMIU	sdram_enc_data[12]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	172	P18
EMIU	sdram_enc_data[13]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	171	N16
EMIU	sdram_enc_data[14]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	170	N17
EMIU	sdram_enc_data[15]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	169	R20
EMIU	sdram_enc_data[16]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	168	R19
EMIU	sdram_enc_data[17]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	167	R18
EMIU	sdram_enc_data[18]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	166	P17
EMIU	sdram_enc_data[19]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	164	R16
EMIU	sdram_enc_data[20]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	163	T20
EMIU	sdram_enc_data[21]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	162	R17
EMIU	sdram_enc_data[22]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	161	T19
EMIU	sdram_enc_data[23]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	160	U20
EMIU	sdram_enc_data[24]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	159	T18
EMIU	sdram_enc_data[25]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	158	T17
EMIU	sdram_enc_data[26]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	157	U19
EMIU	sdram_enc_data[27]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	156	V20
EMIU	sdram_enc_data[28]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	155	U18
EMIU	sdram_enc_data[29]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	154	V19
EMIU	sdram_enc_data[30]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	153	W20
EMIU	sdram_enc_data[31]	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	152	Y20

Table 11 I/O Signals, Sorted by Module (Continued)

Module	Signal Name	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
EMIU	sdram_enc_dqm[0]	Encoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	188	K18
EMIU	sdram_enc_dqm[1]	Encoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	189	K19
EMIU	sdram_enc_dqm[2]	Encoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	190	K20
EMIU	sdram_enc_dqm[3]	Encoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	191	K17
EMIU	sdram_enc_ras_	Encoder SDRAM row address strobe	Output	8	Slew rate cont.	227	C18
EMIU	sdram_enc_we_	Encoder SDRAM write enable	Output	8	Slew rate cont.	231	C17
GPIO	pio[ 0]	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	151	V18
GPIO	pio[ 1]	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	150	T16
GPIO	pio[ 2]	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	149	U17
GPIO	pio[ 3]	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	148	W19
GPIO	pio[ 4]	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	147	T15
GPIO	pio[ 5]	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	146	W18
GPIO	pio[ 6]	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	145	V17
GPIO	pio[ 7]	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	144	U16
GPIO	pio[ 8]	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	143	Y19
GPIO	pio[ 9]	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	142	W17
GPIO	pio[10]	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	140	U15
GPIO	pio[11]	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	139	V16
HIU / Intel	int_	Host interrupt	Output	PCI	Open-drain	11	E3
HIU / Intel	intel_ad[ 0]	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	60	T2
HIU / Intel	intel_ad[ 1]	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	59	N5
HIU / Intel	intel_ad[ 2]	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	58	R3
HIU / Intel	intel_ad[ 3]	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	57	N4
HIU / Intel	intel_ad[ 4]	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	56	T1
HIU / Intel	intel_ad[ 5]	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	55	R2
HIU / Intel	intel_ad[ 6]	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	54	R1
HIU / Intel	intel_ad[ 7]	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	53	M5
HIU / Intel	intel_ad[ 8]	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	51	P2
HIU / Intel	intel_ad[ 9]	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	50	P1
HIU / Intel	intel_ad[10]	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	49	M4
HIU / Intel	intel_ad[11]	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	48	N3
HIU / Intel	intel_ad[12]	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	47	N2
HIU / Intel	intel_ad[13]	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	46	N1
HIU / Intel	intel_ad[14]	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	45	L5
HIU / Intel	intel_ad[15]	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	44	M3

Table 11 I/O Signals, Sorted by Module (Continued)

Module	Signal Name	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
HIU / Intel	intel_as_ale_	Host address select / address latch enable	Bi-Dir	PCI	Tri-state	52	P3
HIU / Intel	intel_cdi_ack_	Host CDI acknowledge	Bi-Dir	PCI	Tri-state	36	K1
HIU / Intel	intel_cdi_req_	Host CDI request	Bi-Dir	PCI	Tri-state	37	K5
HIU / Intel	intel_cdo_ack_	Host CDO acknowledge	Bi-Dir	PCI	Tri-state	39	L2
HIU / Intel	intel_cdo_req_	Compressed data out request	Bi-Dir	PCI	Tri-state	22	G3
HIU / Intel	intel_cs_	Host chip select	Bi-Dir	PCI	Tri-state	42	M1
HIU / Intel	intel_dtack_	Host CDO transfer acknowledge	Bi-Dir	PCI	Open-drain	40	L1
HIU / Intel	intel_rd_	Host read	Bi-Dir	PCI	Tri-state	33	K4
HIU / Intel	intel_wr_	Host write	Bi-Dir	PCI	Tri-state	32	J1
HIU / Moto	hiu_host_cdi_req_	Host CDI request	Bi-Dir	PCI	Tri-state	37	K5
HIU / Moto	hiu_host_cdo_req_	Compressed data out request	Bi-Dir	PCI	Tri-state	22	G3
HIU / Moto	hiu_host_dtack_	Host CDO transfer acknowledge	Bi-Dir	PCI	Open-drain	40	L1
HIU / Moto	host_hiu_addr[ 0]	Host address [15:0]	Bi-Dir	PCI	Tri-state	43	M2
HIU / Moto	host_hiu_addr[ 1]	Host address [15:0]	Bi-Dir	PCI	Tri-state	31	J2
HIU / Moto	host_hiu_addr[ 2]	Host address [15:0]	Bi-Dir	PCI	Tri-state	30	J3
HIU / Moto	host_hiu_addr[ 3]	Host address [15:0]	Bi-Dir	PCI	Tri-state	29	J5
HIU / Moto	host_hiu_addr[ 4]	Host address [15:0]	Bi-Dir	PCI	Tri-state	28	H1
HIU / Moto	host_hiu_addr[ 5]	Host address [15:0]	Bi-Dir	PCI	Tri-state	27	H2
HIU / Moto	host_hiu_addr[ 6]	Host address [15:0]	Bi-Dir	PCI	Tri-state	26	H3
HIU / Moto	host_hiu_addr[ 7]	Host address [15:0]	Bi-Dir	PCI	Tri-state	25	J4
HIU / Moto	host_hiu_addr[ 8]	Host address [15:0]	Bi-Dir	PCI	Tri-state	24	G1
HIU / Moto	host_hiu_addr[ 9]	Host address [15:0]	Bi-Dir	PCI	Tri-state	21	H4
HIU / Moto	host_hiu_addr[10]	Host address [15:0]	Bi-Dir	PCI	Tri-state	20	H5
HIU / Moto	host_hiu_addr[11]	Host address [15:0]	Bi-Dir	PCI	Tri-state	19	F1
HIU / Moto	host_hiu_addr[12]	Host address [15:0]	Bi-Dir	PCI	Tri-state	18	F2
HIU / Moto	host_hiu_addr[13]	Host address [15:0]	Bi-Dir	PCI	Tri-state	17	F3
HIU / Moto	host_hiu_addr[14]	Host address [15:0]	Bi-Dir	PCI	Tri-state	16	G4
HIU / Moto	host_hiu_addr[15]	Host address [15:0]	Bi-Dir	PCI	Tri-state	15	G5
HIU / Moto	host_hiu_as_	Host address select	Bi-Dir	PCI	Tri-state	52	P3
HIU / Moto	host_hiu_cdi_ack_	Host CDI acknowledge	Bi-Dir	PCI	Tri-state	36	K1
HIU / Moto	host_hiu_cdo_ack_	Host CDO acknowledge	Bi-Dir	PCI	Tri-state	39	L2
HIU / Moto	host_hiu_cs_	Host chip select	Bi-Dir	PCI	Tri-state	42	M1
HIU / Moto	host_hiu_data[ 0]	Host data [15:0]	Bi-Dir	PCI	Tri-state	60	T2
HIU / Moto	host_hiu_data[ 1]	Host data [15:0]	Bi-Dir	PCI	Tri-state	59	N5
HIU / Moto	host_hiu_data[ 2]	Host data [15:0]	Bi-Dir	PCI	Tri-state	58	R3
HIU / Moto	host_hiu_data[ 3]	Host data [15:0]	Bi-Dir	PCI	Tri-state	57	N4

Table 11 I/O Signals, Sorted by Module (Continued)

Module	Signal Name	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
HIU / Moto	host_hiu_data[ 4]	Host data [15:0]	Bi-Dir	PCI	Tri-state	56	T1
HIU / Moto	host_hiu_data[ 5]	Host data [15:0]	Bi-Dir	PCI	Tri-state	55	R2
HIU / Moto	host_hiu_data[ 6]	Host data [15:0]	Bi-Dir	PCI	Tri-state	54	R1
HIU / Moto	host_hiu_data[ 7]	Host data [15:0]	Bi-Dir	PCI	Tri-state	53	M5
HIU / Moto	host_hiu_data[ 8]	Host data [15:0]	Bi-Dir	PCI	Tri-state	51	P2
HIU / Moto	host_hiu_data[ 9]	Host data [15:0]	Bi-Dir	PCI	Tri-state	50	P1
HIU / Moto	host_hiu_data[10]	Host data [15:0]	Bi-Dir	PCI	Tri-state	49	M4
HIU / Moto	host_hiu_data[11]	Host data [15:0]	Bi-Dir	PCI	Tri-state	48	N3
HIU / Moto	host_hiu_data[12]	Host data [15:0]	Bi-Dir	PCI	Tri-state	47	N2
HIU / Moto	host_hiu_data[13]	Host data [15:0]	Bi-Dir	PCI	Tri-state	46	N1
HIU / Moto	host_hiu_data[14]	Host data [15:0]	Bi-Dir	PCI	Tri-state	45	L5
HIU / Moto	host_hiu_data[15]	Host data [15:0]	Bi-Dir	PCI	Tri-state	44	M3
HIU / Moto	host_hiu_rw_	Host read/write	Bi-Dir	PCI	Tri-state	32	J1
HIU / Moto	int_	Host interrupt	Output	PCI	Open-drain	11	E3
HIU / PCI	pci_ad[ 5]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	55	R2
HIU / PCI	pci_ad[ 0]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	60	T2
HIU / PCI	pci_ad[ 1]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	59	N5
HIU / PCI	pci_ad[ 2]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	58	R3
HIU / PCI	pci_ad[ 3]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	57	N4
HIU / PCI	pci_ad[ 4]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	56	T1
HIU / PCI	pci_ad[ 6]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	54	R1
HIU / PCI	pci_ad[ 7]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	53	M5
HIU / PCI	pci_ad[ 8]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	51	P2
HIU / PCI	pci_ad[ 9]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	50	P1
HIU / PCI	pci_ad[10]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	49	M4
HIU / PCI	pci_ad[11]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	48	N3
HIU / PCI	pci_ad[12]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	47	N2
HIU / PCI	pci_ad[13]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	46	N1
HIU / PCI	pci_ad[14]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	45	L5
HIU / PCI	pci_ad[15]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	44	M3
HIU / PCI	pci_ad[16]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	43	M2
HIU / PCI	pci_ad[17]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	31	J2
HIU / PCI	pci_ad[18]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	30	J3
HIU / PCI	pci_ad[19]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	29	J5
HIU / PCI	pci_ad[20]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	28	H1
HIU / PCI	pci_ad[21]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	27	H2

Table 11 I/O Signals, Sorted by Module (Continued)

Module	Signal Name	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
HIU / PCI	pci_ad[22]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	26	H3
HIU / PCI	pci_ad[23]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	25	J4
HIU / PCI	pci_ad[24]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	24	G1
HIU / PCI	pci_ad[25]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	21	H4
HIU / PCI	pci_ad[26]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	20	H5
HIU / PCI	pci_ad[27]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	19	F1
HIU / PCI	pci_ad[28]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	18	F2
HIU / PCI	pci_ad[29]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	17	F3
HIU / PCI	pci_ad[30]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	16	G4
HIU / PCI	pci_ad[31]	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	15	G5
HIU / PCI	pci_cbe_[0]	PCI bus command / byte enables	Bi-Dir	PCI	Tri-state	52	P3
HIU / PCI	pci_cbe_[1]	PCI bus command / byte enables	Bi-Dir	PCI	Tri-state	42	M1
HIU / PCI	pci_cbe_[2]	PCI bus command / byte enables	Bi-Dir	PCI	Tri-state	32	J1
HIU / PCI	pci_cbe_[3]	PCI bus command / byte enables	Bi-Dir	PCI	Tri-state	22	G3
HIU / PCI	pci_clk	PCI clock	Input	PCI		12	E2
HIU / PCI	pci_devsel_	PCI device select	Bi-Dir	PCI	Tri-state	36	K1
HIU / PCI	pci_frame_	PCI cycle frame / transaction	Bi-Dir	PCI	Tri-state	33	K4
HIU / PCI	pci_gnt_	PCI grant	Input	PCI	Tri-state	38	L3
HIU / PCI	pci_idsel	PCI init. device select	Input	PCI		23	G2
HIU / PCI	pci_inta_	PCI interrupt A	Output	PCI	Open-drain	11	E3
HIU / PCI	pci_irdy_	PCI initiator ready	Bi-Dir	PCI	Tri-state	34	K3
HIU / PCI	pci_par	PCI parity	Bi-Dir	PCI	Tri-state	41	L4
HIU / PCI	pci_perr_	PCI parity error	Bi-Dir	PCI	Tri-state	39	L2
HIU / PCI	pci_req_	PCI bus request	Bi-Dir	PCI	Tri-state	13	E1
HIU / PCI	pci_serr_	PCI system error	Bi-Dir	PCI	Open-drain	40	L1
HIU / PCI	pci_stop_	PCI stop transaction	Bi-Dir	PCI	Tri-state	37	K5
HIU / PCI	pci_trdy_	PCI target ready	Bi-Dir	PCI	Tri-state	35	K2
ICI	scl	ICI clock	Bi-Dir	4	Schmitt trig.	136	U14
ICI	sda	ICI data	Bi-Dir	4	Schmitt trig.	137	Y17
JTAG	tck	Test clock	Input		Pull-up	63	V1
JTAG	tdi	Test data in	Input		Pull-up	64	T3
JTAG	tdo	Test data out	Output	4	Pull-up/ tri-state	65	R4
JTAG	tms	Test mode select	Input		Pull-up	62	U1
JTAG	trst_	Test reset	Input		Pull-down	61	P4
mPLL	PLL_bypass	Main PLL disable / bypass	Input			69	T4
mPLL	PLL_clock	Main PLL clock	Input			68	W1



Table 11 I/O Signals, Sorted by Module (Continued)

Module	Signal Name	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
Mux	cdo[0]	Compressed data out [7:0]	Output	8		239	A16
Mux	cdo[1]	Compressed data out [7:0]	Output	8		238	D15
Mux	cdo[2]	Compressed data out [7:0]	Output	8		237	B16
Mux	cdo[3]	Compressed data out [7:0]	Output	8		236	A17
Mux	cdo[4]	Compressed data out [7:0]	Output	8		235	C16
Mux	cdo[5]	Compressed data out [7:0]	Output	8		234	D16
Mux	cdo[6]	Compressed data out [7:0]	Output	8		233	B17
Mux	cdo[7]	Compressed data out [7:0]	Output	8		232	A18
Mux	cdo_clk	Compressed data out clock	Output	8		240	D14
Mux	cdo_sop	Compressed data start of packet	Output	8		242	C15
Mux	cdo_valid	Compressed data out valid	Output	8		246	D13
Mux	excd_clk	External compressed data clock	Input		Pull-down	243	B15
Mux	excd_rd	External compressed data read	Input		Pull-up	244	A15
Mux	fifo_level	Mux FIFO level	Output	8		247	C14
ROM	rom_addr[ 0]	ROM address [21:0]	Output	8		280	C8
ROM	rom_addr[ 1]	ROM address [21:0]	Output	8		279	D8
ROM	rom_addr[ 2]	ROM address [21:0]	Output	8		277	B7
ROM	rom_addr[ 3]	ROM address [21:0]	Output	8		276	E9
ROM	rom_addr[ 4]	ROM address [21:0]	Output	8		275	A6
ROM	rom_addr[ 5]	ROM address [21:0]	Output	8		274	D9
ROM	rom_addr[ 6]	ROM address [21:0]	Output	8		273	B8
ROM	rom_addr[ 7]	ROM address [21:0]	Output	8		272	C9
ROM	rom_addr[ 8]	ROM address [21:0]	Output	8		247	C14
ROM	rom_addr[ 9]	ROM address [21:0]	Output	8		246	D13
ROM	rom_addr[10]	ROM address [21:0]	Output	8		242	C15
ROM	rom_addr[11]	ROM address [21:0]	Output	8		240	D14
ROM	rom_addr[12]	ROM address [21:0]	Output	8		239	A16
ROM	rom_addr[13]	ROM address [21:0]	Output	8		238	D15
ROM	rom_addr[14]	ROM address [21:0]	Output	8		237	B16
ROM	rom_addr[15]	ROM address [21:0]	Output	8		236	A17
ROM	rom_addr[16]	ROM address [21:0]	Output	8		235	C16
ROM	rom_addr[17]	ROM address [21:0]	Output	8		234	D16
ROM	rom_addr[18]	ROM address [21:0]	Output	8		233	B17
ROM	rom_addr[19]	ROM address [21:0]	Output	8		232	A18
ROM	rom_addr[20]	ROM address [21:0]	Output	8		285	C6
ROM	rom_addr[21]	ROM address [21:0]	Output	8		284	B5

Table 11 I/O Signals, Sorted by Module (Continued)

Module	Signal Name	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
ROM	rom_ce_	ROM chip enable	Output	8		278	C7
ROM	rom_data[0]	ROM data [7:0]	Bi-Dir	4	Pull-up	270	A8
ROM	rom_data[1]	ROM data [7:0]	Bi-Dir	4	Pull-up	269	E10
ROM	rom_data[2]	ROM data [7:0]	Bi-Dir	4	Pull-up	268	B9
ROM	rom_data[3]	ROM data [7:0]	Bi-Dir	4	Pull-up	267	C10
ROM	rom_data[4]	ROM data [7:0]	Bi-Dir	4	Pull-up	266	D10
ROM	rom_data[5]	ROM data [7:0]	Bi-Dir	4	Pull-up	265	A9
ROM	rom_data[6]	ROM data [7:0]	Bi-Dir	4	Pull-up	264	B10
ROM	rom_data[7]	ROM data [7:0]	Bi-Dir	4	Pull-up	263	A10
ROM	rom_oe_	ROM output enable	Output	8		281	A5
ROM	rom_we_	ROM write enable	Output	8		282	B6
VIU	clk_27	Video input clock 27 MHz	Input			260	A11
VIU	clk_vbi	External VBI clock 27 MHz	Input		Pull-up	226	E15
VIU	vbi_data[0]	VBI data in [7:0]	Bi-Dir	8	Pull-up	210	E19
VIU	vbi_data[1]	VBI data in [7:0]	Bi-Dir	8	Pull-up	209	F18
VIU	vbi_data[2]	VBI data in [7:0]	Bi-Dir	8	Pull-up	208	H16
VIU	vbi_data[3]	VBI data in [7:0]	Bi-Dir	8	Pull-up	207	E20
VIU	vbi_data[4]	VBI data in [7:0]	Bi-Dir	8	Pull-up	206	H17
VIU	vbi_data[5]	VBI data in [7:0]	Bi-Dir	8	Pull-up	205	F19
VIU	vbi_data[6]	VBI data in [7:0]	Bi-Dir	8	Pull-up	204	F20
VIU	vbi_data[7]	VBI data in [7:0]	Bi-Dir	8	Pull-up	203	J16
VIU	vbi_data_en	VBI data enable	Input		Pull-up	211	G17
VIU	vpo[0]	Video input data [7:0]	Input			259	C11
VIU	vpo[1]	Video input data [7:0]	Input			258	D11
VIU	vpo[2]	Video input data [7:0]	Input			257	A12
VIU	vpo[3]	Video input data [7:0]	Input			256	B12
VIU	vpo[4]	Video input data [7:0]	Input			255	C12
VIU	vpo[5]	Video input data [7:0]	Input			254	E12
VIU	vpo[6]	Video input data [7:0]	Input			253	A13
VIU	vpo[7]	Video input data [7:0]	Input			252	B13
VOU	vou_clk	Video output clock 27 MHz	Output	8		271	A7
VOU	vou_vpo[0]	Video output data [7:0]	Output	8		280	C8
VOU	vou_vpo[1]	Video output data [7:0]	Output	8		279	D8
VOU	vou_vpo[2]	Video output data [7:0]	Output	8		277	B7
VOU	vou_vpo[3]	Video output data [7:0]	Output	8		276	E9

Table 11 I/O Signals, Sorted by Module (Continued)

Module	Signal Name	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
VOU	vou_vpo[4]	Video output data [7:0]	Output	8		275	A6
VOU	vou_vpo[5]	Video output data [7:0]	Output	8		274	D9
VOU	vou_vpo[6]	Video output data [7:0]	Output	8		273	B8
VOU	vou_vpo[7]	Video output data [7:0]	Output	8		272	C9

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Hardware Reference Manual - PRELIMINARY

Table 12 I/O Signals, Sorted by Signal Name

Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
amclk_dec	AOU	Audio out master clock	Output	8		286	A4
amclk_enc	AIU	Audio in master clock	Output	8		212	D20
cdi[0]	Demux	Compressed data in [7:0]	Input		Pull-up	8	D3
cdi[1]	Demux	Compressed data in [7:0]	Input		Pull-up	7	D1
cdi[2]	Demux	Compressed data in [7:0]	Input		Pull-up	6	D2
cdi[3]	Demux	Compressed data in [7:0]	Input		Pull-up	5	C1
cdi[4]	Demux	Compressed data in [7:0]	Input		Pull-up	4	C2
cdi[5]	Demux	Compressed data in [7:0]	Input		Pull-up	3	B1
cdi[6]	Demux	Compressed data in [7:0]	Input		Pull-up	2	C3
cdi[7]	Demux	Compressed data in [7:0]	Input		Pull-up	1	D4
cdi_clk	Demux	Compressed data in clock	Input		Pull-up	10	F4
cdi_valid	Demux	Compressed data in enable	Input		Pull-up	9	E4
cdo[0]	Mux	Compressed data out [7:0]	Output	8		239	A16
cdo[1]	Mux	Compressed data out [7:0]	Output	8		238	D15
cdo[2]	Mux	Compressed data out [7:0]	Output	8		237	B16
cdo[3]	Mux	Compressed data out [7:0]	Output	8		236	A17
cdo[4]	Mux	Compressed data out [7:0]	Output	8		235	C16
cdo[5]	Mux	Compressed data out [7:0]	Output	8		234	D16
cdo[6]	Mux	Compressed data out [7:0]	Output	8		233	B17
cdo[7]	Mux	Compressed data out [7:0]	Output	8		232	A18
cdo_clk	Mux	Compressed data out clock	Output	8		240	D14
cdo_sop	Mux	Compressed data start of packet	Output	8		242	C15
cdo_valid	Mux	Compressed data out valid	Output	8		246	D13
clk_27	VIU	Video input clock 27 MHz	Input			260	A11
clk_vbi	VIU	External VBI clock 27 MHz	Input		Pull-up	226	E15
ejtag_dclk	EJTAG	Debug clock	Output	8		66	P5
ejtag_pcst[0]	EJTAG	Program counter status trace[2:0]	Output	8		78	Y1
ejtag_pcst[1]	EJTAG	Program counter status trace[2:0]	Output	8		79	Y2
ejtag_pcst[2]	EJTAG	Program counter status trace[2:0]	Output	8		80	W3
ejtag_pcst2[0]	EJTAG	Program counter status trace2[2:0]	Output	8		67	U2
ejtag_pcst2[1]	EJTAG	Program counter status trace2[2:0]	Output	8		76	T6
ejtag_pcst2[2]	EJTAG	Program counter status trace2[2:0]	Output	8		77	V3
ejtag_pcst3[0]	EJTAG	Program counter status trace3[2:0]	Bi-Dir	8	Pull-up	210	E19
ejtag_pcst3[1]	EJTAG	Program counter status trace3[2:0]	Bi-Dir	8	Pull-up	209	F18
ejtag_pcst3[2]	EJTAG	Program counter status trace3[2:0]	Bi-Dir	8	Pull-up	208	H16

Table 12 I/O Signals, Sorted by Signal Name (Continued)

Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
ejtag_pcst4[0]	EJTAG	Program counter status trace4[2:0]	Bi-Dir	8	Pull-up	207	E20
ejtag_pcst4[1]	EJTAG	Program counter status trace4[2:0]	Bi-Dir	8	Pull-up	206	H17
ejtag_pcst4[2]	EJTAG	Program counter status trace4[2:0]	Bi-Dir	8	Pull-up	205	F19
excd_clk	Mux	External compressed data clock	Input		Pull-down	243	B15
excd_rd	Mux	External compressed data read	Input		Pull-up	244	A15
fifo_level	Mux	Mux FIFO level	Output	8		247	C14
hiu_host_cdi_req_	HIU / Moto	Host CDI request	Bi-Dir	PCI	Tri-state	37	K5
hiu_host_cdo_req_	HIU / Moto	Compressed data out request	Bi-Dir	PCI	Tri-state	22	G3
hiu_host_dtrack_	HIU / Moto	Host CDO transfer acknowledge	Bi-Dir	PCI	Open-drain	40	L1
host_hiu_addr[ 0]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	43	M2
host_hiu_addr[ 1]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	31	J2
host_hiu_addr[ 2]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	30	J3
host_hiu_addr[ 3]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	29	J5
host_hiu_addr[ 4]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	28	H1
host_hiu_addr[ 5]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	27	H2
host_hiu_addr[ 6]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	26	H3
host_hiu_addr[ 7]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	25	J4
host_hiu_addr[ 8]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	24	G1
host_hiu_addr[ 9]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	21	H4
host_hiu_addr[10]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	20	H5
host_hiu_addr[11]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	19	F1
host_hiu_addr[12]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	18	F2
host_hiu_addr[13]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	17	F3
host_hiu_addr[14]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	16	G4
host_hiu_addr[15]	HIU / Moto	Host address [15:0]	Bi-Dir	PCI	Tri-state	15	G5
host_hiu_as_	HIU / Moto	Host address select	Bi-Dir	PCI	Tri-state	52	P3
host_hiu_cdi_ack_	HIU / Moto	Host CDI acknowledge	Bi-Dir	PCI	Tri-state	36	K1
host_hiu_cdo_ack_	HIU / Moto	Host CDO acknowledge	Bi-Dir	PCI	Tri-state	39	I2
host_hiu_cs_	HIU / Moto	Host chip select	Bi-Dir	PCI	Tri-state	42	M1
host_hiu_data[ 0]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	60	T2
host_hiu_data[ 1]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	59	N5
host_hiu_data[ 2]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	58	R3
host_hiu_data[ 3]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	57	N4
host_hiu_data[ 4]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	56	T1
host_hiu_data[ 5]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	55	R2
host_hiu_data[ 6]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	54	R1

Table 12 I/O Signals, Sorted by Signal Name (Continued)

Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
host_hiu_data[ 7]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	53	M5
host_hiu_data[ 8]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	51	P2
host_hiu_data[ 9]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	50	P1
host_hiu_data[10]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	49	M4
host_hiu_data[11]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	48	N3
host_hiu_data[12]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	47	N2
host_hiu_data[13]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	46	N1
host_hiu_data[14]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	45	L5
host_hiu_data[15]	HIU / Moto	Host data [15:0]	Bi-Dir	PCI	Tri-state	44	M3
host_hiu_rw_	HIU / Moto	Host read/write	Bi-Dir	PCI	Tri-state	32	J1
int_	HIU / Moto	Host interrupt	Output	PCI	Open-drain	11	E3
int_	HIU / Intel	Host interrupt	Output	PCI	Open-drain	11	E3
intel_ad[ 0]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	60	T2
intel_ad[ 1]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	59	N5
intel_ad[ 2]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	58	R3
intel_ad[ 3]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	57	N4
intel_ad[ 4]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	56	T1
intel_ad[ 5]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	55	R2
intel_ad[ 6]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	54	R1
intel_ad[ 7]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	53	M5
intel_ad[ 8]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	51	P2
intel_ad[ 9]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	50	P1
intel_ad[10]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	49	M4
intel_ad[11]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	48	N3
intel_ad[12]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	47	N2
intel_ad[13]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	46	N1
intel_ad[14]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	45	L5
intel_ad[15]	HIU / Intel	Host data / address [15:0]	Bi-Dir	PCI	Tri-state	44	M3
intel_as_ale_	HIU / Intel	Host address select / address latch enable	Bi-Dir	PCI	Tri-state	52	P3
intel_cdi_ack_	HIU / Intel	Host CDI acknowledge	Bi-Dir	PCI	Tri-state	36	K1
intel_cdi_req_	HIU / Intel	Host CDI request	Bi-Dir	PCI	Tri-state	37	K5
intel_cdo_ack_	HIU / Intel	Host CDO acknowledge	Bi-Dir	PCI	Tri-state	39	L2
intel_cdo_req_	HIU / Intel	Compressed data out request	Bi-Dir	PCI	Tri-state	22	G3
intel_cs_	HIU / Intel	Host chip select	Bi-Dir	PCI	Tri-state	42	M1
intel_dtack_	HIU / Intel	Host CDO transfer acknowledge	Bi-Dir	PCI	Open-drain	40	L1
intel_rd_	HIU / Intel	Host read	Bi-Dir	PCI	Tri-state	33	K4

Table 12 I/O Signals, Sorted by Signal Name (Continued)

Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
intel_wr_	HIU / Intel	Host write	Bi-Dir	PCI	Tri-state	32	J1
pci_ad[ 0]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	60	T2
pci_ad[ 1]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	59	N5
pci_ad[ 2]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	58	R3
pci_ad[ 3]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	57	N4
pci_ad[ 4]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	56	T1
pci_ad[ 5]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	55	R2
pci_ad[ 6]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	54	R1
pci_ad[ 7]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	53	M5
pci_ad[ 8]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	51	P2
pci_ad[ 9]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	50	P1
pci_ad[10]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	49	M4
pci_ad[11]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	48	N3
pci_ad[12]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	47	N2
pci_ad[13]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	46	N1
pci_ad[14]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	45	L5
pci_ad[15]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	44	M3
pci_ad[16]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	43	M2
pci_ad[17]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	31	J2
pci_ad[18]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	30	J3
pci_ad[19]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	29	J5
pci_ad[20]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	28	H1
pci_ad[21]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	27	H2
pci_ad[22]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	26	H3
pci_ad[23]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	25	J4
pci_ad[24]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	24	G1
pci_ad[25]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	21	H4
pci_ad[26]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	20	H5
pci_ad[27]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	19	F1
pci_ad[28]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	18	F2
pci_ad[29]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	17	F3
pci_ad[30]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	16	G4
pci_ad[31]	HIU / PCI	PCI data/address [31:0]	Bi-Dir	PCI	Tri-state	15	G5
pci_cbe_[0]	HIU / PCI	PCI bus command / byte enables	Bi-Dir	PCI	Tri-state	52	P3
pci_cbe_[1]	HIU / PCI	PCI bus command / byte enables	Bi-Dir	PCI	Tri-state	42	M1
pci_cbe_[2]	HIU / PCI	PCI bus command / byte enables	Bi-Dir	PCI	Tri-state	32	J1

Table 12 I/O Signals, Sorted by Signal Name (Continued)

Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
pci_cbe_[3]	HIU / PCI	PCI bus command / byte enables	Bi-Dir	PCI	Tri-state	22	G3
pci_clk	HIU / PCI	PCI clock	Input	PCI		12	E2
pci_devsel_	HIU / PCI	PCI device select	Bi-Dir	PCI	Tri-state	36	K1
pci_frame_	HIU / PCI	PCI cycle frame / transaction	Bi-Dir	PCI	Tri-state	33	K4
pci_gnt_	HIU / PCI	PCI grant	Input	PCI	Tri-state	38	L3
pci_idsel	HIU / PCI	PCI init. device select	Input	PCI		23	G2
pci_inta_	HIU / PCI	PCI interrupt A	Output	PCI	Open-drain	11	E3
pci_irdy_	HIU / PCI	PCI initiator ready	Bi-Dir	PCI	Tri-state	34	K3
pci_par	HIU / PCI	PCI parity	Bi-Dir	PCI	Tri-state	41	L4
pci_perr_	HIU / PCI	PCI parity error	Bi-Dir	PCI	Tri-state	39	L2
pci_req_	HIU / PCI	PCI bus request	Bi-Dir	PCI	Tri-state	13	E1
pci_serr_	HIU / PCI	PCI system error	Bi-Dir	PCI	Open-drain	40	L1
pci_stop_	HIU / PCI	PCI stop transaction	Bi-Dir	PCI	Tri-state	37	K5
pci_trdy_	HIU / PCI	PCI target ready	Bi-Dir	PCI	Tri-state	35	K2
pcr_clk	Chip	PCR clock	Input			261	E11
pio[ 0]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	151	V18
pio[ 1]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	150	T16
pio[ 2]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	149	U17
pio[ 3]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	148	W19
pio[ 4]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	147	T15
pio[ 5]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	146	W18
pio[ 6]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	145	V17
pio[ 7]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	144	U16
pio[ 8]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	143	Y19
pio[ 9]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	142	W17
pio[10]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	140	U15
pio[11]	GPIO	General purpose I/O [11:0]	Bi-Dir	8	Pull-up	139	V16
PLL_amclk_dec	AOU	External audio out master clock	Input			300	A1
PLL_amclk_enc	AIU	External audio in master clock	Input			213	C20
PLL_bypass	mPLL	Main PLL disable / bypass	Input			69	T4
PLL_clock	mPLL	Main PLL clock	Input			68	W1
reset_	Chip	Global reset	Input		Schmitt trig.	262	B11
rom_addr[ 0]	ROM	ROM address [21:0]	Output	8		280	C8
rom_addr[ 1]	ROM	ROM address [21:0]	Output	8		279	D8
rom_addr[ 2]	ROM	ROM address [21:0]	Output	8		277	B7
rom_addr[ 3]	ROM	ROM address [21:0]	Output	8		276	E9



Table 12 I/O Signals, Sorted by Signal Name (Continued)

Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
rom_addr[ 4]	ROM	ROM address [21:0]	Output	8		275	A6
rom_addr[ 5]	ROM	ROM address [21:0]	Output	8		274	D9
rom_addr[ 6]	ROM	ROM address [21:0]	Output	8		273	B8
rom_addr[ 7]	ROM	ROM address [21:0]	Output	8		272	C9
rom_addr[ 8]	ROM	ROM address [21:0]	Output	8		247	C14
rom_addr[ 9]	ROM	ROM address [21:0]	Output	8		246	D13
rom_addr[10]	ROM	ROM address [21:0]	Output	8		242	C15
rom_addr[11]	ROM	ROM address [21:0]	Output	8		240	D14
rom_addr[12]	ROM	ROM address [21:0]	Output	8		239	A16
rom_addr[13]	ROM	ROM address [21:0]	Output	8		238	D15
rom_addr[14]	ROM	ROM address [21:0]	Output	8		237	B16
rom_addr[15]	ROM	ROM address [21:0]	Output	8		236	A17
rom_addr[16]	ROM	ROM address [21:0]	Output	8		235	C16
rom_addr[17]	ROM	ROM address [21:0]	Output	8		234	D16
rom_addr[18]	ROM	ROM address [21:0]	Output	8		233	B17
rom_addr[19]	ROM	ROM address [21:0]	Output	8		232	A18
rom_addr[20]	ROM	ROM address [21:0]	Output	8		285	C6
rom_addr[21]	ROM	ROM address [21:0]	Output	8		284	B5
rom_cc_	ROM	ROM chip enable	Output	8		278	C7
rom_data[0]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	270	A8
rom_data[1]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	269	E10
rom_data[2]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	268	B9
rom_data[3]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	267	C10
rom_data[4]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	266	D10
rom_data[5]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	265	A9
rom_data[6]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	264	B10
rom_data[7]	ROM	ROM data [7:0]	Bi-Dir	4	Pull-up	263	A10
rom_oe_	ROM	ROM output enable	Output	8		281	A5
rom_we_	ROM	ROM write enable	Output	8		282	B6
sck_dec	AOU	Audio out clock	Output	8		282	B6
sck_enc	AIU	I <sup>2</sup> S Audio in clock	Bi-Dir	8	Pull-up	250	D12
scl	ICI	ICI clock	Bi-Dir	4	Schmitt trig.	136	U14
sd0_dec	AOU	Audio out channel 1 - I <sup>2</sup> S	Output	8		284	B5
sd0_enc	AIU	I <sup>2</sup> S Audio in channel 1	Input		Pull-up	248	B14
sd1_dec	AOU	Audio out channel 2 - S/P-DIF	Output	8		285	C6
sd1_enc	AIU	I <sup>2</sup> S Audio in channel 2	Input		Pull-up	249	A14

Table 12 I/O Signals, Sorted by Signal Name (Continued)

Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
sda	ICI	ICI data	Bi-Dir	4	Schmitt trig.	137	Y17
sdram_dec_addr[ 0]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	114	W11
sdram_dec_addr[ 1]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	116	U11
sdram_dec_addr[ 2]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	118	W12
sdram_dec_addr[ 3]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	120	T11
sdram_dec_addr[ 4]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	122	W13
sdram_dec_addr[ 5]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	123	V13
sdram_dec_addr[ 6]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	121	Y13
sdram_dec_addr[ 7]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	119	V12
sdram_dec_addr[ 8]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	117	Y12
sdram_dec_addr[ 9]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	115	Y11
sdram_dec_addr[10]	DMIU	Decoder SDRAM address [10:0]	Output	8	Slew rate cont.	113	V11
sdram_dec_ba[0]	DMIU	Decoder SDRAM bank select[1:0]	Output	8	Slew rate cont.	124	U12
sdram_dec_ba[1]	DMIU	Decoder SDRAM bank select[1:0]	Output	8	Slew rate cont.	138	Y18
sdram_dec_cas_	DMIU	Decoder SDRAM column address strobe	Output	8	Slew rate cont.	135	W16
sdram_dec_cke	DMIU	Decoder SDRAM clock enable	Output	8	Slew rate cont.	126	W14
sdram_dec_clk	DMIU	Decoder SDRAM clock	Bi-Dir	24		127	V14
sdram_dec_cs_	DMIU	Decoder SDRAM chip select	Output	8	Slew rate cont.	128	T12
sdram_dec_data[ 0]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	112	T10
sdram_dec_data[ 1]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	111	Y10
sdram_dec_data[ 2]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	110	W10
sdram_dec_data[ 3]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	109	V10
sdram_dec_data[ 4]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	108	U10
sdram_dec_data[ 5]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	107	Y9
sdram_dec_data[ 6]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	106	W9
sdram_dec_data[ 7]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	105	V9
sdram_dec_data[ 8]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	104	T9
sdram_dec_data[ 9]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	103	Y8
sdram_dec_data[10]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	102	W8
sdram_dec_data[11]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	101	V8
sdram_dec_data[12]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	100	U9
sdram_dec_data[13]	DMIU	Decoder DRAM data [31:0]	Bi-Dir	8	Slew rate cont.	99	Y7
sdram_dec_data[14]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	98	W7
sdram_dec_data[15]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	97	V7
sdram_dec_data[16]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	96	U8
sdram_dec_data[17]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	95	T8

Table 12 I/O Signals, Sorted by Signal Name (Continued)

Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
sdram_dec_data[18]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	94	Y6
sdram_dec_data[19]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	93	W6
sdram_dec_data[20]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	92	V6
sdram_dec_data[21]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	91	T7
sdram_dec_data[22]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	90	U7
sdram_dec_data[23]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	89	Y5
sdram_dec_data[24]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	88	U6
sdram_dec_data[25]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	87	W5
sdram_dec_data[26]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	86	Y4
sdram_dec_data[27]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	85	V5
sdram_dec_data[28]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	84	U5
sdram_dec_data[29]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	83	W4
sdram_dec_data[30]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	82	Y3
sdram_dec_data[31]	DMIU	Decoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	81	V4
sdram_dec_dqm[0]	DMIU	Decoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	129	Y15
sdram_dec_dqm[1]	DMIU	Decoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	130	W15
sdram_dec_dqm[2]	DMIU	Decoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	131	Y16
sdram_dec_dqm[3]	DMIU	Decoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	132	U13
sdram_dec_ras_	DMIU	Decoder SDRAM row address strobe	Output	8	Slew rate cont.	133	V15
sdram_dec_we_	DMIU	Decoder SDRAM write enable	Output	8	Slew rate cont.	125	Y14
sdram_enc_addr[ 0]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	193	J19
sdram_enc_addr[ 1]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	195	K16
sdram_enc_addr[ 2]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	197	H19
sdram_enc_addr[ 3]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	199	J17
sdram_enc_addr[ 4]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	201	G19
sdram_enc_addr[ 5]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	202	G18
sdram_enc_addr[ 6]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	200	G20
sdram_enc_addr[ 7]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	198	H18
sdram_enc_addr[ 8]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	196	H20
sdram_enc_addr[ 9]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	194	J18
sdram_enc_addr[10]	EMIU	Encoder SDRAM address [10:0]	Output	8	Slew rate cont.	192	J20
sdram_enc_ba[0]	EMIU	Encoder SDRAM bank select [1:0]	Output	8	Slew rate cont.	229	A19
sdram_enc_ba[1]	EMIU	Encoder SDRAM bank select [1:0]	Output	8	Slew rate cont.	230	B18
sdram_enc_cas_	EMIU	Encoder SDRAM column address strobe	Output	8	Slew rate cont.	228	A20

Table 12 I/O Signals, Sorted by Signal Name (Continued)

Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
sdram_enc_cke	EMIU	Encoder SDRAM clock enable	Output	8	Slew rate cont.	186	L20
sdram_enc_clk	EMIU	Encoder SDRAM clock	Bi-Dir	24		185	L19
sdram_enc_cs_	EMIU	Encoder SDRAM chip select	Output	8	Slew rate cont.	187	L16
sdram_enc_data[ 0]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	184	L18
sdram_enc_data[ 1]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	183	L17
sdram_enc_data[ 2]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	182	M20
sdram_enc_data[ 3]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	181	M19
sdram_enc_data[ 4]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	180	M18
sdram_enc_data[ 5]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	179	M16
sdram_enc_data[ 6]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	178	N20
sdram_enc_data[ 7]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	177	N19
sdram_enc_data[ 8]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	176	N18
sdram_enc_data[ 9]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	175	M17
sdram_enc_data[10]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	174	P20
sdram_enc_data[11]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	173	P19
sdram_enc_data[12]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	172	P18
sdram_enc_data[13]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	171	N16
sdram_enc_data[14]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	170	N17
sdram_enc_data[15]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	169	R20
sdram_enc_data[16]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	168	R19
sdram_enc_data[17]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	167	R18
sdram_enc_data[18]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	166	P17
sdram_enc_data[19]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	164	R16
sdram_enc_data[20]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	163	T20
sdram_enc_data[21]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	162	R17
sdram_enc_data[22]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	161	T19
sdram_enc_data[23]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	160	U20
sdram_enc_data[24]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	159	T18
sdram_enc_data[25]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	158	T17
sdram_enc_data[26]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	157	U19
sdram_enc_data[27]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	156	V20
sdram_enc_data[28]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	155	U18
sdram_enc_data[29]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	154	V19
sdram_enc_data[30]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	153	W20
sdram_enc_data[31]	EMIU	Encoder SDRAM data [31:0]	Bi-Dir	8	Slew rate cont.	152	Y20
sdram_enc_dqm[0]	EMIU	Encoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	188	K18

Table 12 I/O Signals, Sorted by Signal Name (Continued)

Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
sdram_enc_dqm[1]	EMIU	Encoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	189	K19
sdram_enc_dqm[2]	EMIU	Encoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	190	K20
sdram_enc_dqm[3]	EMIU	Encoder SDRAM I/O mask [3:0]	Output	8	Slew rate cont.	191	K17
sdram_enc_ras_	EMIU	Encoder SDRAM row address strobe	Output	8	Slew rate cont.	227	C18
sdram_enc_we_	EMIU	Encoder SDRAM write enable	Output	8	Slew rate cont.	231	C17
tck	JTAG	Test clock	Input		Pull-up	63	V1
tdi	JTAG	Test data in	Input		Pull-up	64	T3
tdo	JTAG	Test data out	Output	4	Pull-up/ tri-state	65	R4
tms	JTAG	Test mode select	Input		Pull-up	62	U1
trst_	JTAG	Test reset	Input		Pull-down	61	P4
vbi_data[0]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	210	E19
vbi_data[1]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	209	F18
vbi_data[2]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	208	H16
vbi_data[3]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	207	E20
vbi_data[4]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	206	H17
vbi_data[5]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	205	F19
vbi_data[6]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	204	F20
vbi_data[7]	VIU	VBI data in [7:0]	Bi-Dir	8	Pull-up	203	J16
vbi_data_en	VIU	VBI data enable	Input		Pull-up	211	G17
vou_clk	VOU	Video output clock 27 MHz	Output	8		271	A7
vou_vpo[0]	VOU	Video output data [7:0]	Output	8		280	C8
vou_vpo[1]	VOU	Video output data [7:0]	Output	8		279	D8
vou_vpo[2]	VOU	Video output data [7:0]	Output	8		277	B7
vou_vpo[3]	VOU	Video output data [7:0]	Output	8		276	E9
vou_vpo[4]	VOU	Video output data [7:0]	Output	8		275	A6
vou_vpo[5]	VOU	Video output data [7:0]	Output	8		274	D9
vou_vpo[6]	VOU	Video output data [7:0]	Output	8		273	B8
vou_vpo[7]	VOU	Video output data [7:0]	Output	8		272	C9
vpo[0]	VIU	Video input data [7:0]	Input			259	C11
vpo[1]	VIU	Video input data [7:0]	Input			258	D11
vpo[2]	VIU	Video input data [7:0]	Input			257	A12
vpo[3]	VIU	Video input data [7:0]	Input			256	B12
vpo[4]	VIU	Video input data [7:0]	Input			255	C12
vpo[5]	VIU	Video input data [7:0]	Input			254	E12

Table 12 I/O Signals, Sorted by Signal Name (Continued)

Signal Name	Module	Description	I / O	Drive (ma)	Drive Attributes	Pad No.	Ball Coord.
vpo[6]	VIU	Video input data [7:0]	Input			253	A13
vpo[7]	VIU	Video input data [7:0]	Input			252	B13
ws_dec	AOU	Audio out channel select	Output	8		281	A5
ws_enc	AIU	I <sup>2</sup> S Audio in channel select	Bi-Dir	8	Pull-up	251	C13

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Table 13 Power and Ground Connections

Signal Name	Module	Ball Coord	Pad No.	Drive (ma)	I / O	Description
CORE VDD		D7	287		VDD	1.8V
CORE VDD		E13	245		VDD	1.8V
CORE VDD		E14	241		VDD	1.8V
CORE VDD		E8	283		VDD	1.8V
CORE VDD		F10	P1		VDD	IVDD power ring 1.8V
CORE VDD		F12	P1		VDD	IVDD power ring 1.8V
CORE VDD		F5	14		VDD	1.8V
CORE VDD		H15	P1		VDD	IVDD power ring 1.8V
CORE VDD		H6	P1		VDD	IVDD power ring 1.8V
CORE VDD		K15	P1		VDD	IVDD power ring 1.8V
CORE VDD		L6	P1		VDD	IVDD power ring 1.8V
CORE VDD		M15	P1		VDD	IVDD power ring 1.8V
CORE VDD		N6	P1		VDD	IVDD power ring 1.8V
CORE VDD		P16	165		VDD	1.8V
CORE VDD		P6	P1		VDD	IVDD power ring 1.8V
CORE VDD		R11	P1		VDD	IVDD power ring 1.8V
CORE VDD		R13	P1		VDD	IVDD power ring 1.8V
CORE VDD		R9	P1		VDD	IVDD power ring 1.8V
d1PLL_dvdd	dPLL	E6	295	1	AVDD	PVDD1P PLL 1.8V
d1PLL_dvss	dPLL	C4	294	1	AVSS	PVSS1P PLL Ground
d1PLL_avdd	dPLL	E5	297	1	AVDD	PVDD1P PLL 1.8V
d1PLL_avss	dPLL	B3	296	1	AVSS	PVSS1P PLL Ground
d1PLL_pvdd	dPLL	B2	299	5	PVDD	PVDD5P PLL Pad Ring 1.8V
d1PLL_pvss	dPLL	A2	298	5	PVSS	PVSS5P PLL Pad Ring Ground
d2PLL_dvdd	dPLL	E7	289	1	AVDD	PVDD1P PLL 1.8V
d2PLL_dvss	dPLL	D6	288	1	AVSS	PVSS1P PLL Ground
d2PLL_avdd	dPLL	B4	291	1	AVDD	PVDD1P PLL 1.8V

Table 13 Power and Ground Connections (Continued)

Signal Name	Module	Ball Coord	Pad No.	Drive (ma)	I / O	Description
d2PLL_avss	dPLL	C5	290	1	AVSS	PVSS1P PLL Ground
d2PLL_pvdd	dPLL	D5	293	5	PVDD	PVDD5P PLL Pad Ring 1.8V
d2PLL_pvss	dPLL	A3	292	5	PVSS	PVSS5P PLL Pad Ring Ground
e1PLL_dvdd	ePLL	F17	215	1	AVDD	PVDD1P PLL 1.8V
e1PLL_dvss	ePLL	E18	214	1	AVSS	PVSS1P PLL Ground
e1PLL_avdd	ePLL	D19	217	1	AVDD	PVDD1P PLL 1.8V
e1PLL_avss	ePLL	G16	216	1	AVSS	PVSS1P PLL Ground
e1PLL_pvdd	ePLL	E17	219	5	PVDD	PVDD5P PLL Pad Ring 1.8V
e1PLL_pvss	ePLL	B20	218	5	PVSS	PVSS5P PLL Pad Ring Ground
e2PLL_dvdd	ePLL	F16	221	1	AVDD	PVDD1P PLL 1.8V
e2PLL_dvss	ePLL	D18	220	1	AVSS	PVSS1P PLL Ground
e2PLL_avdd	ePLL	B19	223	1	AVDD	PVDD1P PLL 1.8V
e2PLL_avss	ePLL	C19	222	1	AVSS	PVSS1P PLL Ground
e2PLL_pvdd	ePLL	E16	225	5	PVDD	PVDD5P PLL Pad Ring 1.8V
e2PLL_pvss	ePLL	D17	224	5	PVSS	PVSS5P PLL Pad Ring Ground
I/O VDD		F11	P4		VDD	OVDD3 power ring 3.3V
I/O VDD		F13	P4		VDD	OVDD3 power ring 3.3V
I/O VDD		F15	P5		VDD	PVDD power ring 3.3V
I/O VDD		F6	P5		VDD	PVDD power ring 3.3V
I/O VDD		F8	P4		VDD	OVDD3 power ring 3.3V
I/O VDD		F9	P4		VDD	OVDD3 power ring 3.3V
I/O VDD		J15	P3		VDD	OVDDM power ring 3.3V
I/O VDD		J6	P2		VDD	OVDDA power ring 3.3V
I/O VDD		K6	P2		VDD	OVDDA power ring 3.3V
I/O VDD		L15	P3		VDD	OVDDM power ring 3.3V
I/O VDD		M6	P2		VDD	OVDDA power ring 3.3V
I/O VDD		N15	P3		VDD	OVDDM power ring 3.3V
I/O VDD		R10	P3		VDD	OVDDM power ring 3.3V



Table 13 Power and Ground Connections (Continued)

Signal Name	Module	Ball Coord	Pad No.	Drive (ma)	I / O	Description
I/O VDD		R12	P3		VDD	OVDDM power ring 3.3V
I/O VDD		R15	P5		VDD	PVDD power ring 3.3V
I/O VDD		R6	P5		VDD	PVDD power ring 3.3V
I/O VDD		R8	P3		VDD	OVDDM power ring 3.3V
I/O VDD		T13	134		VDD	3.3V
I/O VDD		T14	141		VDD	3.3V
mPLL_dvdd	mPLL	V2	71	1	AVDD	PVDD1P PLL 1.8V
mPLL_dvss	mPLL	U3	70	1	AVSS	PVSS1P PLL Ground
mPLL_avdd	mPLL	W2	73	1	AVDD	PVDD1P PLL 1.8V
mPLL_avss	mPLL	R5	72	1	AVSS	PVSS1P PLL Ground
mPLL_pvdd	mPLL	T5	75	5	PVDD	PVDD5P PLL Pad Ring 1.8V
mPLL_pvss	mPLL	U4	74	5	PVSS	PVSS5P PLL Pad Ring Ground
VSS		H10			VSS	Ground / Thermal
VSS		H11			VSS	Ground / Thermal
VSS		H12			VSS	Ground / Thermal
VSS		H13			VSS	Ground / Thermal
VSS		H8			VSS	Ground / Thermal
VSS		H9			VSS	Ground / Thermal
VSS		J10			VSS	Ground / Thermal
VSS		J11			VSS	Ground / Thermal
VSS		J12			VSS	Ground / Thermal
VSS		J13			VSS	Ground / Thermal
VSS		J8			VSS	Ground / Thermal
VSS		J9			VSS	Ground / Thermal
VSS		K10			VSS	Ground / Thermal
VSS		K11			VSS	Ground / Thermal
VSS		K12			VSS	Ground / Thermal
VSS		K13			VSS	Ground / Thermal

Table 13 Power and Ground Connections (Continued)

Signal Name	Module	Ball Coord	Pad No.	Drive (ma)	I / O	Description
VSS		K8			VSS	Ground / Thermal
VSS		K9			VSS	Ground / Thermal
VSS		L10			VSS	Ground / Thermal
VSS		L11			VSS	Ground / Thermal
VSS		L12			VSS	Ground / Thermal
VSS		L13			VSS	Ground / Thermal
VSS		L8			VSS	Ground / Thermal
VSS		L9			VSS	Ground / Thermal
VSS		M10			VSS	Ground / Thermal
VSS		M11			VSS	Ground / Thermal
VSS		M12			VSS	Ground / Thermal
VSS		M13			VSS	Ground / Thermal
VSS		M8			VSS	Ground / Thermal
VSS		M9			VSS	Ground / Thermal
VSS		N10			VSS	Ground / Thermal
VSS		N11			VSS	Ground / Thermal
VSS		N12			VSS	Ground / Thermal
VSS		N13			VSS	Ground / Thermal
VSS		N8			VSS	Ground / Thermal
VSS		N9			VSS	Ground / Thermal

**Table 14 Signal Multiplexing Scheme<sup>1</sup>**

Signal Name	Signal Name 2	Module	Module 2	Pad No.	Ball Coord.
cdo[0]	rom_addr[12]	Mux	ROM	239	A16
cdo[1]	rom_addr[13]	Mux	ROM	238	D15
cdo[2]	rom_addr[14]	Mux	ROM	237	B16
cdo[3]	rom_addr[15]	Mux	ROM	236	A17
cdo[4]	rom_addr[16]	Mux	ROM	235	C16
cdo[5]	rom_addr[17]	Mux	ROM	234	D16
cdo[6]	rom_addr[18]	Mux	ROM	233	B17
cdo[7]	rom_addr[19]	Mux	ROM	232	A18
cdo_clk	rom_addr[11]	Mux	ROM	240	D14
cdo_sop	rom_addr[10]	Mux	ROM	242	C15
cdo_valid	rom_addr[9]	Mux	ROM	246	D13
fifo_level	rom_addr[8]	Mux	ROM	247	C14
sck_dec	rom_we_	AOU	ROM	282	B6
sd0_dec	rom_addr[21]	AOU	ROM	284	B5
sd1_dec	rom_addr[20]	AOU	ROM	285	C6
vbi_data[0]	ejtag_pcst3[0]	VIU	EJTAG	210	E19
vbi_data[1]	ejtag_pcst3[1]	VIU	EJTAG	209	F18
vbi_data[2]	ejtag_pcst3[2]	VIU	EJTAG	208	H16
vbi_data[3]	ejtag_pcst4[0]	VIU	EJTAG	207	E20
vbi_data[4]	ejtag_pcst4[1]	VIU	EJTAG	206	H17
vbi_data[5]	ejtag_pcst4[2]	VIU	EJTAG	205	F19
vou_vpo[0]	rom_addr[0]	VOU	ROM	280	C8
vou_vpo[1]	rom_addr[1]	VOU	ROM	279	D8
vou_vpo[2]	rom_addr[2]	VOU	ROM	277	B7
vou_vpo[3]	rom_addr[3]	VOU	ROM	276	E9
vou_vpo[4]	rom_addr[4]	VOU	ROM	275	A6
vou_vpo[5]	rom_addr[5]	VOU	ROM	274	D9
vou_vpo[6]	rom_addr[6]	VOU	ROM	273	B8
vou_vpo[7]	rom_addr[7]	VOU	ROM	272	C9
ws_dec	rom_oe_	AOU	ROM	281	A5

1. Except host interface signals. See [Table 16 on page 144](#), [Table 17 on page 145](#).

Table 15 Board-Level Requirements for Unused Input Pins <sup>1</sup>

Pad No.	Ball Coord.	Signal Name	Drive Attributes	External Connection (if pin is not used)
1	D4	cdi[7]	Pull-up	OK to leave floating (no-connect)
2	C3	cdi[6]	Pull-up	OK to leave floating (no-connect)
3	B1	cdi[5]	Pull-up	OK to leave floating (no-connect)
4	C2	cdi[4]	Pull-up	OK to leave floating (no-connect)
5	C1	cdi[3]	Pull-up	OK to leave floating (no-connect)
6	D2	cdi[2]	Pull-up	OK to leave floating (no-connect)
7	D1	cdi[1]	Pull-up	OK to leave floating (no-connect)
8	D3	cdi[0]	Pull-up	OK to leave floating (no-connect)
9	E4	cdi_valid	Pull-up	OK to leave floating (no-connect)
10	F4	cdi_clk	Pull-up	OK to leave floating (no-connect)
61	P4	trst_	Pull-down	As required by emulator
62	U1	tms	Pull-up	As required by emulator
63	V1	tck	Pull-up	As required by emulator
64	T3	tdi	Pull-up	As required by emulator
68	W1	PLL_clk		External pull-down
69	T4	PLL_bypass		External pull-down
203	J16	vbi_data[7]	Pull-up	OK to leave floating (no-connect)
204	F20	vbi_data[6]	Pull-up	OK to leave floating (no-connect)
205	F19	vbi_data[5]	Pull-up	OK to leave floating (no-connect)
206	H17	vbi_data[4]	Pull-up	OK to leave floating (no-connect)
207	E20	vbi_data[3]	Pull-up	OK to leave floating (no-connect)
208	H16	vbi_data[2]	Pull-up	OK to leave floating (no-connect)
209	F18	vbi_data[1]	Pull-up	OK to leave floating (no-connect)
210	E19	vbi_data[0]	Pull-up	OK to leave floating (no-connect)
211	G17	vbi_data_en	Pull-up	OK to leave floating (no-connect)
213	C20	PLL_amclk_enc		Tie to ground
226	E15	clk_vbi	Pull-up	OK to leave floating (no-connect)
243	B15	excd_clk	Pull-down	OK to leave floating (no-connect)
244	A15	excd_rd	Pull-up	OK to leave floating (no-connect)
248	B14	sd0_enc	Pull-up	OK to leave floating (no-connect)
249	A14	sd1_enc	Pull-up	OK to leave floating (no-connect)
252	B13	vpo[7]		Tie to ground
253	A13	vpo[6]		Tie to ground
254	E12	vpo[5]		Tie to ground
255	C12	vpo[4]		Tie to ground

**Table 15 Board-Level Requirements for Unused Input Pins <sup>1</sup> (Continued)**

Pad No.	Ball Coord.	Signal Name	Drive Attributes	External Connection (if pin is not used)
256	B12	vpo[3]		Tie to ground
257	A12	vpo[2]		Tie to ground
258	D11	vpo[1]		Tie to ground
259	C11	vpo[0]		Tie to ground
260	A11	clk_27		Tie to ground
261	E11	pcr_clk		Tie to ground
262	B11	reset_		Tie to Vcc
300	A1	PLL_amclk_dec		Tie to ground

1. Except host interface signals. See [Table 16 on page 144](#), [Table 17 on page 145](#).

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Table 16 Host Interface, Address/Data Bus

Host Interface Mode						Pad No.	Ball Coord.	What to do with Unused Pin
PCI	Dir.	Motorola	Dir.	Intel	Dir.			
pci_ad[0]	I/O	host_hiu_data[0]	I/O	intel_ad[0]	I/O	60	T2	Tie to ground
pci_ad[1]	I/O	host_hiu_data[1]	I/O	intel_ad[1]	I/O	59	N5	Tie to ground
pci_ad[2]	I/O	host_hiu_data[2]	I/O	intel_ad[2]	I/O	58	R3	Tie to ground
pci_ad[3]	I/O	host_hiu_data[3]	I/O	intel_ad[3]	I/O	57	N4	Tie to ground
pci_ad[4]	I/O	host_hiu_data[4]	I/O	intel_ad[4]	I/O	56	T1	Tie to ground
pci_ad[5]	I/O	host_hiu_data[5]	I/O	intel_ad[5]	I/O	55	R2	Tie to ground
pci_ad[6]	I/O	host_hiu_data[6]	I/O	intel_ad[6]	I/O	54	R1	Tie to ground
pci_ad[7]	I/O	host_hiu_data[7]	I/O	intel_ad[7]	I/O	53	M5	Tie to ground
pci_ad[8]	I/O	host_hiu_data[8]	I/O	intel_ad[8]	I/O	51	P2	Tie to ground
pci_ad[9]	I/O	host_hiu_data[9]	I/O	intel_ad[9]	I/O	50	P1	Tie to ground
pci_ad[10]	I/O	host_hiu_data[10]	I/O	intel_ad[10]	I/O	49	M4	Tie to ground
pci_ad[11]	I/O	host_hiu_data[11]	I/O	intel_ad[11]	I/O	48	N3	Tie to ground
pci_ad[12]	I/O	host_hiu_data[12]	I/O	intel_ad[12]	I/O	47	N2	Tie to ground
pci_ad[13]	I/O	host_hiu_data[13]	I/O	intel_ad[13]	I/O	46	N1	Tie to ground
pci_ad[14]	I/O	host_hiu_data[14]	I/O	intel_ad[14]	I/O	45	L5	Tie to ground
pci_ad[15]	I/O	host_hiu_data[15]	I/O	intel_ad[15]	I/O	44	M3	Tie to ground
pci_ad[16]	I/O	host_hiu_addr[0]	In			43	M2	Tie to ground
pci_ad[17]	I/O	host_hiu_addr[1]	In			31	J2	Tie to ground
pci_ad[18]	I/O	host_hiu_addr[2]	In			30	J3	Tie to ground
pci_ad[19]	I/O	host_hiu_addr[3]	In			29	J5	Tie to ground
pci_ad[20]	I/O	host_hiu_addr[4]	In			28	H1	Tie to ground
pci_ad[21]	I/O	host_hiu_addr[5]	In			27	H2	Tie to ground
pci_ad[22]	I/O	host_hiu_addr[6]	In			26	H3	Tie to ground
pci_ad[23]	I/O	host_hiu_addr[7]	In			25	J4	Tie to ground
pci_ad[24]	I/O	host_hiu_addr[8]	In			24	G1	Tie to ground
pci_ad[25]	I/O	host_hiu_addr[9]	In			21	H4	Tie to ground
pci_ad[26]	I/O	host_hiu_addr[10]	In			20	H5	Tie to ground
pci_ad[27]	I/O	host_hiu_addr[11]	In			19	F1	Tie to ground
pci_ad[28]	I/O	host_hiu_addr[12]	In			18	F2	Tie to ground
pci_ad[29]	I/O	host_hiu_addr[13]	In			17	F3	Tie to ground
pci_ad[30]	I/O	host_hiu_addr[14]	In			16	G4	Tie to ground
pci_ad[31]	I/O	host_hiu_addr[15]	In			15	G5	Tie to ground

Table 17 Host Interface Bus Control Signals <sup>1</sup>

Host Interface Mode									Pad No.	Ball Coord.
PCI			Motorola			Intel				
Signal	Dir.	Tie to	Signal	Dir.	Tie to	Signal	Dir.	Tie to		
pci_cbe_[0]	I/O	Vcc	host_hiu_as_	In	Vcc	intel_as_ale_	In	Vcc	52	P3
pci_cbe_[1]	I/O	Vcc	host_hiu_cs_	In	Vcc	intel_cs_	In	Vcc	42	M1
pci_cbe_[2]	I/O	Vcc	host_hiu_rw_	In	Vcc	intel_wr_	Int	Vcc	32	J1
pci_cbe_[3]	I/O	Vcc	hiu_host_cdo_req_	Out	-	intel_cdo_req_	Out	-	22	G3
pci_clk	In	gnd			gnd			gnd	12	E2
pci_devsel_	I/O	Vcc	host_hiu_cdi_ack_	In	Vcc	intel_cdi_ack_	In	Vcc	36	K1
pci_frame_	I/O	Vcc			Vcc	intel_rd_	In	Vcc	33	K4
pci_gnt_	In	Vcc			Vcc			Vcc	38	L3
pci_idsel	In	gnd			gnd			gnd	23	G2
pci_inta_	Out	Vcc	int_	Out	-	int_	Out	-	11	E3
pci_irdy_	I/O	Vcc			Vcc			Vcc	34	K3
pci_par	I/O	gnd			gnd			gnd	41	L4
pci_perr_	I/O	Vcc	host_hiu_cdo_ack_	In	Vcc	intel_cdo_ack_	In	Vcc	39	L2
pci_req_	I/O	Vcc			Vcc			Vcc	13	E1
pci_serr_	I/O	Vcc	hiu_host_dtack_	Out	-	intel_dtack_	Out	-	40	L1
pci_stop_	I/O	Vcc	hiu_host_cdi_req_	Out	-	intel_cdi_req_	Out	-	37	K5
pci_trdy_	I/O	Vcc			Vcc			Vcc	35	K2

## 1. In PCI mode:

Normally, all pins are used.

However,

Unused input-only pins (if any) must be tied inactive (tied to ground if active high, tied to Vcc if active low).

Unused I/O pins (if any) may be tied inactive or left floating (pins are tri-state)

**In Motorola or Intel mode:**

Unused input-only pins must be tied inactive (tied to ground if active high, tied to Vcc if active low).

Unused outputs are left floating.

Unused PCI-only, input-only pins must be tied inactive (for example, pci\_clk must be tied to ground).

Unused PCI-only I/O pins may be tied inactive or left floating (e.g., pci\_irdy\_ may be tied to Vcc, pci\_par\_ may be tied to ground).

**In no-host mode:**

that is, when the chip is booted from ROM and is not connected to an external host,

The rom\_data pins must be set to boot from ROM (see Table 5 on page 49), and

The unused pins of the host interface must be set as shown in Table 16 on page 144 and in the Motorola or Intel column above.

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## CHAPTER 10

*Electrical Characteristics*

This chapter summarizes the following information about the VW2010 chip's electrical properties:

- Maximum input power and environmental ratings
- DC Characteristics
- AC timing diagrams and parameters

*Note:* The following information is preliminary and subject to change based on simulation data and actual measurements for the final version of this document.

## Absolute Maximum Ratings

The following table shows the maximum ratings of the VW2010. Exposure beyond the settings in the following table will result in unpredictable behavior.

**Table 18 Maximum Ratings**

Parameter	Value
I/O supply voltage ( $V_{DD}$ )	$3.3V \pm 10\%$
Core voltage ( $V_{CORE}$ )	$1.8V \pm 10\%$
PLL analog supply voltage	$3.3V \pm 10\%$
PLL digital supply voltage	$3.3V \pm 10\%$
Storage temperature range	-55 to 120°C

**Table 18 Maximum Ratings (Continued)**

Operating temperature range	0 to 75°C
Soldering reflow temperature	200°C for 5 seconds
Power Consumption - Encoder only	0.8 W
Power Consumption - Encoder + Decoder	1.6 W

b

**Power-On Sequence**

The proper power-on sequence is as follows:

- Power on the core voltage Core voltage ( $V_{CORE}$ ), 1.8 VDC first.
- Then power on the I/O supply voltage ( $V_{DD}$ ), 3.3 VDC.
- The delay between  $V_{CORE}$  and  $V_{DD}$  should be about a millisecond.

**Power-Off Sequence**

The proper power-off sequence is as follows:

- Power off the I/O supply voltage ( $V_{DD}$ ), 3.3 VDC first.
- Then power off the core voltage Core voltage ( $V_{CORE}$ ), 1.8 VDC.
- The delay between  $V_{DD}$  and  $V_{CORE}$  should be about a millisecond.

## DC Characteristics

The following table shows the DC limits of the VW2010.

*Note:* The parameters and limits are not 100% tested; they are guaranteed by design characterization.

**Table 19 DC Characteristics**

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$I_I$	Leakage current	Hi-Z output driven to 0.0V and 5.25V	(-10)		(10)	iA
$V_{OH}$	High-level output voltage	$V_{DD}=3.3V, I_{OH}=-2ma$	2.4	-	-	V
$V_{OL}$	Low-level output voltage	$V_{DD}=\text{MIN } I_{OL}=2ma$	-	-	0.4	V
$V_{IH}$	High-level input voltage	$V_{DD}=\text{min}$	2.4	-	-	V
$V_{IL}$	Low-level input voltage	$V_{DD}=\text{max}$	-	-	0.8	V

## AC Timing Characteristics

The following sections specify the AC timing characteristics of the VW2010; see:

- “HIU-Motorola Mode” on page 149
- “HIU-Intel Mode” on page 151
- “HIU-PCI Mode” on page 153
- “Video Input” on page 155
- “Video Output” on page 156
- “VBI Input” on page 156
- “Audio Input” on page 157
- “Audio Output” on page 158
- “Compressed Data Input (CDI)” on page 158
- “Compressed Data Output (CDO)” on page 159
- “Decoder SDRAM Interface (1M16)” on page 166
- “Host DMA Out” on page 161
- “Encoder SDRAM Interface (2M32)” on page 162
- “Decoder SDRAM Interface (1M16)” on page 166
- “ROM Interface” on page 168
- “ICI Interface” on page 169
- “PLL Interface” on page 170
- “JTAG / EJTAG Interface” on page 171

## HIU-Motorola Mode

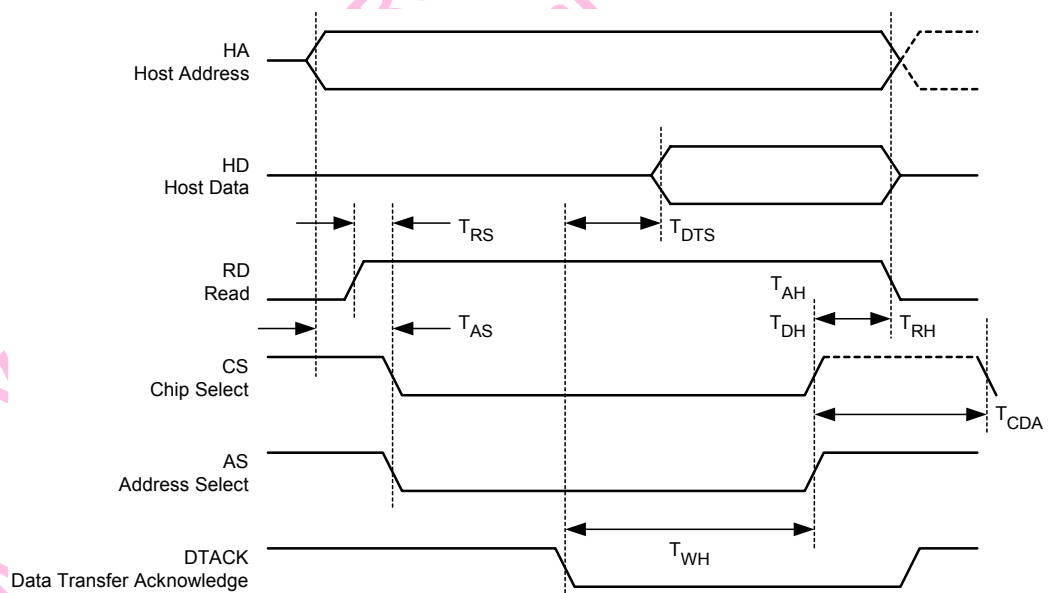
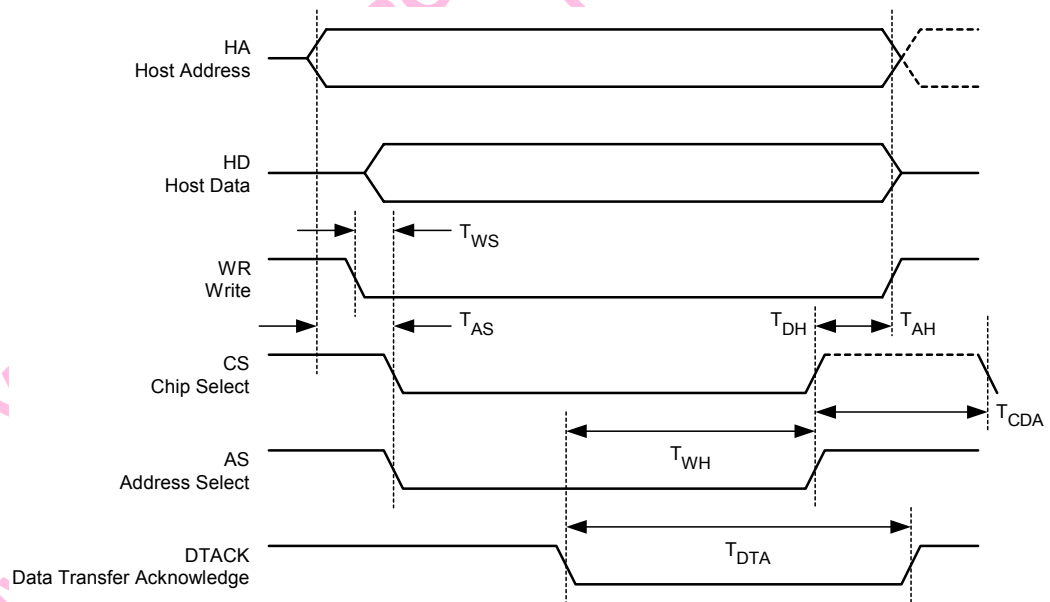


Figure 34 Host Read Timing, HIU-Motorola Mode

**Table 20 Host Read Timing Parameters, HIU-Motorola Mode**

Symbol	Description	Min	Typ	Max	Unit
$T_{AS}$	Address setup time before Chip Select is asserted	2			ns
$T_{AH}$	Address hold time after Chip Select is deasserted	5			ns
$T_{RS}$	Read/write setup time before Chip Select assertion	2			ns
$T_{RH}$	Read/write hold time after Chip Select is deasserted	2			ns
$T_{DTS}$	Dtack asserted to data valid			5	ns
$T_{Dh}$	Chip Select deasserted to Data Invalid	5			ns
$T_{CDA}$	Chip Select deassertion to the next Chip Select assertion	33			ns

**Figure 35 Host Write Timing, HIU-Motorola Mode**

**Table 21 Host Write Timing Parameters, HIU Motorola-Mode**

Symbol	Description	Min	Typ	Max	Unit
$T_{AS}$	Address setup time before Chip Select is asserted	2			ns
$T_{AH}$	Address hold time after Chip Select is deasserted	5			ns
$T_{CDA}$	Time between Chip Select deassertion until the next Chip Select assertion	33			ns
$T_{WS}$	Read/write setup time before Chip Select assertion	2			ns
$T_{WH}$	Dtack assert hold time before Chip Select is deasserted	45			ns
$T_{DH}$	Data hold time after Chip Select is deasserted	1			ns
$T_{DTA}$	Dtack assertion time	66			ns

For additional details, see a Motorola specification such as a 68K series manual.

### HIU-Intel Mode

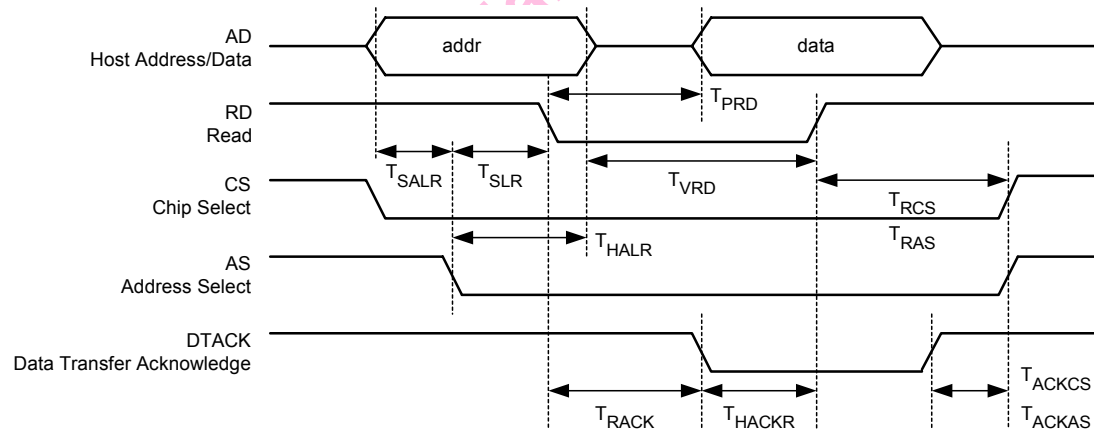
**Figure 36 Host Read Timing, HIU-Intel Mode**

Table 22 Host Read Timing Parameters, HIU-Intel Mode

Symbol	Description	Min	Typ	Max	Unit
$T_{SALR}$	Address set up time	20			ns
$T_{SLR}$	Read set up time	20			ns
$T_{HALR}$	Address hold time	20			ns
$T_{PRD}$	Data delay time		60	120	ns
$T_{VRD}$	Read pulse width		$T_{PRD} + 10$		ns
$T_{RACK}$	DTACK delay from Read		60	120	ns
$T_{HACKR}$	Data hold time		10		ns
$T_{RAS}$	AS delay from Read		20		ns
$T_{RCS}$	CS delay from Read		20		ns
$T_{ACKAS}$	AS delay from DTACK	5			ns
$T_{ACKCS}$	CS delay from DTACK	5			ns

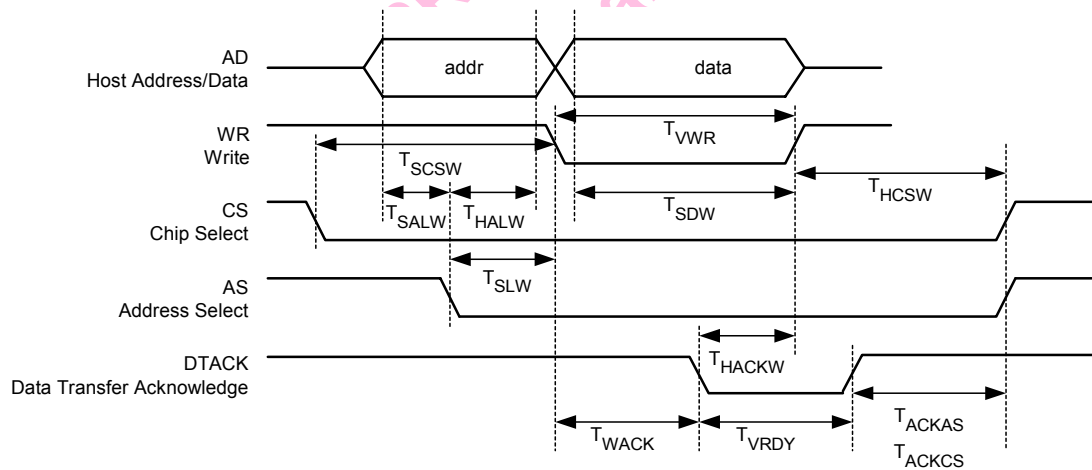


Figure 37 Host Write Timing, HIU-Intel Mode

Table 23 Host Write Timing Parameters, HIU Intel-Mode

Symbol	Description	Min	Typ	Max	Unit
$T_{SALW}$	Address set up time	20			ns
$T_{SLW}$	Write set up time from AS	20			ns
$T_{HALW}$	Address hold time	20			ns
$T_{SCSW}$	Write set up time from CS	40			ns
$T_{HCSW}$	CS hold time		20		ns
$T_{SDW}$	Data valid time		$T_{WACK} + 10$		ns
$T_{VWR}$	Write pulse width		$T_{WACK} + 10$		ns
$T_{VRDY}$	DTACK duration		60		ns
$T_{WACK}$	DTACK delay from Write		60	120	ns
$T_{HACKW}$	Data hold time		10		ns
$T_{ACKAS}$	AS delay from DTACK	5			ns
$T_{ACKCS}$	CS delay from DTACK	5			ns

## HIU-PCI Mode

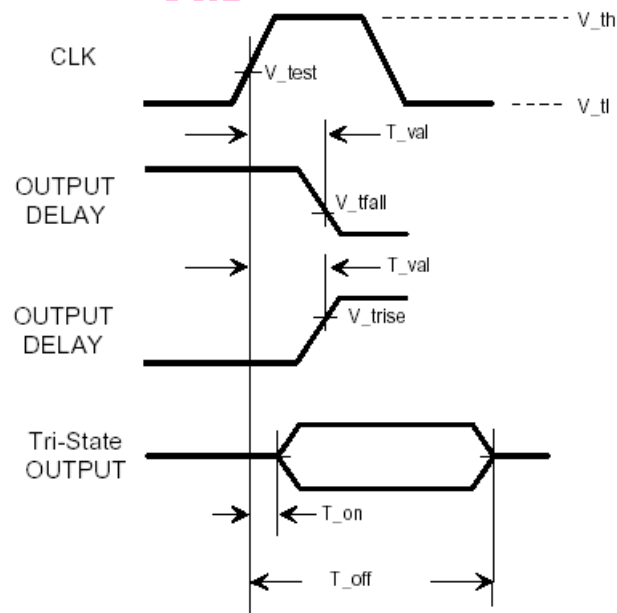


Figure 38 Host Read Timing, HIU-PCI Mode

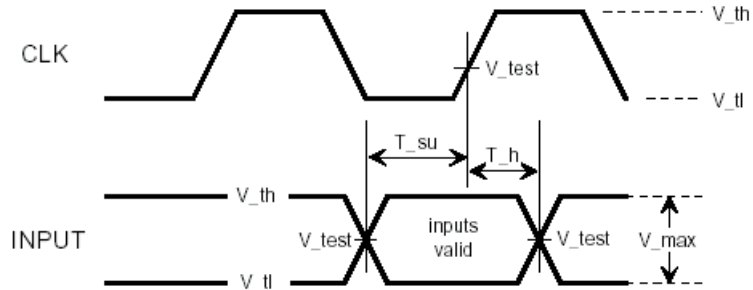


Figure 39 Host Write Timing, HIU-PCI Mode

Table 24 Timing Parameters, HIU-PCI Mode

Symbol	Parameter	66 MHz		33 MHz <sup>7</sup>		Units
		Min	Max	Min	Max	
T <sub>val</sub>	CLK to Signal Valid Delay - bus-based signals	2	6	2	11	ns
T <sub>val(ptp)</sub>	CLK to Signal Valid Delay - point to point signals	2	6	2	12	ns
T <sub>on</sub>	Float to Active Delay	2		2		ns
T <sub>off</sub>	Active to Float Delay		14		28	ns
T <sub>su</sub>	Input Setup Time to CLK - bus-based signals	3		7		ns
T <sub>su(ptp)</sub>	Input Setup Time to CLK - point to point signals	5		10,12		ns
T <sub>h</sub>	Input Hold Time from CLK	0		0		ns
T <sub>rst</sub>	Reset Active Time after power stable	1		1		ms

**PCI Read Transaction**

For timing diagrams and descriptions, see the PCI Local Bus Specification, version 2.2, from PCISIG.

**PCI Write Transaction**

For timing diagrams and descriptions, see the PCI Local Bus Specification, version 2.2, from PCISIG.



## Video Input

Note: Not 100% tested; guaranteed by design characterization

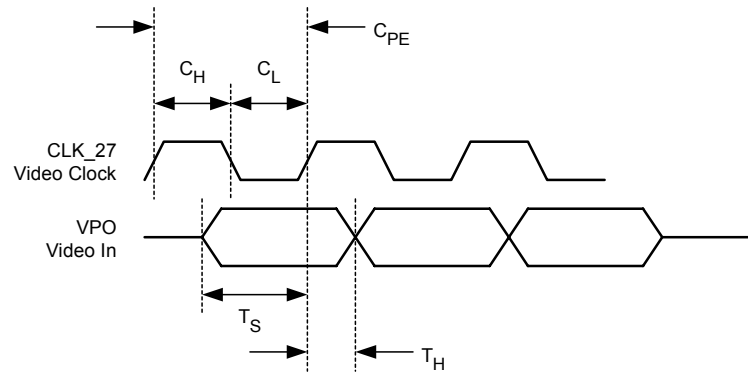


Figure 40 Video Input Timing

Table 25 Video Input Timing Parameters

Symbol	Description	Min	Typ	Max	Unit
$C_{PE}$	27 MHz clock period	18.5			ns
$C_H$	High time	7.0			ns
$C_L$	Low time	7.0			ns
$T_S$	Video data setup time	5.0			ns
$T_H$	Video data hold time	2.0			ns

For additional details, see the ITU-R.BT.656 specification.

## Video Output

Note: Not 100% tested; guaranteed by design characterization

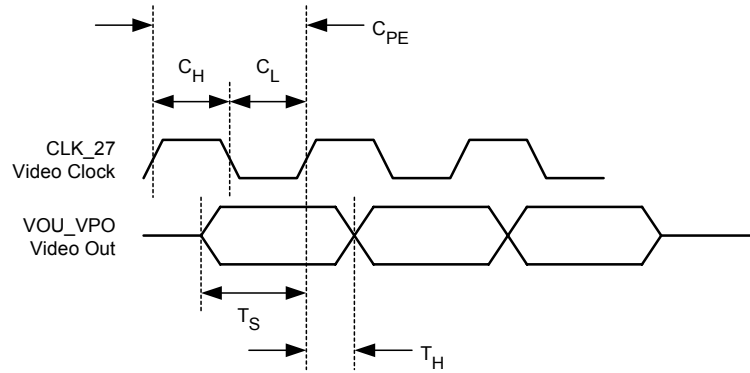


Figure 41 Video Output Timing

Table 26 Video Output Timing Parameters

Symbol	Description	Min	Typ	Max	Unit
$C_{PE}$	27 MHz clock period	18.5			ns
$C_H$	High time	7.0			ns
$C_L$	Low time	7.0			ns
$T_S$	Video data setup time	5.0			ns
$T_H$	Video data hold time	2.0			ns

For additional details, see the ITU-R.BT.656 specification.

## VBI Input

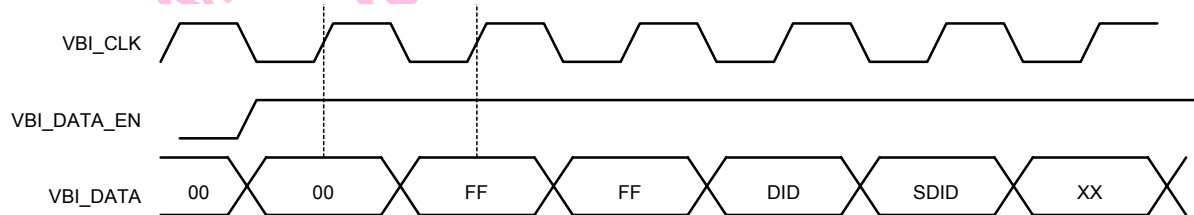


Figure 42 VBI Input Timing

Table 27 VBI Input Timing Parameters

to be added

For additional details see the data sheet for a device such as the Philips Semiconductors SAA7114H PAL/NTSC/SECAM video decoder.

### Audio Input

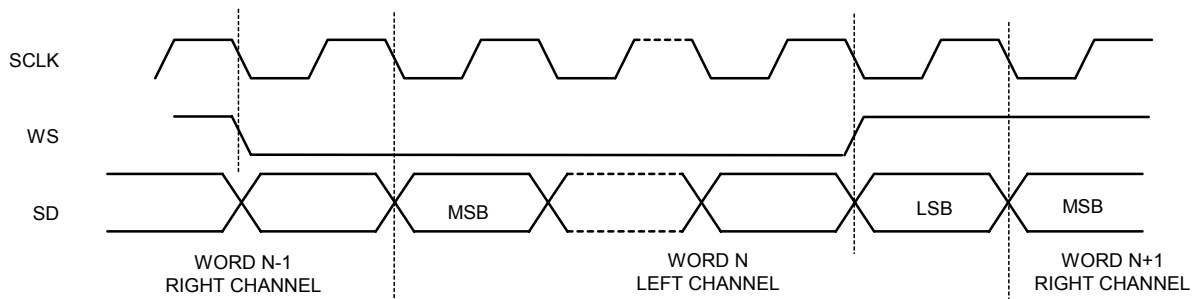


Figure 43 Basic I<sup>2</sup>S Bus Timing

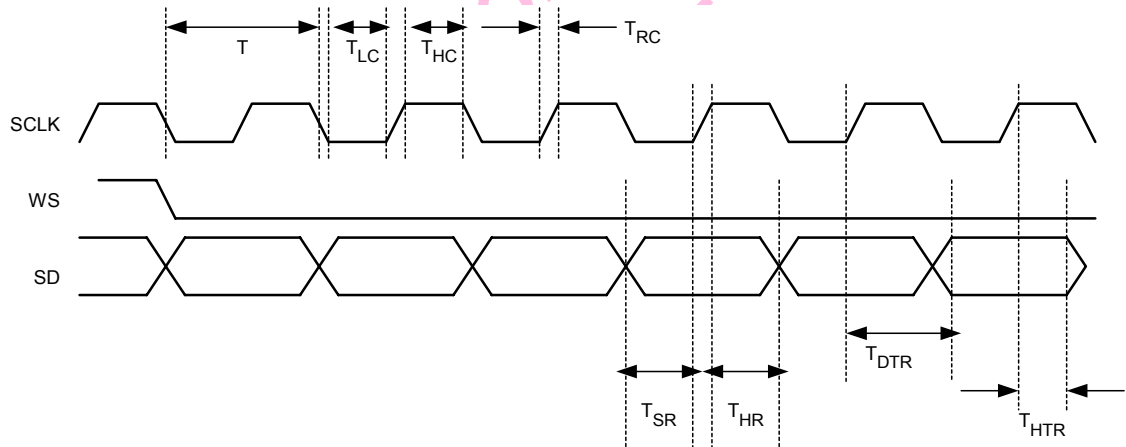


Figure 44 I<sup>2</sup>S Transmitter and Receiver Timing

**Table 28 I<sup>2</sup>S Timing Parameters**

Symbol	Parameter	Value
T	Clock period	
T <sub>tr</sub>	Minimum clock period for transmitter	T > T <sub>tr</sub>
T <sub>r</sub>	Minimum clock period for receiver	T > T <sub>r</sub>
t <sub>LC</sub>		
t <sub>HC</sub>		
t <sub>RC</sub>		
t <sub>sr</sub>		
t <sub>hr</sub>		
t <sub>htr</sub>		
t <sub>dtr</sub>		

For additional details see the Philips I<sup>2</sup>S bus specification.

## Audio Output

### I<sup>2</sup>S Bus Timing

See “Audio Input” on page 157.

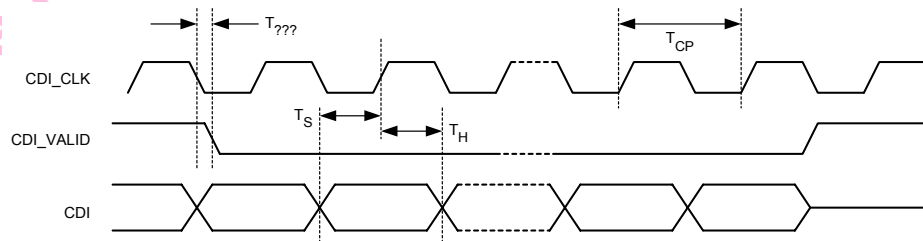
### S/P-DIF Timing

to be added -- need info

**Figure 45 S/P-DIF Audio Output Timing****Table 29 S/P-DIF Audio Output Timing Parameters**

to be added

## Compressed Data Input (CDI)

**Figure 46 Compressed Data Input Timing**

*Note:* CDI\_VALID is from falling edge of CDI\_CLK.

**Table 30 Video Demux / CDI Timing Parameters**

Symbol	Description	Min	Typ	Max	Unit
$C_{PF}$	CDIO_CLK period	18.5			ns
$T_S$	Data setup time	3			ns
$T_H$	Data hold time	5			ns

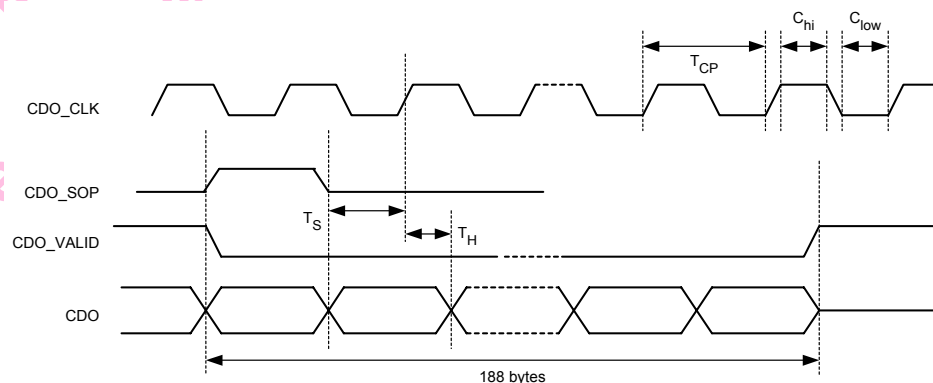
**CDI via Host Interface**

The external host can write compressed data (CDI) to the VW2010 using the host interface protocol as follows:

1. The VW2010 asserts CDI\_REQ (indicates the VW2010 is ready to receive compressed data).
2. The external host asserts CDI\_ACK and drives data on HIU\_DATA[15:0] (the external host is ready to write data on the HIU\_DATA bus).
3. The VW2010 asserts DTACK when it has read the data on HIU\_DATA[15:0].
4. The external host deasserts CDI\_ACK and at the same time stops driving the HIU\_DATA bus (terminates the write cycle).
5. The VW2010 deasserts DTACK.
6. The VW2010 deasserts CDI\_REQ.

*Note:* This signal can be kept active until all data transfer cycles are completed.

7. Repeat 1-6 for each data transfer.

**Compressed Data Output (CDO)****CDO via CDO Port****Figure 47 Video Mux / Compressed Data Output Timing**

*Note:* CDO\_VALID is from falling edge of CDO\_CLK.

**Table 31 Video Mux / CDO Timing Parameters**

Symbol	Description	Min	Typ	Max	Unit
$C_{PF}$	CDO_CLK period	18.5			ns
$T_S$	Data setup time	3			ns
$T_H$	Data hold time	5			ns

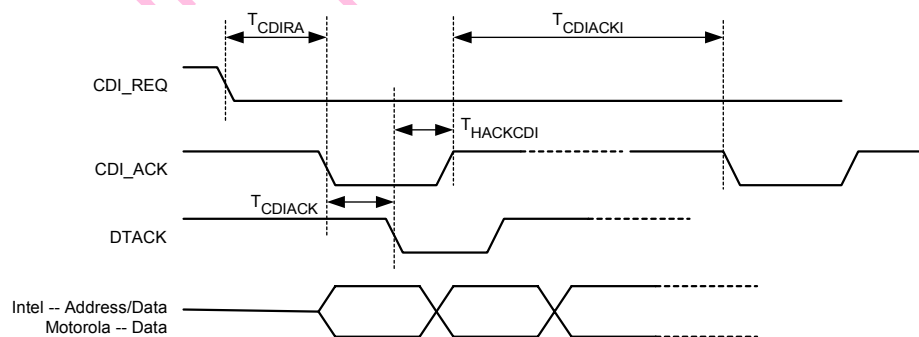
**CDO via Host Interface**

The external host can read compressed data (CDO) from the VW2010 using the host interface protocol as follows:

1. The VW2010 asserts CDO\_REQ (indicates the VW2010 is ready to send compressed data).
2. The external host asserts CDO\_ACK (the external host is ready to read data on the HIU\_DATA bus).
3. The VW2010 asserts DTACK and writes data on HIU\_DATA[15:0].
4. The external host deasserts CDO\_ACK (terminates the read cycle).
5. The VW2010 de-asserts DTACK.
6. The VW2010 de-asserts CDO\_REQ.

*Note:* This signal can be kept active until all data transfer cycles are completed.

7. Repeat 1-6 for each data transfer.

**Host DMA In****Figure 48 DMA-In Timing**

1. The VW2010 asserts CDI\_REQ (indicates the VW2010 is ready to receive data).
2. The external host asserts CDI\_ACK and drives data on HIU\_DATA[15:0] (the external host is ready to write data on the HIU\_DATA bus).
3. The VW2010 asserts DTACK when it has read the data on HIU\_DATA[15:0].
4. The external host deasserts CDI\_ACK and at the same time stops driving the

HIU\_DATA bus (terminates the write cycle).

5. The VW2010 de-asserts DTACK.
6. The VW2010 de-asserts CDI\_REQ.

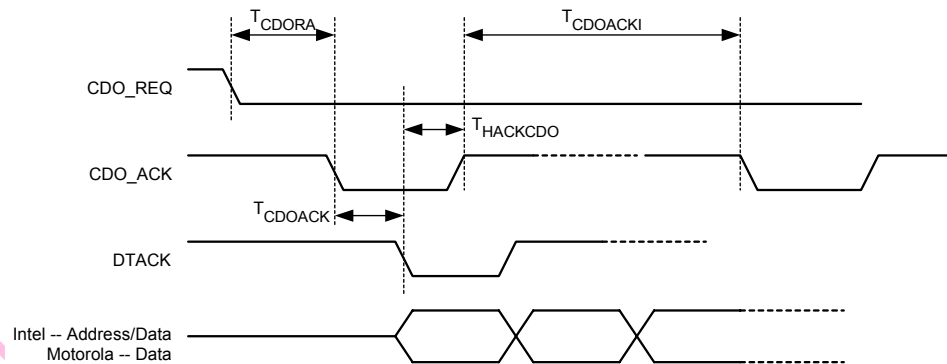
*Note:* This signal can be kept active until all data transfer cycles are completed.

7. Repeat 1-6 for each data transfer.

**Table 32 DMA-In Timing Parameters**

Symbol	Description	Min	Typ	Max	Unit
$T_{CDIRA}$	ACK delay from REQ	10			ns
$T_{CDIACKI}$	Idle time between successive ACK	70			ns
$T_{HACKCDI}$	ACK hold time	10			ns
$T_{CDIACK}$	DTACK delay from ACK		60	120	ns

## Host DMA Out



**Figure 49 DMA-Out Timing**

1. The VW2010 asserts CDO\_REQ (indicates the VW2010 is ready to send data).
2. The external host asserts CDO\_ACK (the external host is ready to read data on the HIU\_DATA bus).
3. The VW2010 asserts DTACK and writes data on HIU\_DATA[15:0].
4. The external host deasserts CDO\_ACK (terminates the read cycle).
5. The VW2010 de-asserts DTACK.
6. The VW2010 de-asserts CDO\_REQ.

*Note:* This signal can be kept active until all data transfer cycles are completed.

7. Repeat 1-6 for each data transfer.

**Table 33 DMA-Out Timing Parameters**

Symbol	Description	Min	Typ	Max	Unit
$T_{CDORA}$	ACK delay from REQ	10			ns
$T_{CDOACKI}$	Idle time between successive ACK	70			ns
$T_{HACKCDO}$	ACK hold time	10			ns
$T_{CDOACK}$	DTACK delay from ACK		60	120	ns

**PCI DMA**

PCI DMA In and PCI DMA Out are performed in accordance with the PCI Specifications.

**Encoder SDRAM Interface (2M32)**

*Note:* In most applications, the same SDRAM is also used for the decoder.

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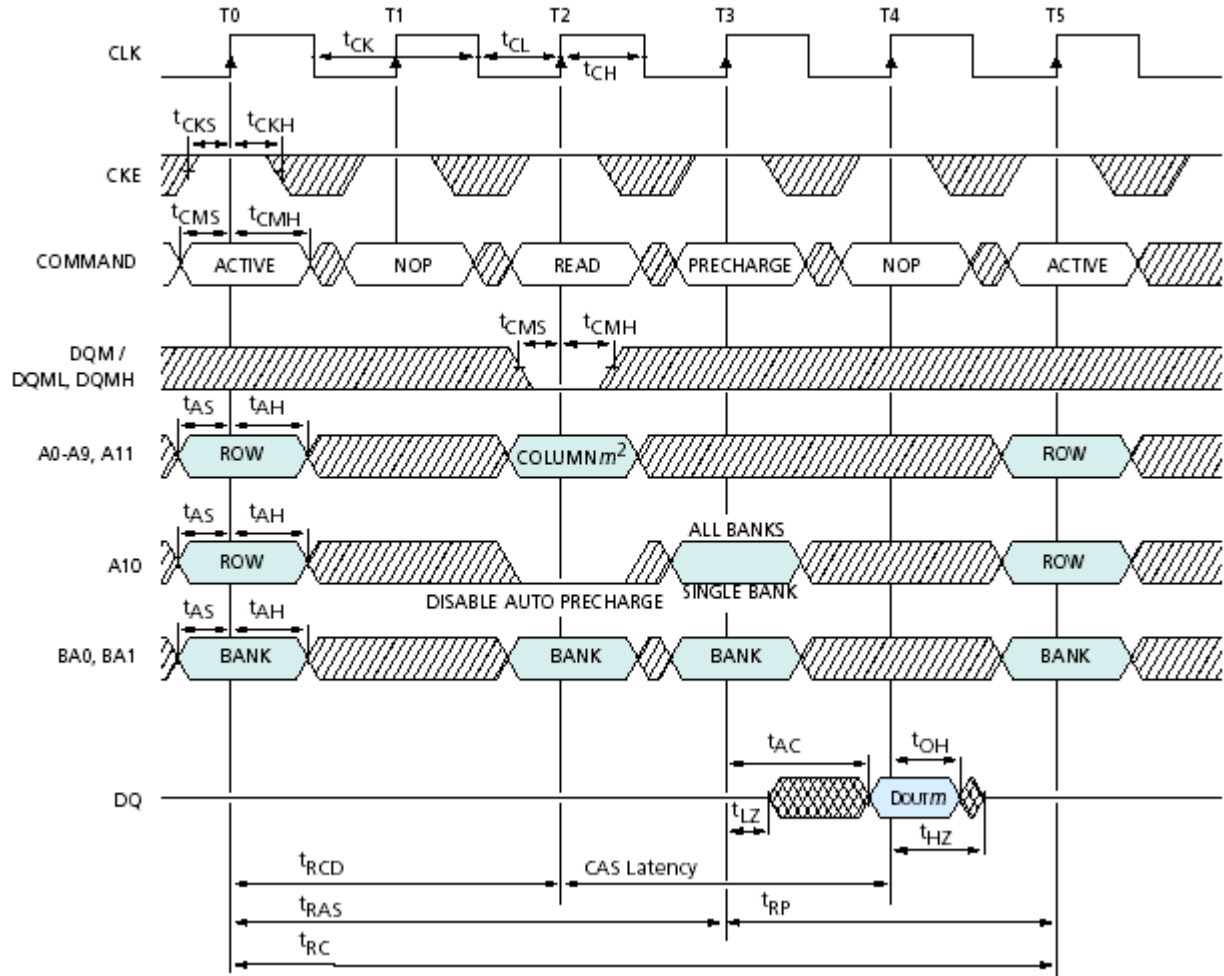


Figure 50 SDRAM Read Cycle Timing (2M32)

Table 34 SDRAM Read Cycle Parameters

SYMBOL*	-5	
	MIN	MAX
t <sub>AC</sub> (3)		45
t <sub>AC</sub> (2)		
t <sub>AC</sub> (1)		
t <sub>AH</sub>	1	
t <sub>AS</sub>	1.5	
t <sub>CH</sub>	2	
t <sub>CL</sub>	2	
t <sub>CK</sub> (3)	5	
t <sub>CK</sub> (2)		
t <sub>CK</sub> (1)		
t <sub>CKH</sub>	1	
t <sub>CKS</sub>	1.5	

SYMBOL*	-5	
	MIN	MAX
t <sub>CMH</sub>	1	
t <sub>CMS</sub>	1.5	
t <sub>HZ</sub> (3)	4.5	
t <sub>HZ</sub> (2)		
t <sub>HZ</sub> (1)		
t <sub>LZ</sub>	1	
t <sub>OH</sub>	1.5	
t <sub>RAS</sub>	38.7	120,000
t <sub>RC</sub>	55	
t <sub>RCD</sub>	15	
t <sub>RP</sub>	15	

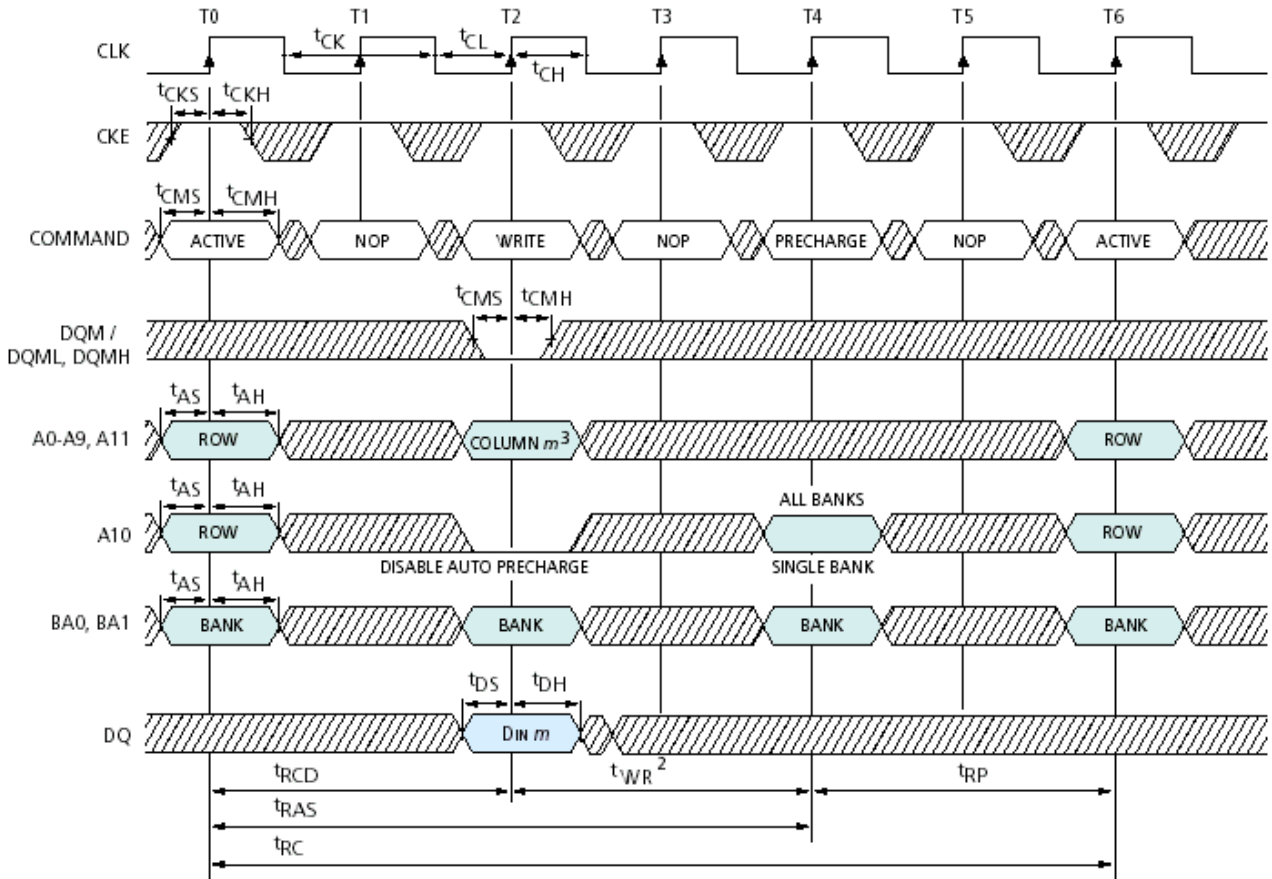


Figure 51 SDRAM Write Cycle Timing (2M32)

Table 35 SDRAM Write Cycle Parameters

SYMBOL*	-5	
	MIN	MAX
t <sub>AH</sub>	1	
t <sub>AS</sub>	1.5	
t <sub>CH</sub>	2	
t <sub>CL</sub>	2	
t <sub>CK</sub> (3)	5	
t <sub>CK</sub> (2)		
t <sub>CK</sub> (1)		
t <sub>CKH</sub>	1	
t <sub>CKS</sub>	1.5	

SYMBOL*	-5	
	MIN	MAX
t <sub>CMH</sub>	1	
t <sub>CMS</sub>	1.5	
t <sub>DH</sub>	1	
t <sub>DS</sub>	1.5	
t <sub>RAS</sub>	38.7	120,000
t <sub>RC</sub>	55	
t <sub>RCD</sub>	15	
t <sub>RP</sub>	15	
t <sub>WR</sub>	2 t <sub>CK</sub>	

For additional details, see the Micron MT48LC2M32B2 data sheet.

**Decoder SDRAM Interface (1M16)**

*Note:* In some applications, a smaller-capacity SDRAM may be sufficient to support the decoder.

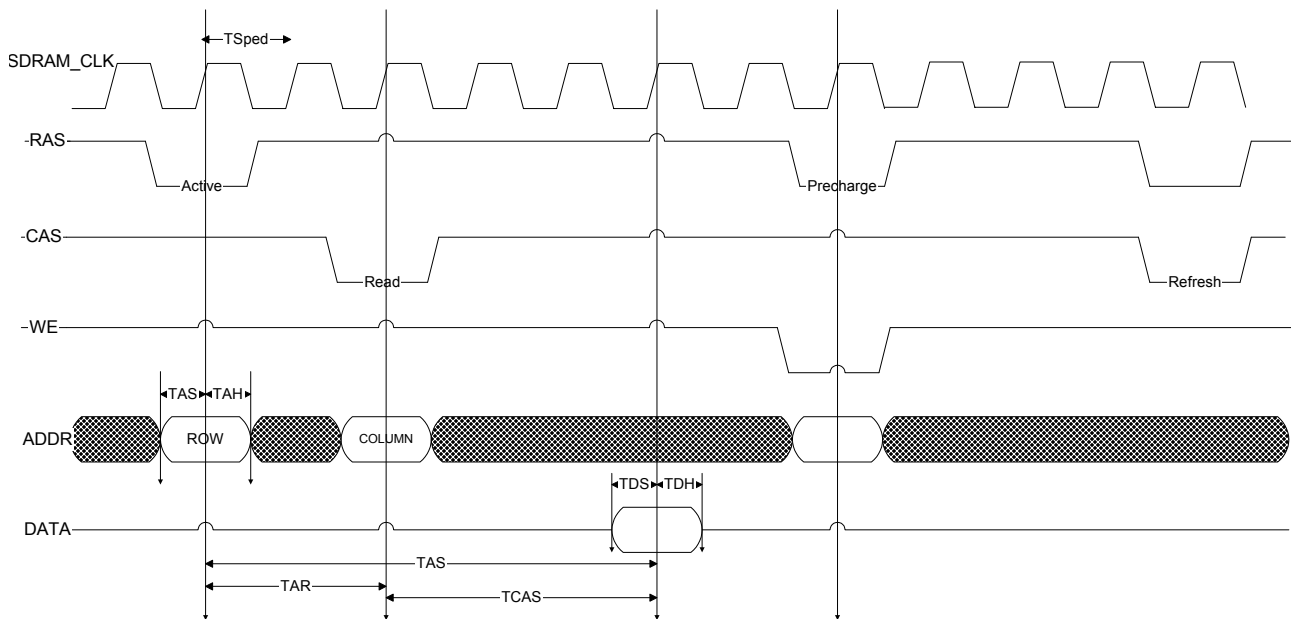
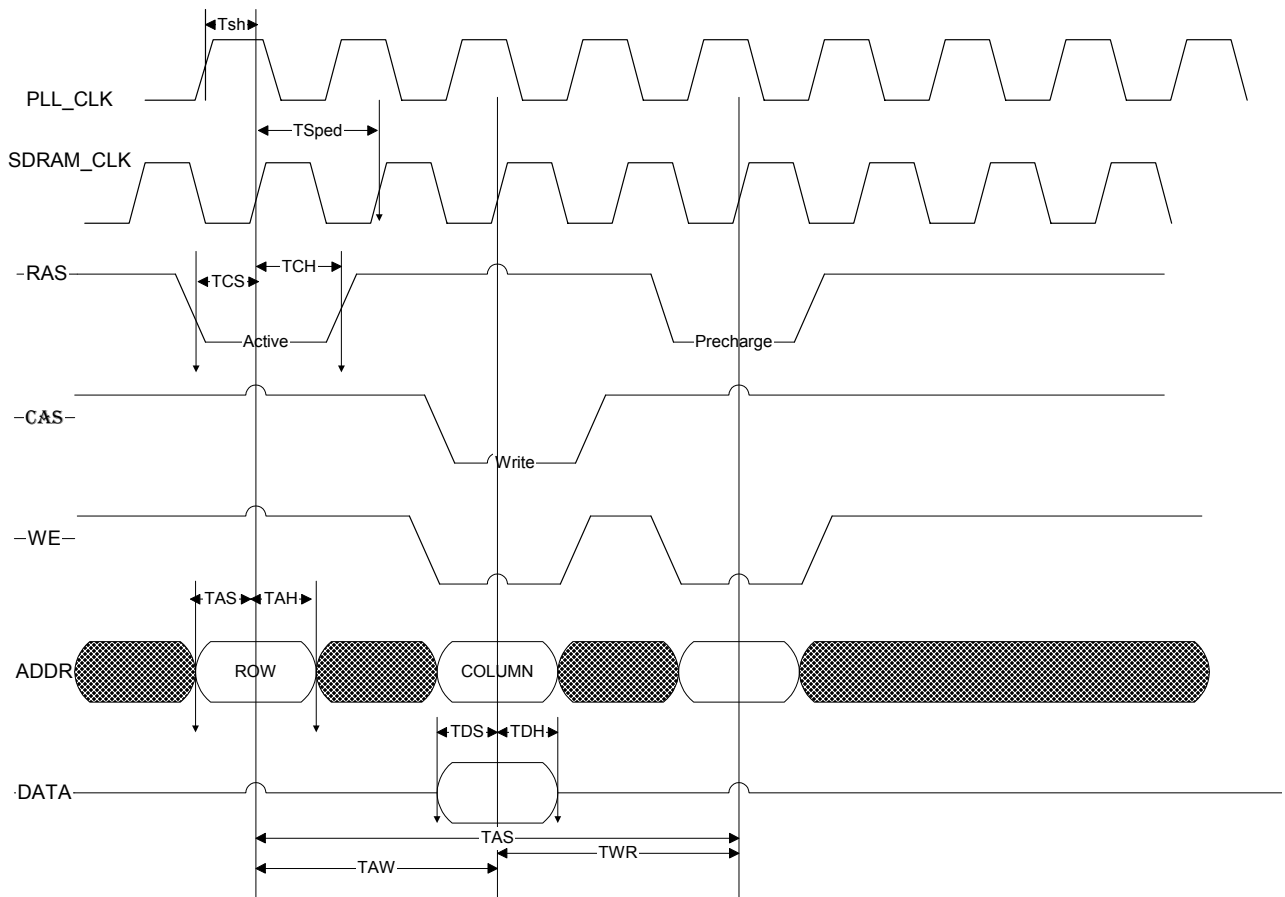


Figure 52 SDRAM Read Cycle Timing (1M16)

**Table 36 SDRAM Read Cycle Parameters**

Symbol	Description	Min	Typ	Max	Unit
$T_{AS}$	Address setup time	2		-	ns
$T_{AH}$	Address hold time	1.5		-	ns
$T_{DS}$	Data setup time	2		-	ns
$T_{DH}$	Data hold time	2		-	ns
$T_{CAS}$	CAS latency (3 cycles)	3		3	Clock
$T_{AR}$	Active to read time	3		3	Clock



**Figure 53 SDRAM Write Cycle Timing (1M16)**

Table 37 SDRAM Write Cycle Parameters

Symbol	Description	Min	Typ	Max	Unit
$T_{Sped}$	SDRAM clock cycle time	9			ns
$T_{SH}$	SDRAM_CLK delay from PLL_CLK	7			ns
$T_{AS}$	Address setup time	4			ns
$T_{AH}$	Address hold time	2			ns
$T_{CS}$	RAS setup time	4			ns
$T_{CH}$	RAS hold time	2			ns
$T_{DS}$	Data setup time	4			ns
$T_{DH}$	Data hold time	2			ns
$T_{AW}$	Active to write time	3		3	Clock
$T_{WR}$	Write to precharge time	2		2	Clock

For additional details, see the Micron MT48LC1M16A1 data sheet.

## ROM Interface

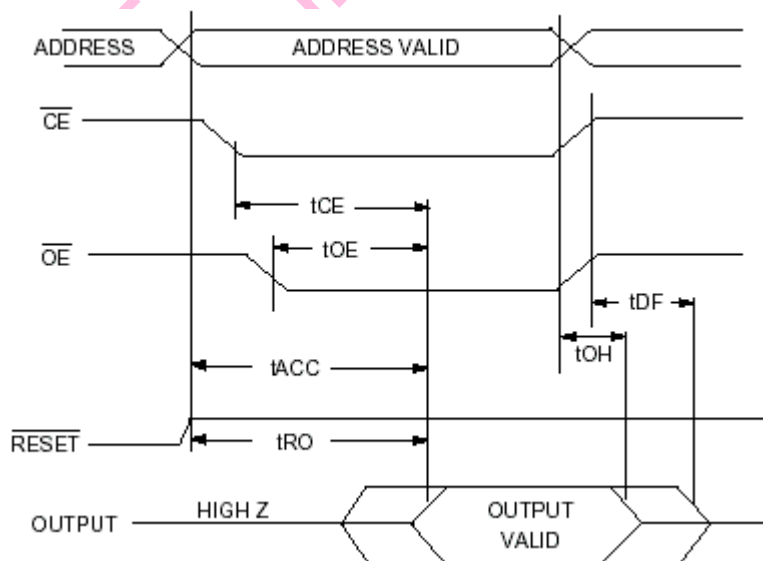


Figure 54 ROM Interface Read Timing

**Table 38 ROM Read Timing Parameters**

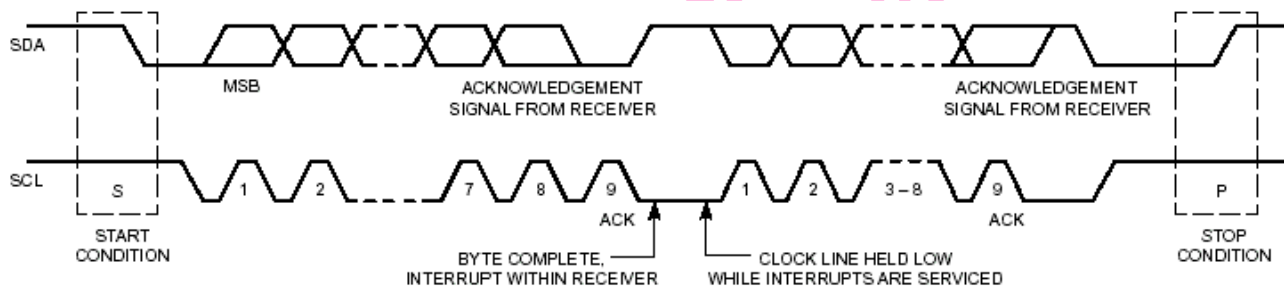
Symbol	Parameter	AT49BV16X4(T)-90		AT49BV16X4(T)-12		Units
		Min	Max	Min	Max	
$t_{AOC}$	Address to Output Delay		90		120	ns
$t_{CE}^{(1)}$	$\overline{CE}$ to Output Delay		90		120	ns
$t_{CE}^{(2)}$	$\overline{OE}$ to Output Delay	0	40	0	50	ns
$t_{OE}^{(3/4)}$	$\overline{OE}$ or $\overline{CE}$ to Output Float	0	25	0	30	ns
$t_{OH}$	Output Hold from $\overline{OE}$ , $\overline{CE}$ or Address, whichever occurred first	0		0		ns
$t_{RO}$	RESET to Output Delay		800		800	ns

For additional details, see the Digi Key AT49BV1614 data sheet.

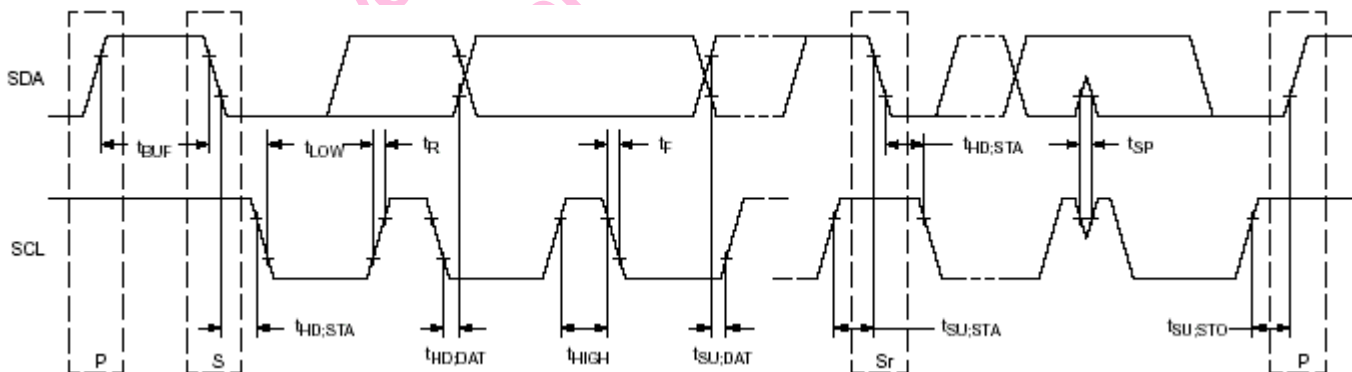
**ICI Interface**

Table 39 on page 170 shows the ICI interface timing parameters and Figure 55 shows the data transfers on the ICI bus.

During write operations, data transfers are relative to the SCL output. During read operations, data transfers are relative to the SCL input.



**Figure 55 Data Transfer on the ICI Bus**



**Figure 56 ICI Timing**

Table 39 ICI Timing Parameters

PARAMETER	SYMBOL	STANDARD-MODE I <sup>2</sup> C-BUS		FAST-MODE I <sup>2</sup> C-BUS		UNIT
		Min.	Max.	Min.	Max.	
SCL clock frequency	f <sub>SCL</sub>	0	100	0	400	kHz
Bus free time between a STOP and START condition	t <sub>BUF</sub>	4.7	–	1.3	–	μs
Hold time (repeated) START condition. After this period, the first clock pulse is generated	t <sub>HD;STA</sub>	4.0	–	0.6	–	μs
LOW period of the SCL clock	t <sub>LOW</sub>	4.7	–	1.3	–	μs
HIGH period of the SCL clock	t <sub>HIGH</sub>	4.0	–	0.6	–	μs
Set-up time for a repeated START condition	t <sub>SU;STA</sub>	4.7	–	0.6	–	μs
Data hold time: for CBUS compatible masters (see NOTE, Section 9.1.3) for I <sup>2</sup> C-bus devices	t <sub>HD;DAT</sub>	5.0 0 <sup>1)</sup>	– –	– 0 <sup>1)</sup>	– 0.9 <sup>2)</sup>	μs μs
Data set-up time	t <sub>SU;DAT</sub>	250	–	100 <sup>3)</sup>	–	ns
Rise time of both SDA and SCL signals	t <sub>r</sub>	–	1000	20 + 0.1C <sub>b</sub> <sup>4)</sup>	300	ns
Fall time of both SDA and SCL signals	t <sub>f</sub>	–	300	20 + 0.1C <sub>b</sub> <sup>4)</sup>	300	ns
Set-up time for STOP condition	t <sub>SU;STO</sub>	4.0	–	0.6	–	μs
Capacitive load for each bus line	C <sub>b</sub>	–	400	–	400	pF

All values referred to V<sub>IHmin</sub> and V<sub>ILmax</sub> levels (see Table 3).

1. A device must internally provide a hold time of at least 300 ns for the SDA signal (referred to the V<sub>IHmin</sub> of the SCL signal) in order to bridge the undefined region of the falling edge of SCL.
2. The maximum t<sub>HD;DAT</sub> has only to be met if the device does not stretch the LOW period (t<sub>LOW</sub>) of the SCL signal.
3. A fast-mode I<sup>2</sup>C-bus device can be used in a standard-mode I<sup>2</sup>C-bus system, but the requirement t<sub>SU;DAT</sub> ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line t<sub>rmax</sub> + t<sub>SU;DAT</sub> = 1000 + 250 = 1250 ns (according to the standard-mode I<sup>2</sup>C-bus specification) before the SCL line is released.
4. C<sub>b</sub> = total capacitance of one bus line in pF.

For additional details, see the Philips Semiconductor I<sup>2</sup>C specification.

## PLL Interface

For details, see the ICS511 and the MK2745-21 data sheets from Integrated Circuit Systems.



**JTAG / EJTAG Interface**

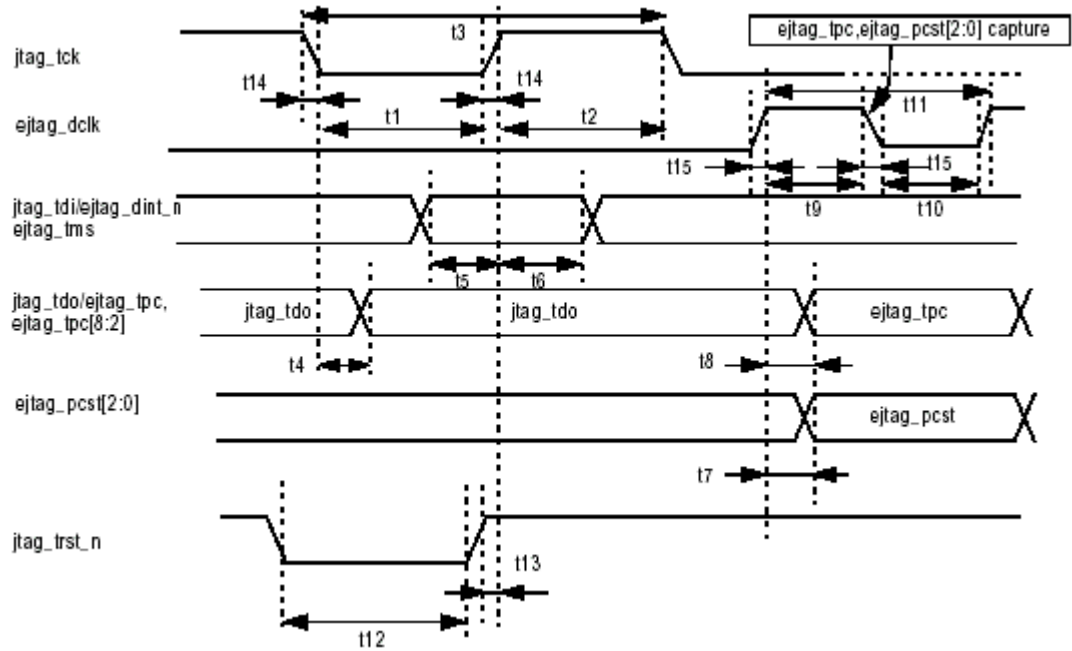


Figure 57 JTAG / EJTAG Timing

- |                    |                                |
|--------------------|--------------------------------|
| t1 = $t_{TCKLOW}$  | t11 = $t_{DCK}$                |
| t2 = $t_{TCKHIGH}$ | t12 = $t_{TRSTDO}$             |
| t3 = $t_{TCK}$     | t13 = $t_{TRSTR}$              |
| t4 = $t_{TD0DO}$   | t14 = $t_{TCK RISE, TCK FALL}$ |
| t5 = $t_{TDIS}$    | t15 = $t_{DCK RISE, DCK FALL}$ |
| t6 = $t_{TDIH}$    |                                |
| t7 = $t_{PCSTDO}$  |                                |
| t8 = $t_{TPCDO}$   |                                |
| t9 = $t_{DCKHIGH}$ |                                |
| t10 = $t_{DCKLOW}$ |                                |

Table 40 JTAG / EJTAG Timing Parameters

to be added

For additional details, see the JTAG standard IEEE 1149-1 and an EJTAG data sheet from EPI, for example.

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# Index

## Numerics

	91266
	Heading2
DMA Out	161

## A

A/V Input Interfaces	15
A/V Output Interfaces	15
AC Timing Characteristics	148
Alpha Blending	34
Anti-flickering	35
Applications	16
Audio 1 buffer	23, 31
Audio 2 buffer	23, 31
Audio 3 buffer	24, 31
Audio 4 buffer	24, 31
Audio DAC	36
Audio Decoding Features	12
Audio Encoding Features	12
Audio Input Interface	64
Audio Input Timing	157
Audio Output Interface	72
Audio Output Timing	158
Audio Output Unit (AOU)	36
Audio PLL	52
Audio PLL Signals	84

## B

Background Color Plane	33
Basic Design	54
BGA Ball Map	90
Big-endian	4, 76
Board-Level Requirements for Unused Input Pins	142
Boot Mode	49
Boot Mode Stuffing Options	49

## C

CDI Port	32
----------	----

CDO	
ASI mode .....	25
VW2000 mode .....	25
CDO Modes .....	25
CDO Streams .....	25
Chip Mode Select .....	50
Clock Pins .....	92
Compressed Data Input Timing .....	158
Compressed Data Output Timing .....	159
Cursor Plane .....	34

**D**

Data Cache (dmem) .....	40
Data Input Paths - Compressed Data .....	6
Data Input Paths - Uncompressed Data .....	5
Data Output Paths - Compressed Data .....	6
Data Output Paths - Uncompressed Data .....	7
Data Paths .....	3
Data Paths via the Buffers .....	31
Decoder Buffers .....	30
Decoder Core Modules .....	32
Decoder Interface Signals .....	69
Decoder Memory Interface .....	71
Decoder Memory Interface Unit (DMIU) .....	41
Decoder Modules .....	2
Decoder Paths .....	6
Decoder Processor Unit (dCPU) .....	32
Demultiplexer Interface .....	70
Demultiplexing .....	13
Design Example .....	54
Clock Source .....	54
EEPROM Interface .....	59
Embedded Host mode .....	61
PCI Interface .....	60
ROM Interface .....	58
SDRAM Interface .....	56
DMA channel .....	47
DMA Controller .....	46
DMA race conditions .....	47
Drive Attributes .....	92
Drive Attributes in Host Mode .....	92
Drive Strengths .....	92

**E**

EJTAG Enable .....	50
EJTAG Mode .....	62
EJTAG port .....	50
Electrical Characteristics .....	147
Embedded Host Mode .....	61
Embedded Processor (MIPS/DSP) .....	40
Encoder Interface Signals .....	63
Encoder Memory Interface .....	65
Encoder Memory Interface Unit (EMIU) .....	41
Encoder Modules .....	1
Encoder Path .....	5
Extended JTAG .....	54
Extended JTAG Signals .....	85
External Address Decoder .....	60

	External Buffer Control .....	24
<b>F</b>		
	Features and Benefits .....	16
	Field prediction .....	33
	Frame prediction .....	33
<b>G</b>		
	General Purpose I/O (GPIO) .....	50
	GPIO Signals .....	82
	Graphics .....	13
	Graphics Planes .....	34
<b>H</b>		
	Host / PCI Interface .....	41
	Host / PCI Port .....	32
	Host Interface, Intel Mode .....	78
	Host Interface, Motorola Mode .....	76
	Host Interface, PCI Mode .....	79
	Host Interfaces .....	15
	Host Mode .....	49
	Host Read Timing, HIU-Intel Mode .....	151
	Host Read Timing, HIU-Motorola Mode .....	149
	Host Read Timing, HIU-PCI Mode .....	153
	Host Write Timing, HIU-Intel Mode .....	152
	Host Write Timing, HIU-Motorola Mode .....	150
	Host Write Timing, HIU-PCI Mode .....	154
<b>I</b>		
	I/O Signals, Sorted by Pad Number .....	93, 104, 115, 126
	I2S Bus Timing .....	157
	ICI Signals .....	83
	IDC Interface Timing .....	169
	Inter-Device Communications (IDC) .....	51
	Inverse Quantization / Inverse DCT Unit (IQ/IDCT) .....	33
	Inverse scan .....	32
<b>J</b>		
	JTAG .....	54
	JTAG Signals .....	84
<b>L</b>		
	Little-endian .....	78
<b>M</b>		
	Main PLL Signals .....	83
	Memory Interfaces .....	41
	MIPS Audio Decoder .....	40
	MIPS Audio Encoder .....	40
	MIPS Demultiplexer .....	40
	MIPS Multiplexer .....	40
	Motion compensation .....	33
	Motion Compensation Unit (MCU) .....	33
	Motion vectors .....	33

MPEG Display Plane .....	33
MPEG specification ISO/IEC 13818-2 .....	33
MPEG-4 / MPEG-2 Feature Differences .....	13
Multiple Devices .....	60
Multiplexer Interface .....	66
Multiplexing .....	12
Mux buffer .....	24

**O**

On-Screen Display (OSD) .....	35
-------------------------------	----

**P**

Package Information .....	87
PCI DMA .....	162
PCI Interface .....	79
PCI Mode .....	49
PCI Read Transaction .....	154
PCI Write Transaction .....	154
Phase Locked Loop (PLL) .....	51
Pin-out Diagram .....	89
PMU Initial State .....	52
PMU Normal State .....	53
PMU Sleep State .....	53
Power and Ground Connections .....	137
Power Management (PMU) .....	52
Power-Off Sequence .....	148
Power-On Sequence .....	148
Prediction modes .....	33
PSI buffer .....	31

**R**

ROM data bus .....	49
ROM Interface .....	81
ROM Interface (RIU) .....	48
ROM Interface Timing .....	168
ROM Power-Up Modes .....	49

**S**

SDRAM Read Cycle Timing (1M16) .....	166
SDRAM Read Cycle Timing (2M32) .....	163
SDRAM Write Cycle Timing (1M16) .....	167
SDRAM Write Cycle Timing (2M32) .....	165
Signal Multiplexing .....	91
Signal Multiplexing Scheme (sorted by signal name) .....	141
Simultaneous memory hits .....	47
System clock .....	51
System Interface Signals .....	75
System Interfaces .....	15
System Modules .....	2, 39

**T**

Termination Rules .....	92
Time Shifting Path .....	7
Transcoding / Transrating Path .....	7

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**U**

Unused Pins .....92  
User data buffer .....24, 31

**V**

Variable Length Decoding Unit (VLD) .....32  
VBI buffer .....24  
VBI bus .....50  
VBI Input Interface .....65  
VBI Input Timing .....156  
Video buffer .....24, 31  
Video Decoding Features .....12  
Video encoder .....36  
Video Encoding Features .....11  
Video Input Interface .....64  
Video Input Timing .....155, 156  
Video layers .....32  
Video Output Interface .....72  
Video Output Unit (VOU) .....33

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